

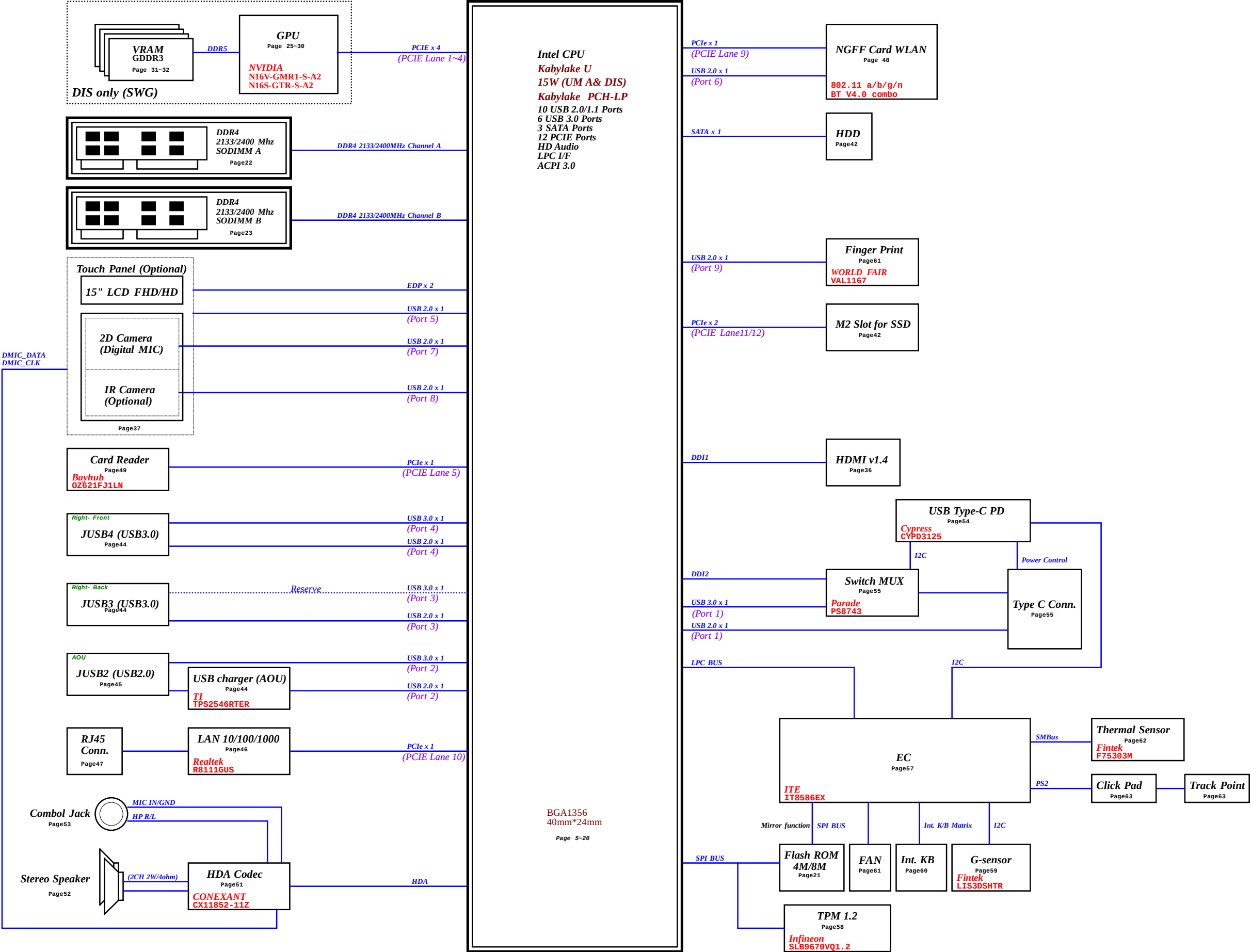
LCFC Confidential

KENOBI NM-A821 Rev2.0 Schematic

Intel KabyLake Processor with DDR4 + PCH-LP
NVIDA N16V-GMR GDDR3 2GB
2016-08-24 Rev2.0

Security Classification		LC Future Center Secret Data		Title		
Issued Date	2015/10/5	Deciphered Date	2016/12/31	COVER PAGE		
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Kenobi KBL U Block Diagram



Voltage Rails (O --> Means ON , X --> Means OFF)

Power Plane State	B+ +3VL	+3VALW +5VALW +1VALW +1.8VALW	+2.5V +1.2V +VCC_STG	+5VS +3VS +VCC_CORE +VCC_IO +VCC_SA +VCC_ST +VGA_CORE +3VS_VGA +1.5VS_VGA +3VS_AON +1VS_VGA +0.6VS
S0	0	0	0	0
S3	0	0	0	X
S5 S4/AC Only	0	0	X	X
S5 S4 Battery only	0	X	X	X
S5 S4 AC & Battery don't exist	X	X	X	X

STATE \ SIGNAL	SLP_A#	SLP_S3#	SLP_S4#	SLP_S5#	EC_ON2	EC_ON	SUSP#	SYSON
Full ON	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	HIGH
S1(Power On Suspend)	HIGH	HIGH	HIGH	HIGH	ON	ON	ON	HIGH
S3 (Suspend to RAM)	LOW	LOW	HIGH	HIGH	ON	ON	OFF	HIGH
S4 (Suspend to Disk)	LOW	LOW	LOW	HIGH	ON	ON	OFF	LOW
S5 (Soft OFF)	LOW	LOW	LOW	LOW	ON	ON	OFF	LOW

SMBUS Control Table

	SOURCE	Main VGA	BATT (Charger)	SODIMM	WLAN WiMAX	Thermal Sensor	PCH	CP Module	LAN PHY	G sensor	USB Type-C
EC_SMB_CK1 EC_SMB_DA1	IT8580F +3VL	X	V +3VALW	X	X	X	X	X	X	X	X
EC_SMB_CK2 EC_SMB_DA2	IT8580F +3VL	X	X	X	X	X	X	X	X	X	V +3VPD_VDD
EC_SMB_CK3 EC_SMB_DA3	IT8580F +3VS	V +3VS_VGA	X	X	X	V +3VS	V +3V_PCH	X	X	V +3VS_GS	X
PCH_SMB_CLK PCH_SMB_DATA	PCH +3V_PCH	X	X	V +3VS	X	X	X	V +5VS	X	X	X
PCH_SML1CLK PCH_SML1DAT	PCH +3V_PCH	X	X	X	X	X	X	X	X	X	X

BOM Structure Table

BOM Structure	NOTE
PCB@	For PCB load BOM
XDP@	Debug port
UMA@	UMA SKU ID
DIS@	Optimus SKU ID
SSD@	SSD setting
FRP@	Finger printer setting
TYPEC@	For USB Type-C function
ME@	ME Connector
EMC@	For EMC function
EMC_2D@	For EMC function
EMC_NS@	For EMC function
RF_NS@	For RF function
S2G@	For VRAM Strap
CHA@	For VRAMA function
CHB@	For VRAMB function
RANKA@	GPU DDR5 Setting
X76@	GPU VRAM Setting
3DCCD@	3D Camera Setting
VGA@	VGA Setting
MUX@	MUX Setting
ODD@	ODD Setting
TPM@	Trusted Platform Module (TPM)
MIRROR@	For mirror function
NGC6@	For VGA Non GC6 function
GC6@	For VGA GC6 function

USB2 Port

Port	Device
1	JUSB1 TYPE-C
2	JUSB2
3	JUSB3
4	JUSB4
5	Touch Panel
6	BT
7	CMOS
8	IR CAMERA
9	FP/Smart

USB3 Port

Port	Device
1	JUSB1 TYPE-C
2	JUSB2
3	JUSB3
4	JUSB4

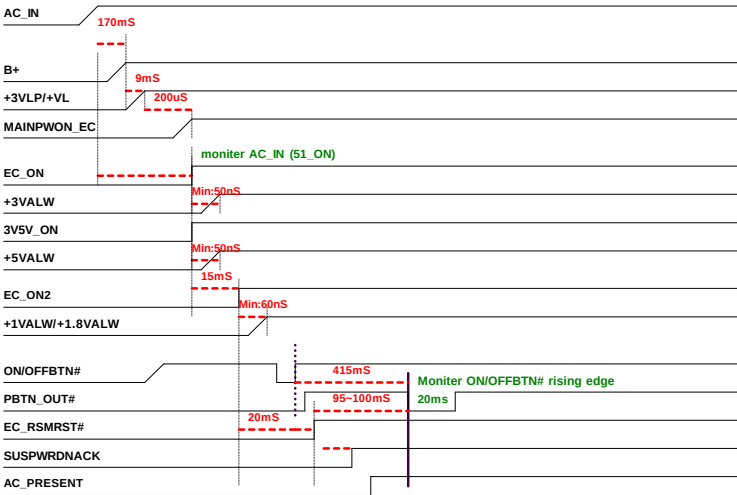
PCIE Port

Port	Device
1	GPU
2	GPU
3	GPU
4	GPU
5	CardReader
6	X
7	X
8	X
9	WLAN
10	LAN
11	M.2 SSD
12	M.2 SSD

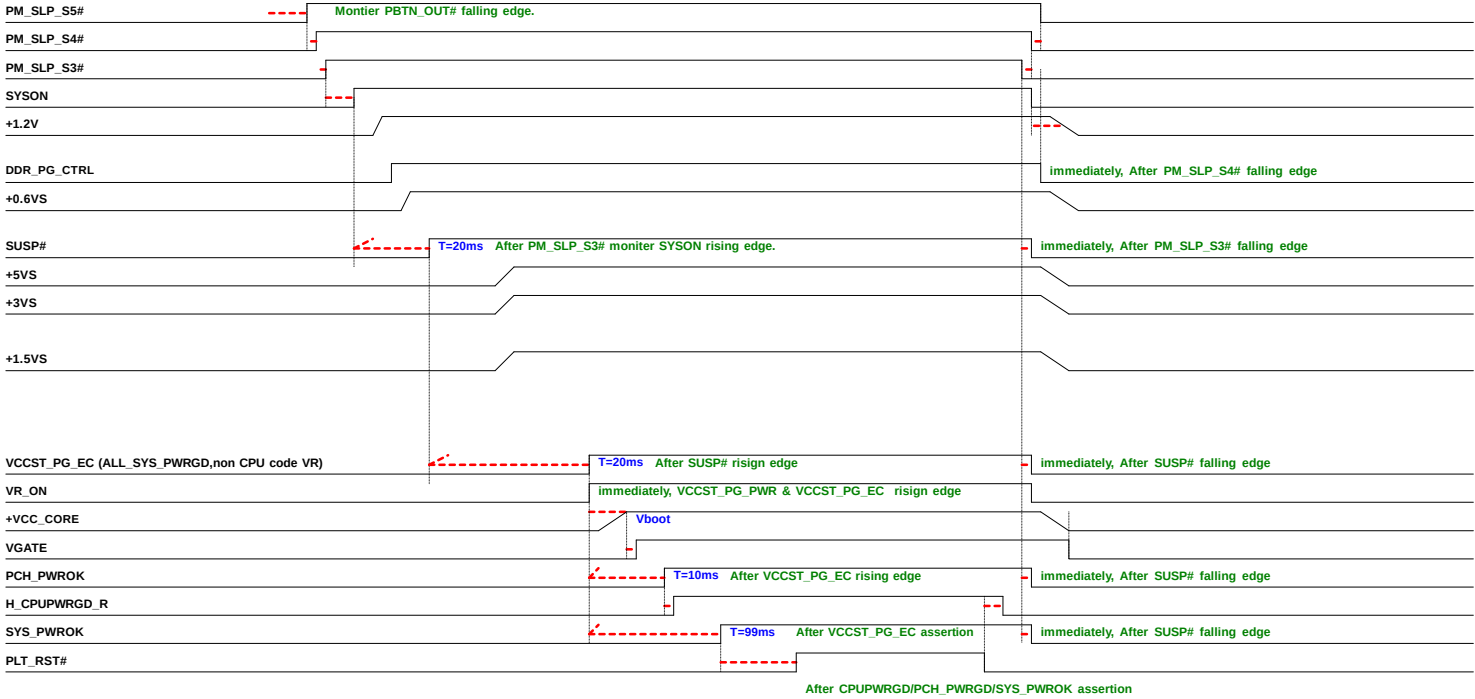
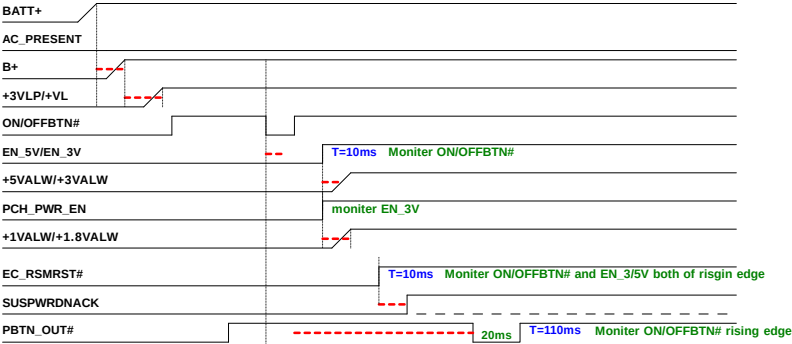
SATA Port

Port	Device
1	HDD
2	X
3	X
4	X

[AC Mode]



[DC Mode]

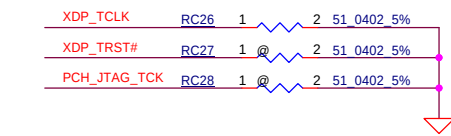
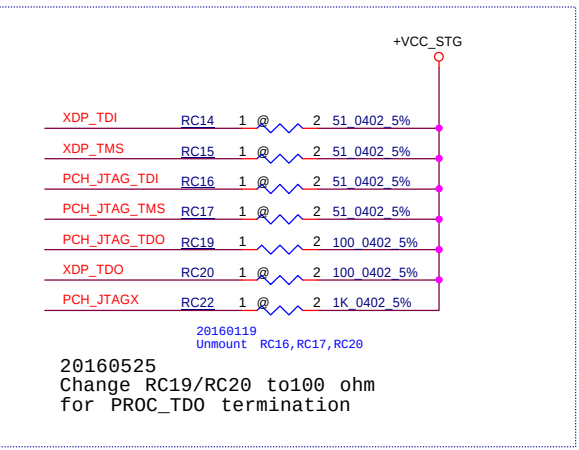
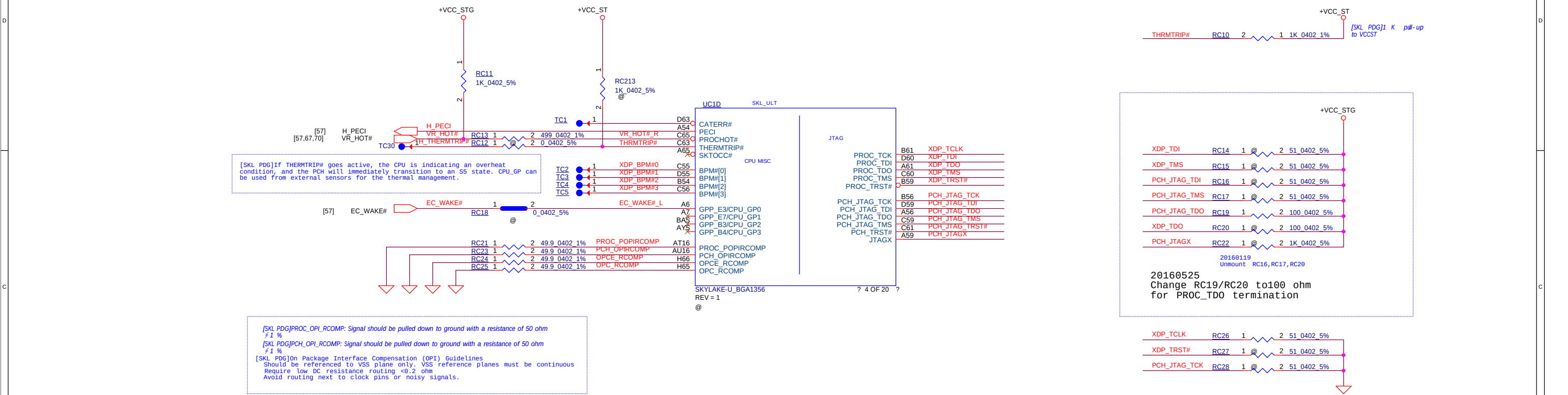


D

C

B

A



Termination option

XDP_TCLK PROC_TCK Termination: 51 ohm +/- 5% pull down to GNG (Ground) Placed to within 200ps (1100 mil) or PROC_TCK pin
PCH_JTAG_TDO PCH_JTAG_TDO Termination: 51ohm +/- 5% pull up to VccSTG or equivalent. Placed to within 200ps (1100 mil) or PCH_JTAG_TDO pin

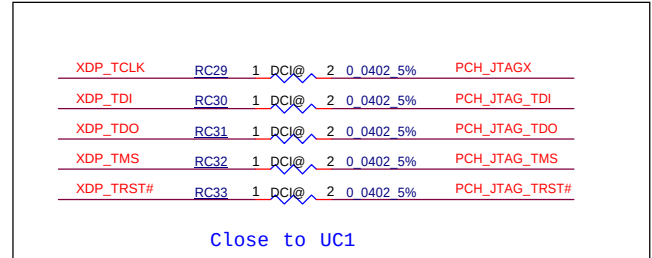
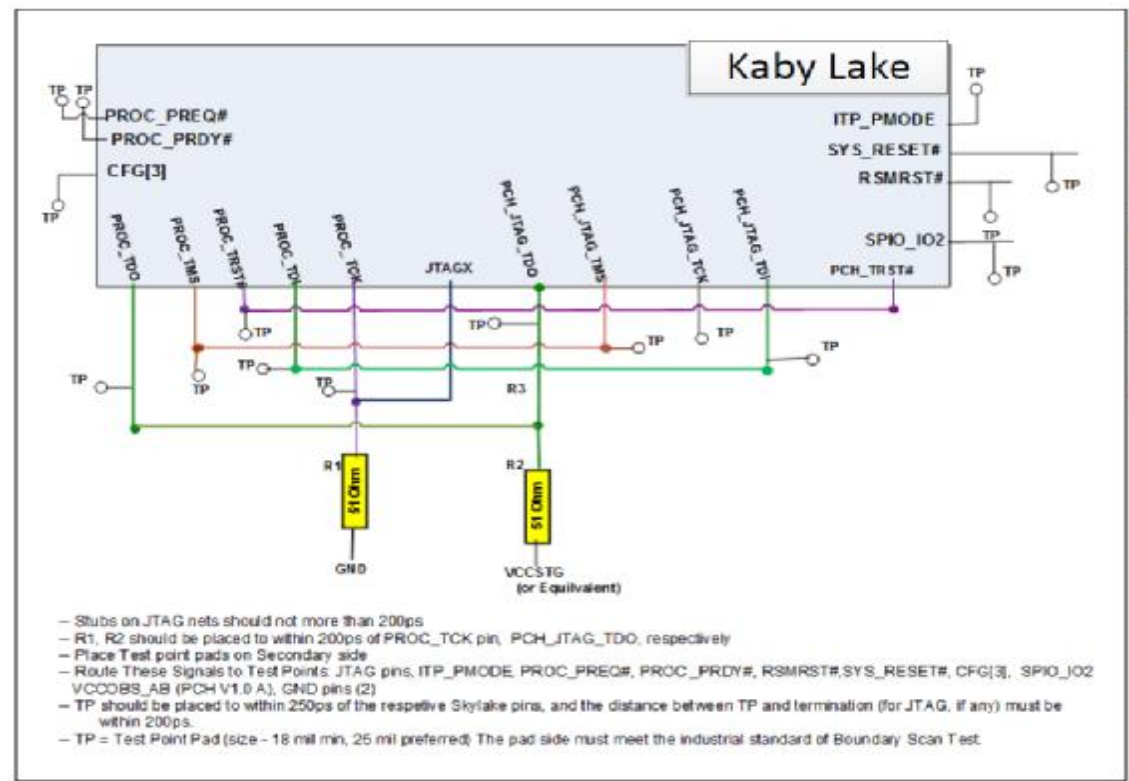


TABLE			
	Pin	Interleave	Non-Interleave
Block 0	AL71	DDR0_DQ[0]	DDR0_DQ[0]
	AL88	DDR0_DQ[1]	DDR0_DQ[1]
	AN68	DDR0_DQ[2]	DDR0_DQ[2]
	AN69	DDR0_DQ[3]	DDR0_DQ[3]
	AL70	DDR0_DQ[4]	DDR0_DQ[4]
	AL89	DDR0_DQ[5]	DDR0_DQ[5]
	AN70	DDR0_DQ[6]	DDR0_DQ[6]
	AN71	DDR0_DQ[7]	DDR0_DQ[7]
	AR70	DDR0_DQ[8]	DDR0_DQ[8]
	AR88	DDR0_DQ[9]	DDR0_DQ[9]
	AU71	DDR0_DQ[10]	DDR0_DQ[10]
	AU88	DDR0_DQ[11]	DDR0_DQ[11]
	AR71	DDR0_DQ[12]	DDR0_DQ[12]
	AR89	DDR0_DQ[13]	DDR0_DQ[13]
	AU70	DDR0_DQ[14]	DDR0_DQ[14]
	AU89	DDR0_DQ[15]	DDR0_DQ[15]
Block 2	BB66	DDR0_DQ[16]	DDR0_DQ[32]
	AW66	DDR0_DQ[17]	DDR0_DQ[33]
	AW69	DDR0_DQ[18]	DDR0_DQ[34]
	AY63	DDR0_DQ[19]	DDR0_DQ[35]
	BA66	DDR0_DQ[20]	DDR0_DQ[36]
	AY66	DDR0_DQ[21]	DDR0_DQ[37]
	BA63	DDR0_DQ[22]	DDR0_DQ[38]
	BB63	DDR0_DQ[23]	DDR0_DQ[39]
	BA61	DDR0_DQ[24]	DDR0_DQ[40]
	AW61	DDR0_DQ[25]	DDR0_DQ[41]
	BB69	DDR0_DQ[26]	DDR0_DQ[42]
	AW69	DDR0_DQ[27]	DDR0_DQ[43]
	BB61	DDR0_DQ[28]	DDR0_DQ[44]
	AY61	DDR0_DQ[29]	DDR0_DQ[45]
	BA69	DDR0_DQ[30]	DDR0_DQ[46]
	AY69	DDR0_DQ[31]	DDR0_DQ[47]
Block 4	AY39	DDR0_DQ[32]	DDR1_DQ[0]
	AW39	DDR0_DQ[33]	DDR1_DQ[1]
	AY37	DDR0_DQ[34]	DDR1_DQ[2]
	AW37	DDR0_DQ[35]	DDR1_DQ[3]
	BB39	DDR0_DQ[36]	DDR1_DQ[4]
	BA39	DDR0_DQ[37]	DDR1_DQ[5]
	BA37	DDR0_DQ[38]	DDR1_DQ[6]
	BB37	DDR0_DQ[39]	DDR1_DQ[7]
	AY36	DDR0_DQ[40]	DDR1_DQ[8]
	AW36	DDR0_DQ[41]	DDR1_DQ[9]
	AY33	DDR0_DQ[42]	DDR1_DQ[10]
	AW33	DDR0_DQ[43]	DDR1_DQ[11]
	BB36	DDR0_DQ[44]	DDR1_DQ[12]
	BA36	DDR0_DQ[45]	DDR1_DQ[13]
	BA33	DDR0_DQ[46]	DDR1_DQ[14]
	BB33	DDR0_DQ[47]	DDR1_DQ[15]
Block 8	AY31	DDR0_DQ[48]	DDR1_DQ[32]
	AW31	DDR0_DQ[49]	DDR1_DQ[33]
	AY29	DDR0_DQ[50]	DDR1_DQ[34]
	AW29	DDR0_DQ[51]	DDR1_DQ[35]
	BB31	DDR0_DQ[52]	DDR1_DQ[36]
	BA31	DDR0_DQ[53]	DDR1_DQ[37]
	AA29	DDR0_DQ[54]	DDR1_DQ[38]
	BB29	DDR0_DQ[55]	DDR1_DQ[39]
	AY27	DDR0_DQ[56]	DDR1_DQ[40]
	AW27	DDR0_DQ[57]	DDR1_DQ[41]
	AY26	DDR0_DQ[58]	DDR1_DQ[42]
	AW26	DDR0_DQ[59]	DDR1_DQ[43]
	BB27	DDR0_DQ[60]	DDR1_DQ[44]
	BA27	DDR0_DQ[61]	DDR1_DQ[45]
	BA26	DDR0_DQ[62]	DDR1_DQ[46]
	BB26	DDR0_DQ[63]	DDR1_DQ[47]

TABLE			
	Pin	Interleave	Non-Interleave
Block 0	AM70	DDR0_DQSN[0]	DDR0_DQSN[0]
	AM69	DDR0_DQSP[0]	DDR0_DQSP[0]
	AT69	DDR0_DQSN[1]	DDR0_DQSN[1]
	AT70	DDR0_DQSP[1]	DDR0_DQSP[1]
Block 2	BA64	DDR0_DQSN[2]	DDR0_DQSN[4]
	AY64	DDR0_DQSP[2]	DDR0_DQSP[4]
	AY60	DDR0_DQSN[3]	DDR0_DQSN[5]
	BA60	DDR0_DQSP[3]	DDR0_DQSP[5]
Block 4	BA38	DDR0_DQSN[4]	DDR1_DQSN[0]
	AY38	DDR0_DQSP[4]	DDR1_DQSP[0]
	AY34	DDR0_DQSN[5]	DDR1_DQSN[1]
	BA34	DDR0_DQSP[5]	DDR1_DQSP[1]
Block 6	BA30	DDR0_DQSN[6]	DDR1_DQSN[4]
	AY30	DDR0_DQSP[6]	DDR1_DQSP[4]
	AY26	DDR0_DQSN[7]	DDR1_DQSN[5]
	BA26	DDR0_DQSP[7]	DDR1_DQSP[5]

TABLE			
Pin	DDR3L	LPDDR3	DDR4
BA51	DDR0_MA[5]	DDR0_CAA[0]	DDR0_MA[5]
BB54	DDR0_MA[3]	DDR0_CAA[1]	DDR0_MA[3]
BA52	DDR0_MA[6]	DDR0_CAA[2]	DDR0_MA[6]
AY52	DDR0_MA[8]	DDR0_CAA[3]	DDR0_MA[8]
AW52	DDR0_MA[7]	DDR0_CAA[4]	DDR0_MA[7]
AY55	DDR0_BA[2]	DDR0_CAA[5]	DDR0_BA[2]
AW54	DDR0_MA[12]	DDR0_CAA[6]	DDR0_MA[12]
BA54	DDR0_MA[11]	DDR0_CAA[7]	DDR0_MA[11]
BA55	DDR0_MA[15]	DDR0_CAA[8]	DDR0_ACT#
AY54	DDR0_MA[14]	DDR0_CAA[9]	DDR0_BG[1]
AU46	DDR0_MA[13]	DDR0_CAB[0]	DDR0_MA[13]
AU48	DDR0_CAS#	DDR0_CAB[1]	DDR0_MA[15]
AT46	DDR0_WE#	DDR0_CAB[2]	DDR0_MA[14]
AU50	DDR0_RAS#	DDR0_CAB[3]	DDR0_MA[16]
AU52	DDR0_BA[0]	DDR0_CAB[4]	DDR0_BA[0]
AY51	DDR0_MA[2]	DDR0_CAB[5]	DDR0_MA[2]
AT48	DDR0_BA[1]	DDR0_CAB[6]	DDR0_BA[1]
AT50	DDR0_MA[10]	DDR0_CAB[7]	DDR0_MA[10]
BB50	DDR0_MA[1]	DDR0_CAB[8]	DDR0_MA[1]
AY59	DDR0_MA[9]	DDR0_CAB[9]	DDR0_MA[9]
BA50	DDR0_MA[3]	Not Used	DDR0_MA[3]
BB52	DDR0_MA[4]	Not Used	DDR0_MA[4]

[22] DDR_A_D[63..0]

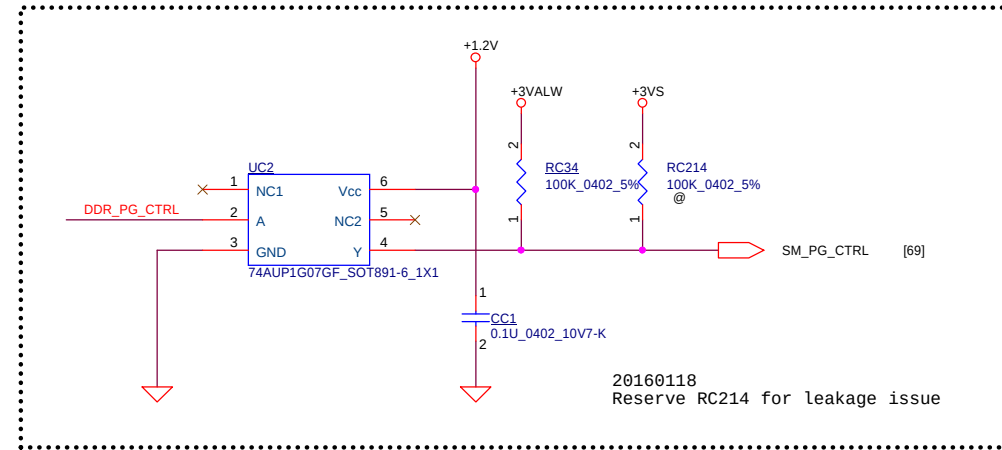
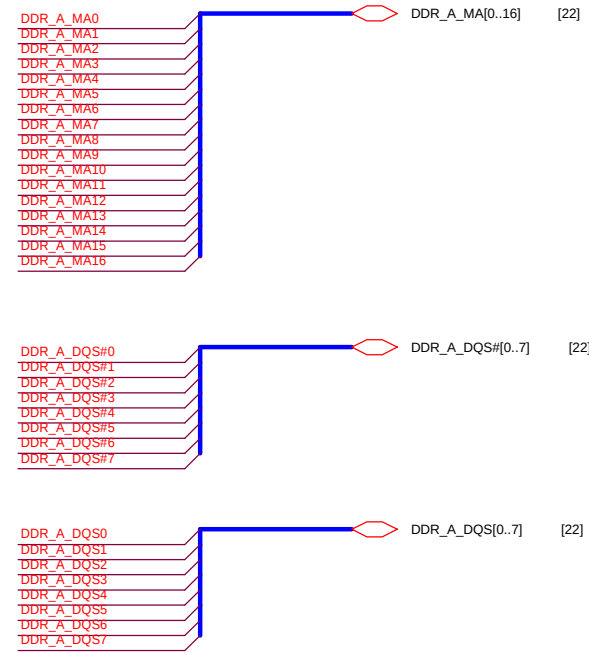
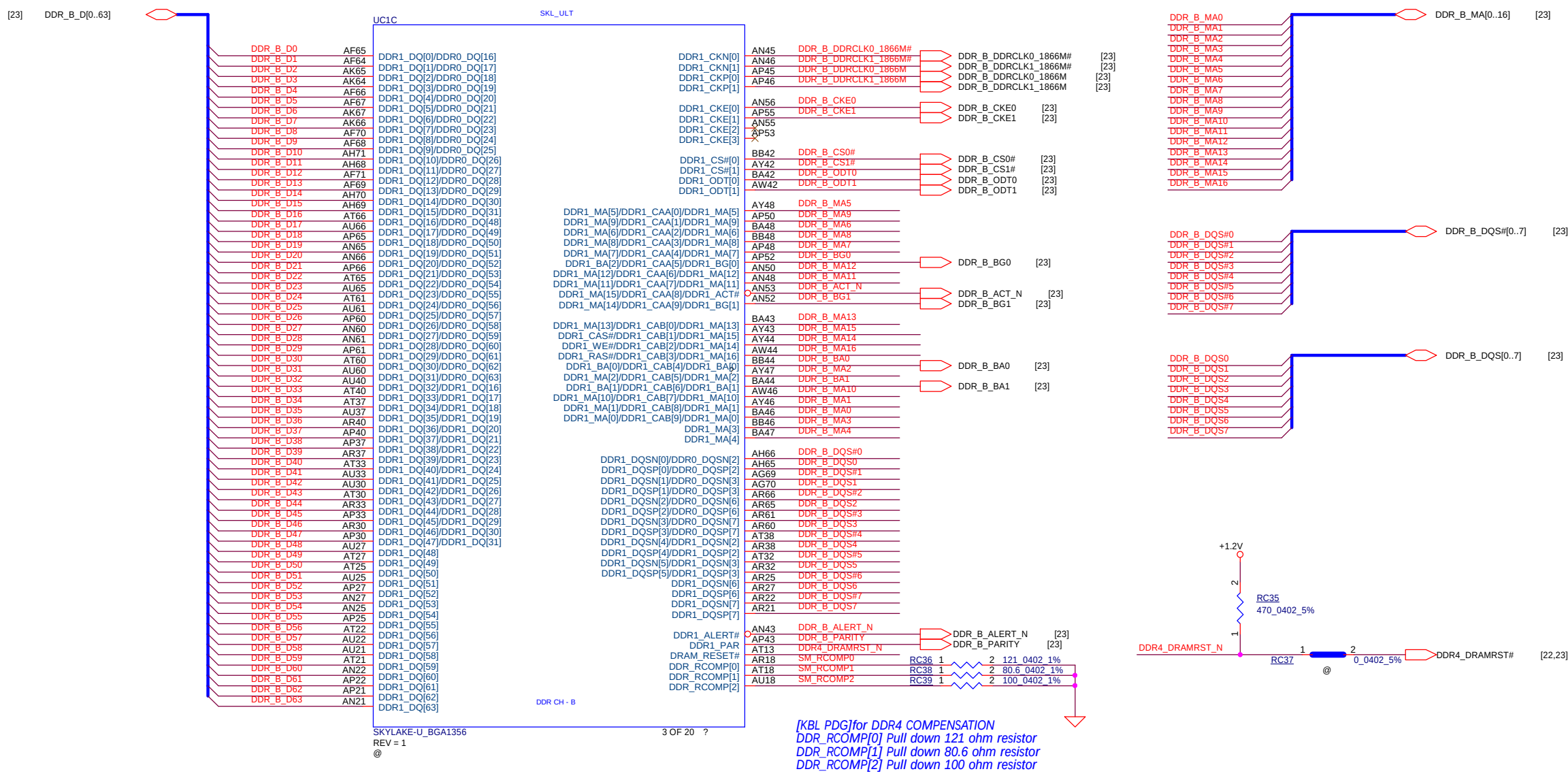


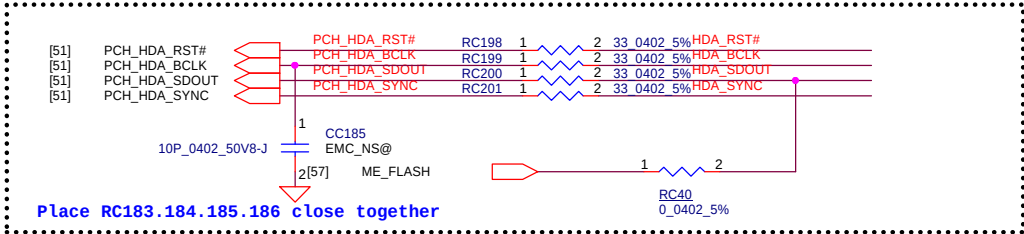
TABLE			
	Pin	Interleave	Non-Interleave
Block 1	AF86	DDR1_DQ[0]	DDR0_DQ[16]
	AF84	DDR1_DQ[1]	DDR0_DQ[17]
	AK86	DDR1_DQ[2]	DDR0_DQ[18]
	AK84	DDR1_DQ[3]	DDR0_DQ[19]
	AF88	DDR1_DQ[4]	DDR0_DQ[20]
	AF87	DDR1_DQ[5]	DDR0_DQ[21]
	AK87	DDR1_DQ[6]	DDR0_DQ[22]
	AK88	DDR1_DQ[7]	DDR0_DQ[23]
	AF70	DDR1_DQ[8]	DDR0_DQ[24]
	AF88	DDR1_DQ[9]	DDR0_DQ[25]
	AH71	DDR1_DQ[10]	DDR0_DQ[26]
	AH88	DDR1_DQ[11]	DDR0_DQ[27]
	AF71	DDR1_DQ[12]	DDR0_DQ[28]
	AF88	DDR1_DQ[13]	DDR0_DQ[29]
	AH70	DDR1_DQ[14]	DDR0_DQ[30]
	AH88	DDR1_DQ[15]	DDR0_DQ[31]
Block 3	AT88	DDR1_DQ[16]	DDR0_DQ[48]
	AU88	DDR1_DQ[17]	DDR0_DQ[49]
	AP86	DDR1_DQ[18]	DDR0_DQ[50]
	AN86	DDR1_DQ[19]	DDR0_DQ[51]
	AN88	DDR1_DQ[20]	DDR0_DQ[52]
	AP88	DDR1_DQ[21]	DDR0_DQ[53]
	AT86	DDR1_DQ[22]	DDR0_DQ[54]
	AU86	DDR1_DQ[23]	DDR0_DQ[55]
	AT81	DDR1_DQ[24]	DDR0_DQ[56]
	AU81	DDR1_DQ[25]	DDR0_DQ[57]
	AP80	DDR1_DQ[26]	DDR0_DQ[58]
	AN80	DDR1_DQ[27]	DDR0_DQ[59]
	AN81	DDR1_DQ[28]	DDR0_DQ[60]
	AP81	DDR1_DQ[29]	DDR0_DQ[61]
	AT80	DDR1_DQ[30]	DDR0_DQ[62]
	AU80	DDR1_DQ[31]	DDR0_DQ[63]
Block 5	AU40	DDR1_DQ[32]	DDR1_DQ[16]
	AT40	DDR1_DQ[33]	DDR1_DQ[17]
	AT37	DDR1_DQ[34]	DDR1_DQ[18]
	AU37	DDR1_DQ[35]	DDR1_DQ[19]
	AR40	DDR1_DQ[36]	DDR1_DQ[20]
	AP40	DDR1_DQ[37]	DDR1_DQ[21]
	AP37	DDR1_DQ[38]	DDR1_DQ[22]
	AR37	DDR1_DQ[39]	DDR1_DQ[23]
	AT33	DDR1_DQ[40]	DDR1_DQ[24]
	AU33	DDR1_DQ[41]	DDR1_DQ[25]
	AU30	DDR1_DQ[42]	DDR1_DQ[26]
	AT30	DDR1_DQ[43]	DDR1_DQ[27]
	AR33	DDR1_DQ[44]	DDR1_DQ[28]
	AP33	DDR1_DQ[45]	DDR1_DQ[29]
	AR30	DDR1_DQ[46]	DDR1_DQ[30]
	AP30	DDR1_DQ[47]	DDR1_DQ[31]
Block 7	AU27	DDR1_DQ[48]	DDR1_DQ[48]
	AT27	DDR1_DQ[49]	DDR1_DQ[49]
	AT26	DDR1_DQ[50]	DDR1_DQ[50]
	AU26	DDR1_DQ[51]	DDR1_DQ[51]
	AP27	DDR1_DQ[52]	DDR1_DQ[52]
	AN27	DDR1_DQ[53]	DDR1_DQ[53]
	AN26	DDR1_DQ[54]	DDR1_DQ[54]
	AP26	DDR1_DQ[55]	DDR1_DQ[55]
	AT22	DDR1_DQ[56]	DDR1_DQ[56]
	AU22	DDR1_DQ[57]	DDR1_DQ[57]
	AU21	DDR1_DQ[58]	DDR1_DQ[58]
	AT21	DDR1_DQ[59]	DDR1_DQ[59]
	AN22	DDR1_DQ[60]	DDR1_DQ[60]
	AP22	DDR1_DQ[61]	DDR1_DQ[61]
	AP21	DDR1_DQ[62]	DDR1_DQ[62]
	AN21	DDR1_DQ[63]	DDR1_DQ[63]

TABLE			
	Pin	Interleave	Non-Interleave
Block 1	AH86	DDR1_DQSN[0]	DDR0_DQSN[2]
	AH65	DDR1_DQSP[0]	DDR0_DQSP[2]
	AG69	DDR1_DQSN[1]	DDR0_DQSN[3]
	AG70	DDR1_DQSP[1]	DDR0_DQSP[3]
Block 3	AR66	DDR1_DQSN[2]	DDR0_DQSN[6]
	AR65	DDR1_DQSP[2]	DDR0_DQSP[6]
	AR61	DDR1_DQSN[3]	DDR0_DQSN[7]
	AR60	DDR1_DQSP[3]	DDR0_DQSP[7]
Block 5	AT38	DDR1_DQSN[4]	DDR1_DQSN[2]
	AR38	DDR1_DQSP[4]	DDR1_DQSP[2]
	AT32	DDR1_DQSN[5]	DDR1_DQSN[3]
	AR32	DDR1_DQSP[5]	DDR1_DQSP[3]
Block 7	AR25	DDR1_DQSN[6]	DDR1_DQSN[6]
	AR27	DDR1_DQSP[6]	DDR1_DQSP[6]
	AR22	DDR1_DQSN[7]	DDR1_DQSN[7]
	AR21	DDR1_DQSP[7]	DDR1_DQSP[7]

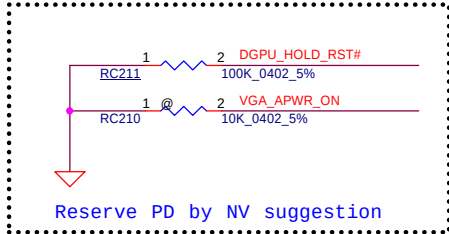
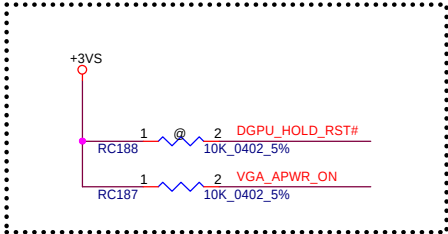
TABLE			
Pin	DDR3L	LPDDR3	DDR4
AY48	DDR1_MA[5]	DDR1_GAA[0]	DDR1_MA[5]
AP90	DDR1_MA[8]	DDR1_GAA[1]	DDR1_MA[9]
BA48	DDR1_MA[6]	DDR1_GAA[2]	DDR1_MA[6]
BS48	DDR1_MA[8]	DDR1_GAA[3]	DDR1_MA[8]
AP48	DDR1_MA[7]	DDR1_GAA[4]	DDR1_MA[7]
AP82	DDR1_BA[2]	DDR1_GAA[5]	DDR1_BG[0]
AN50	DDR1_MA[12]	DDR1_GAA[6]	DDR1_MA[12]
AN48	DDR1_MA[11]	DDR1_GAA[7]	DDR1_MA[11]
AN53	DDR1_MA[10]	DDR1_GAA[8]	DDR1_ACT#
AN52	DDR1_MA[14]	DDR1_GAA[9]	DDR1_BG[1]
BA43	DDR1_MA[13]	DDR1_CAB[0]	DDR1_MA[13]
AY43	DDR1_CAS#	DDR1_CAB[1]	DDR1_MA[16]
AY44	DDR1_WE#	DDR1_CAB[2]	DDR1_MA[14]
AW44	DDR1_RAS#	DDR1_CAB[3]	DDR1_MA[16]
BS44	DDR1_BA[0]	DDR1_CAB[4]	DDR1_BA[0]
AY47	DDR1_MA[2]	DDR1_CAB[5]	DDR1_MA[2]
BA44	DDR1_BA[1]	DDR1_CAB[6]	DDR1_BA[1]
AW46	DDR1_MA[10]	DDR1_CAB[7]	DDR1_MA[10]
AY46	DDR1_MA[11]	DDR1_CAB[8]	DDR1_MA[11]
BA46	DDR1_MA[0]	DDR1_CAB[9]	DDR1_MA[0]
BB46	DDR1_MA[3]	Not Used	DDR1_MA[3]
BA47	DDR1_MA[4]	Not Used	DDR1_MA[4]



[KBL PDG]Manufacturing Mode Jumper
1. If strap is sampled low, the security measures defined in the Flash Descriptor will be in effect (default)
2. If sampled high, the Flash Descriptor Security will be overridden.

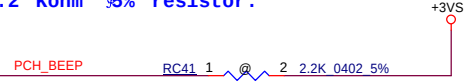


20160408
1.Unstaff RC188 and Staff RC211 with 100K resistor

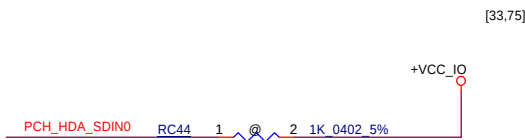


Note:
SPKR (PC_BEEP) has an integrated weak pull-down resistor (20 K ohm nominal) to disable Top-Block Sway by default.

To enable Top-Block Swap, this signal should be pulled up to V3.3S through a 1k to 2.2 Kohm 5% resistor.



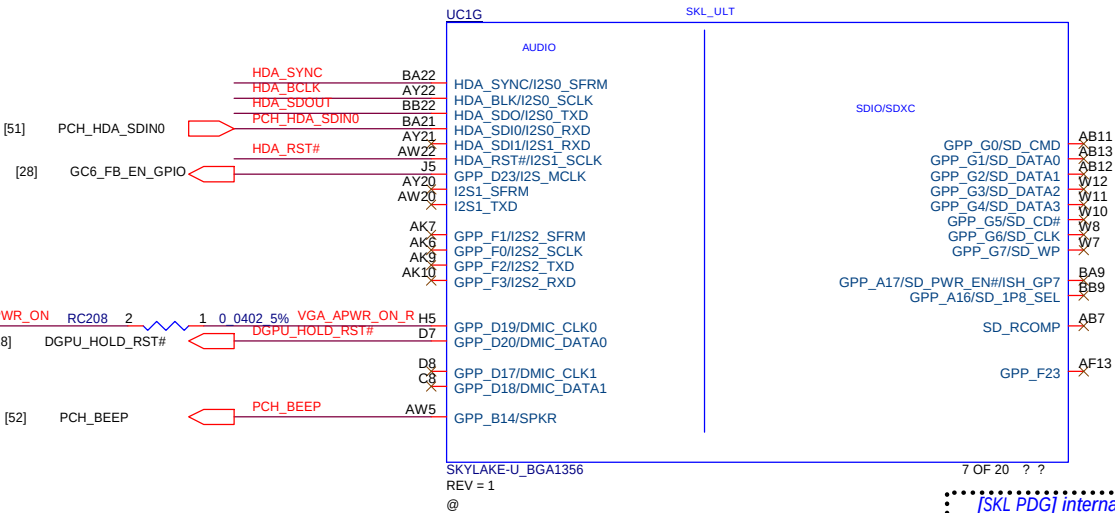
Note:
Internal PD 20K



Note:
HDA_SDO should only be asserted high via external pull-up to 3.3A rail in manufacturing/debug environments ONLY.

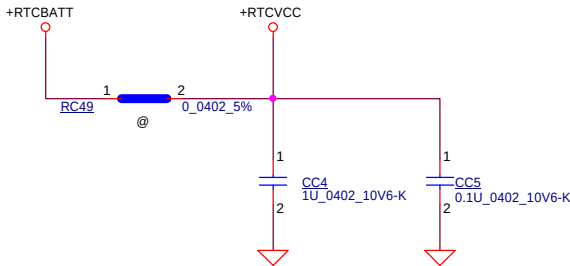


Note:
Internal PD 20K

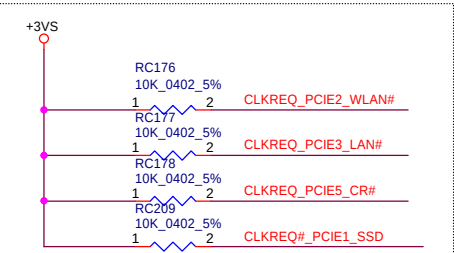
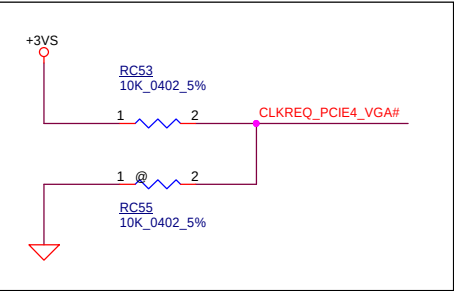
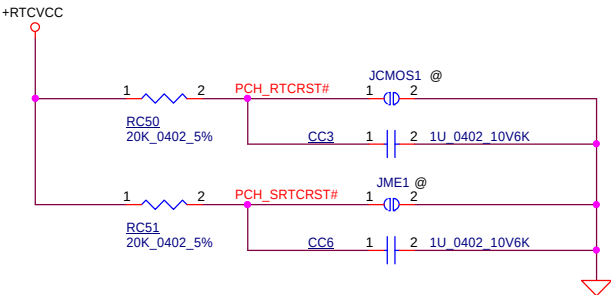


RTC External Circuit

+RTCBATT, +RTCVCC
Trace width = 20mils



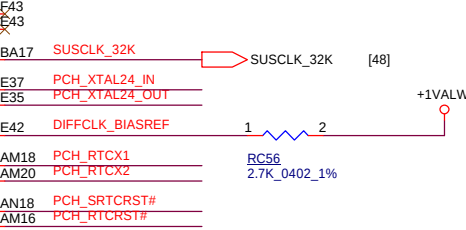
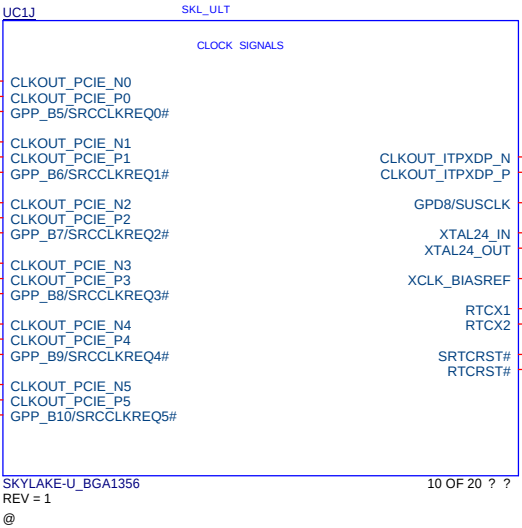
JCMOS, JME Setting, Need Under DDR Door



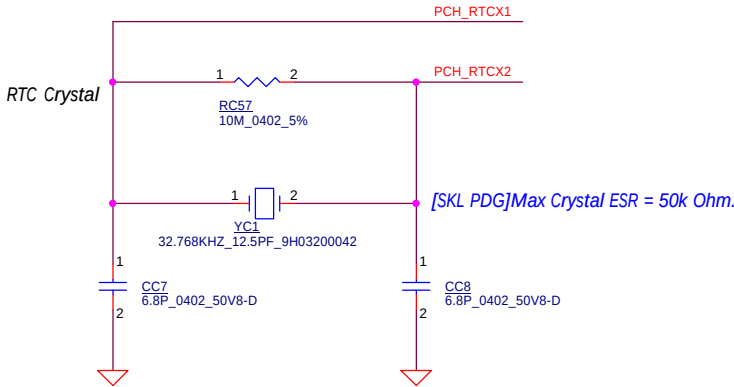
Place RC176,177,178,209 close together

M.2 SSD	[42]	CLK_PCIE_SSD#	CLK_PCIE_SSD#
	[42]	CLK_PCIE_SSD	CLK_PCIE_SSD
	[42]	CLKREQ_PCIE1_SSD	CLKREQ_PCIE1_SSD
WLAN	[48]	CLK_PCIE_WLAN#	CLK_PCIE_WLAN#
	[48]	CLK_PCIE_WLAN	CLK_PCIE_WLAN
	[48]	CLKREQ_PCIE2_WLAN#	CLKREQ_PCIE2_WLAN#
LAN	[46]	CLK_PCIE_LAN#	CLK_PCIE_LAN#
	[46]	CLK_PCIE_LAN	CLK_PCIE_LAN
	[46]	CLKREQ_PCIE3_LAN#	CLKREQ_PCIE3_LAN#
VGA	[25]	CLK_PCIE_VGA#	CLK_PCIE_VGA#
	[25]	CLK_PCIE_VGA	CLK_PCIE_VGA
	[25]	CLKREQ_PCIE4_VGA#	CLKREQ_PCIE4_VGA#
CR	[49]	CLK_PCIE_CR#	CLK_PCIE_CR#
	[49]	CLK_PCIE_CR	CLK_PCIE_CR
	[49]	CLKREQ_PCIE5_CR#	CLKREQ_PCIE5_CR#

[SKL PDG]External pull-up resistor required if used for CLKREQ# functionality.

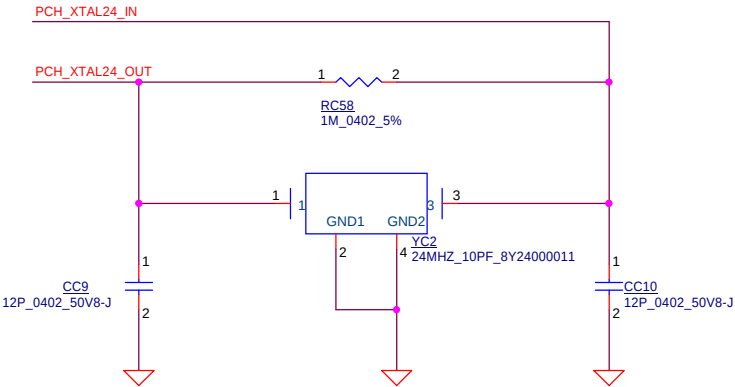


[SKL PDG]
1.Space > 15mils
2.No trace under crystal
3.Place on opposit side of MCP for temp inf l uence
4.The exact capacitor values forC1 and C2 must be based on the crystal maker recommendat i ons
Typical values for C1 and C2 are 18 pF, based on crystal load of 12.5 pF.

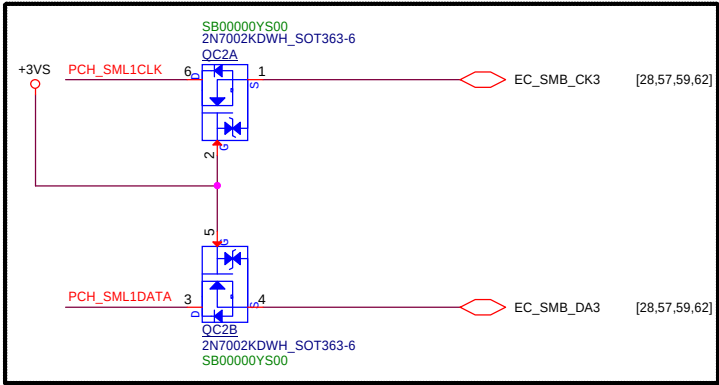
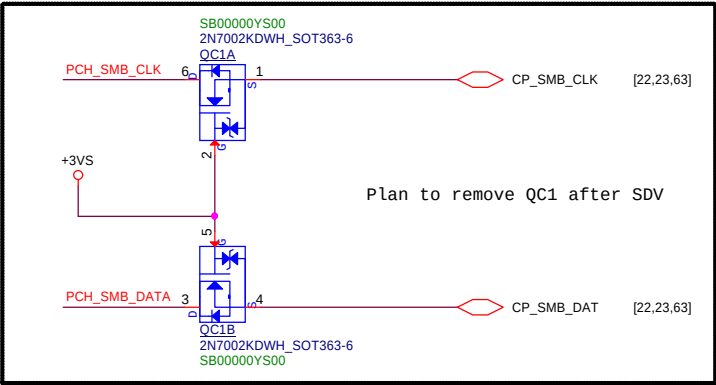
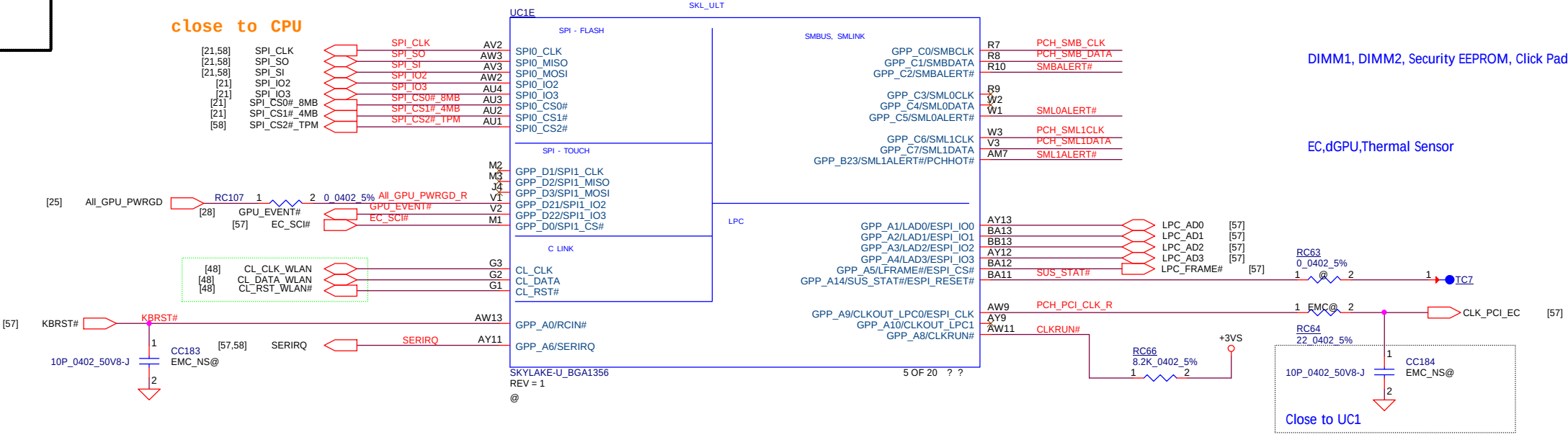
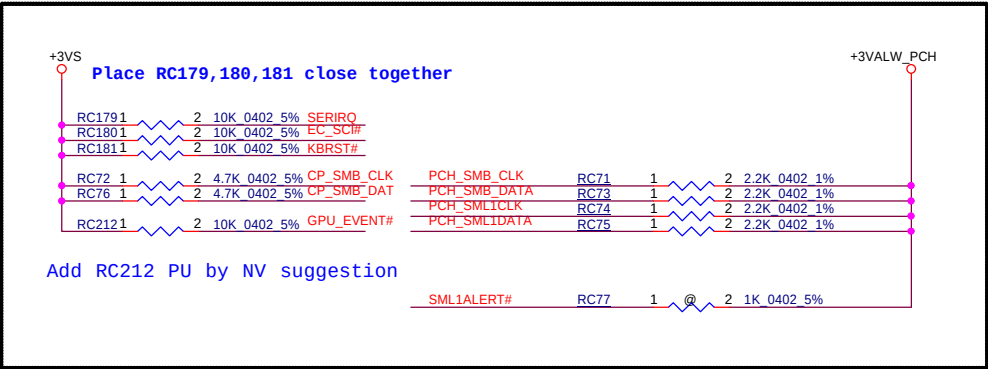
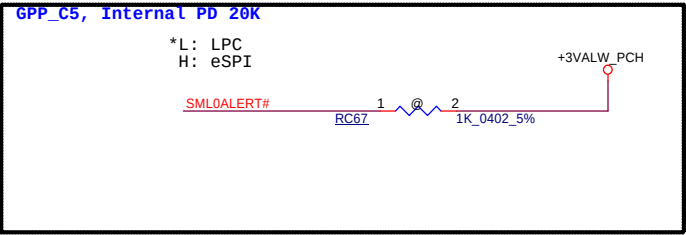
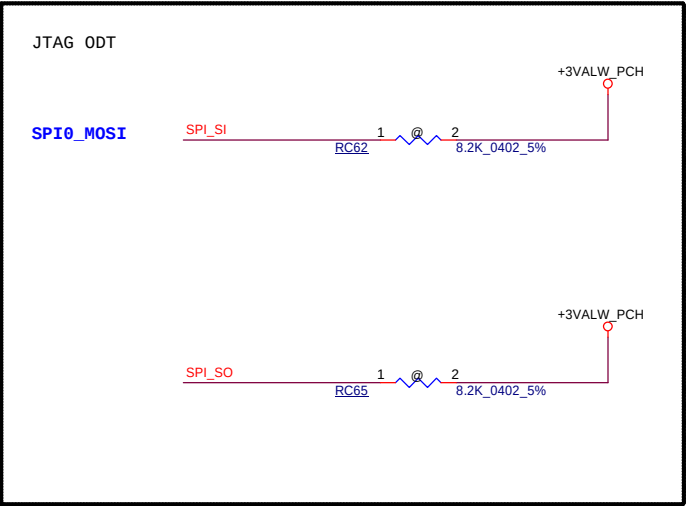
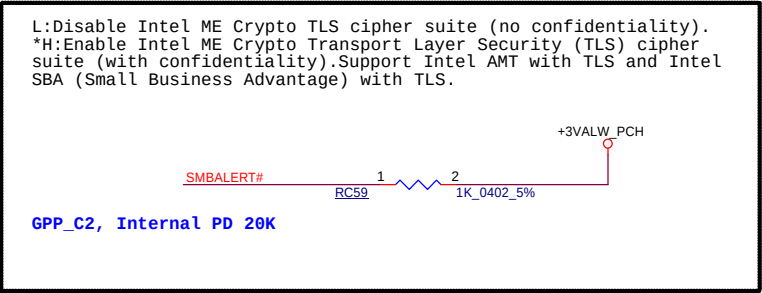


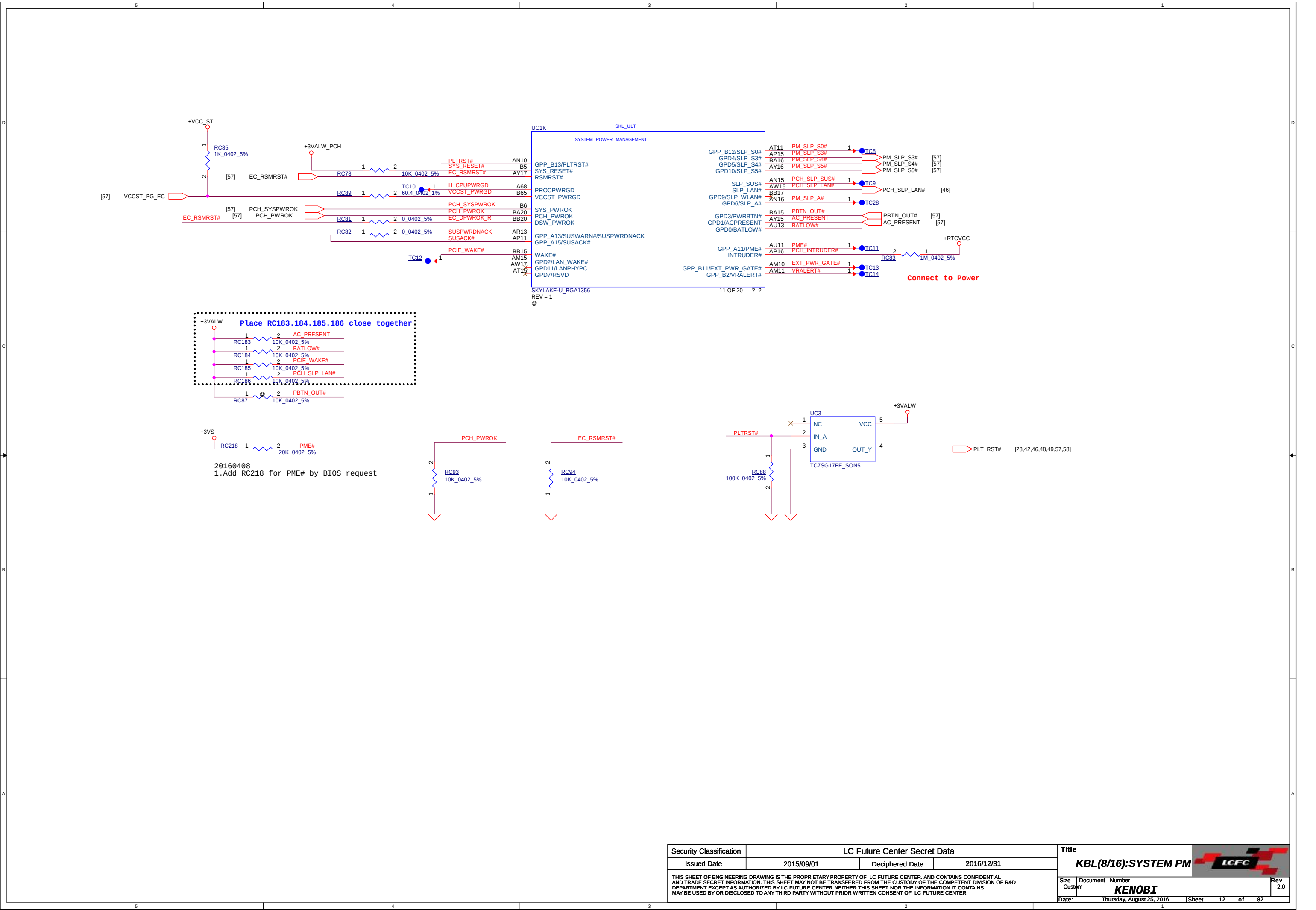
20160127
Change CC7/CC8 to 6.8p by vender suggestion

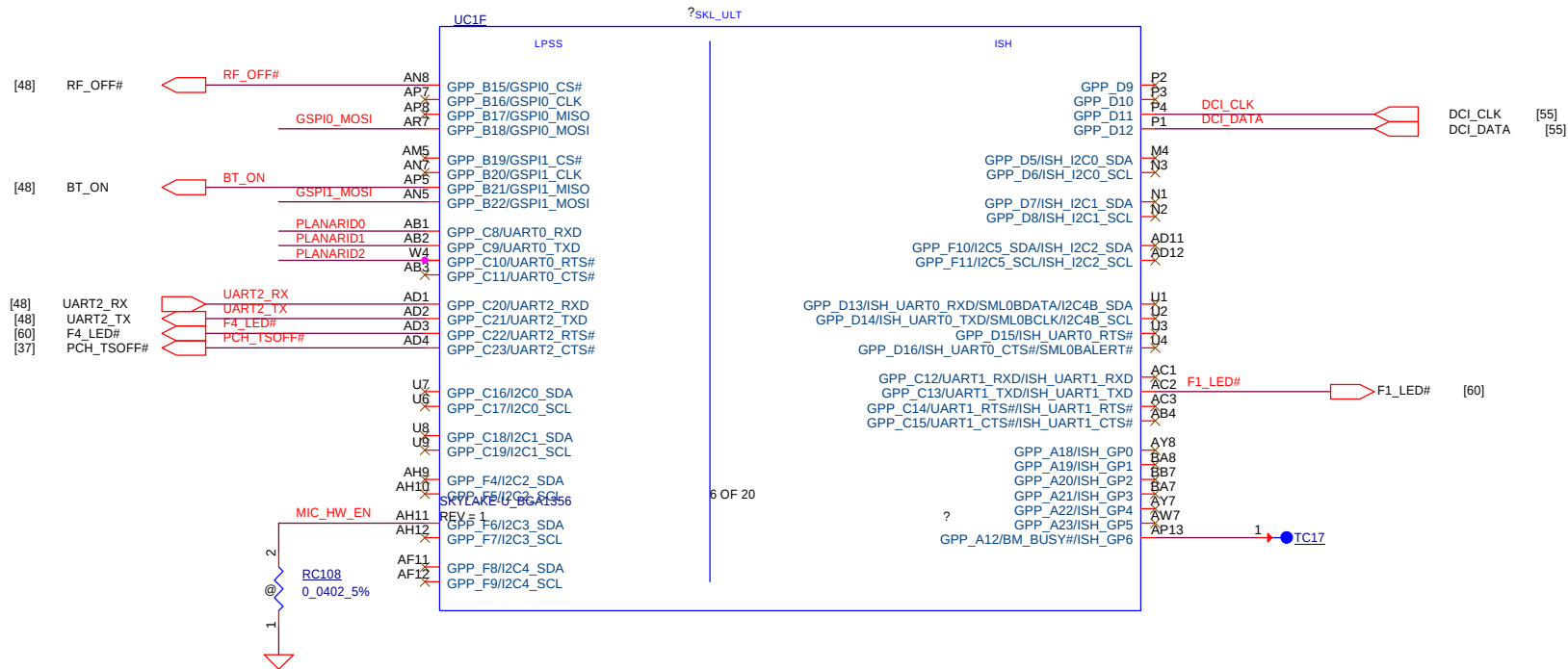
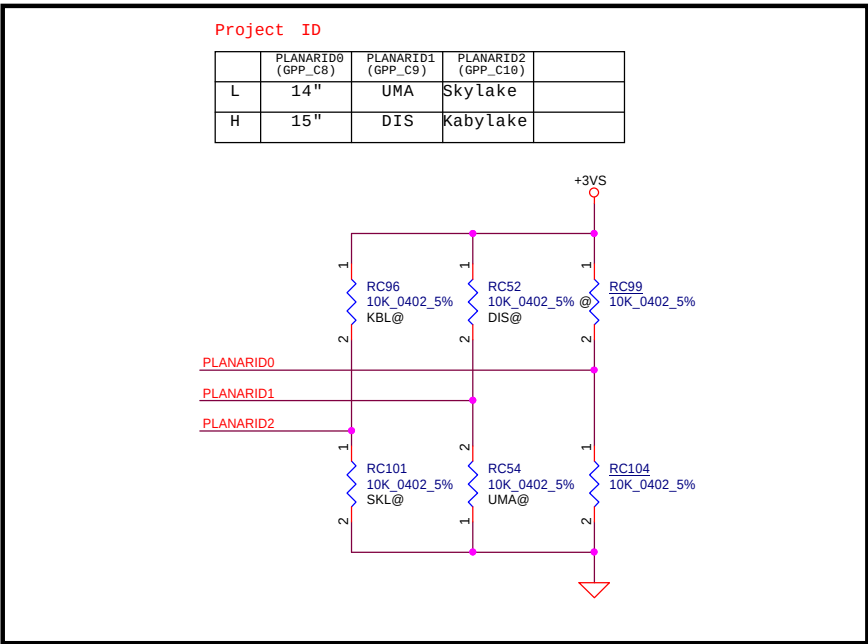
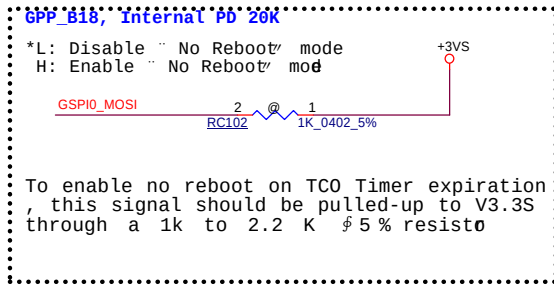
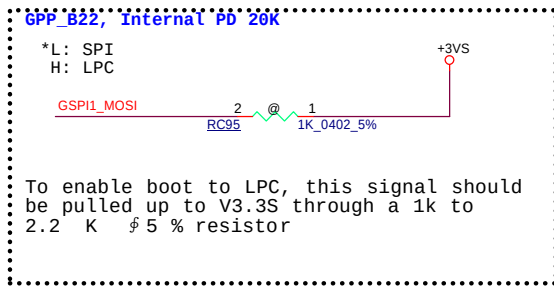
[SKL PDG]
1.A 24 MHz crystal with crystal frequency tolerance and stability of +/-30 ppm
2.Two External Load Capacitors (Ce1 and Ce2)
3.A 1-Mohm bias resistor (Rf)

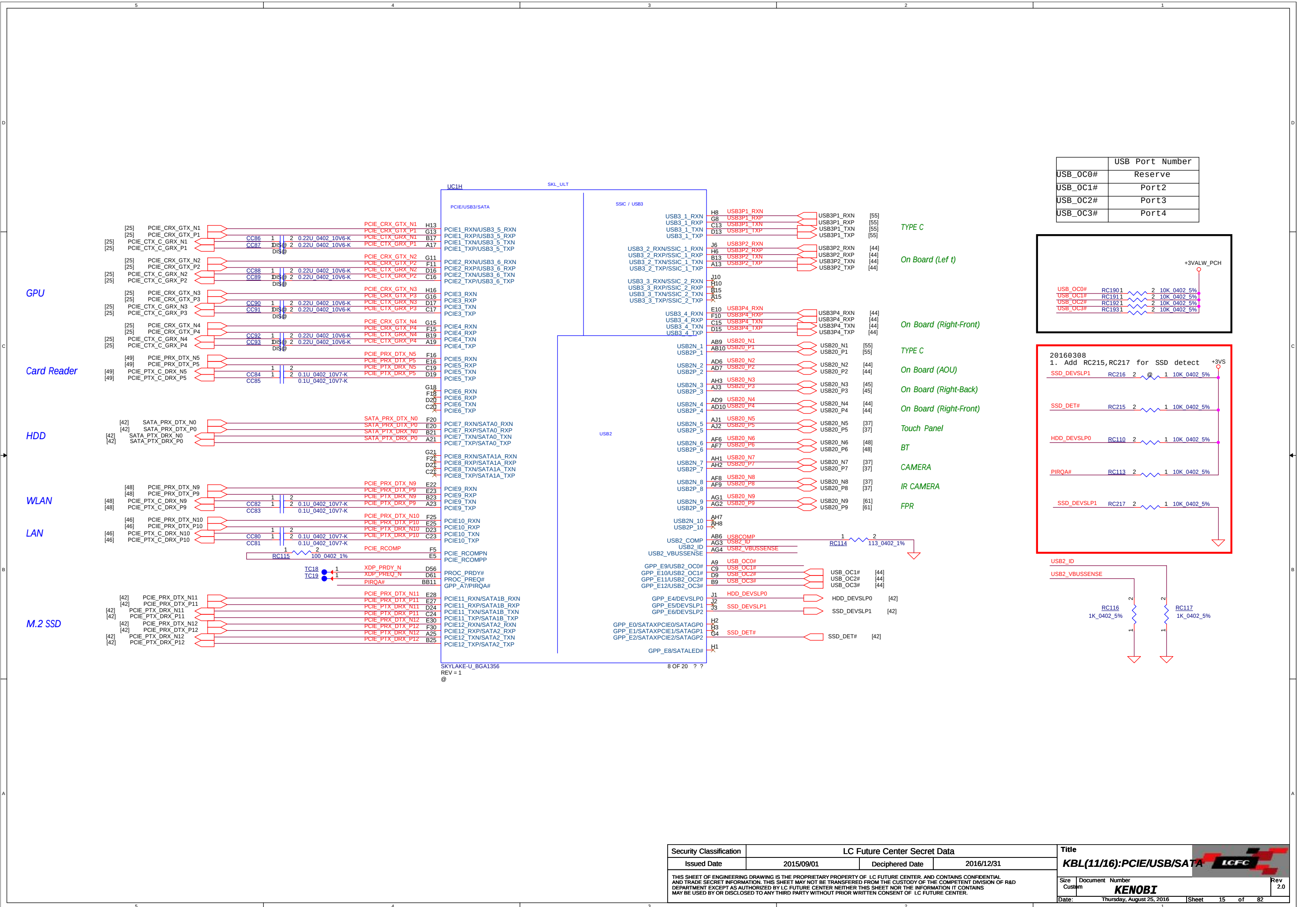


Functional Strap Definitions

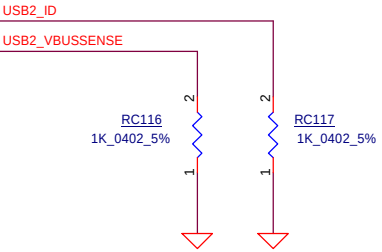
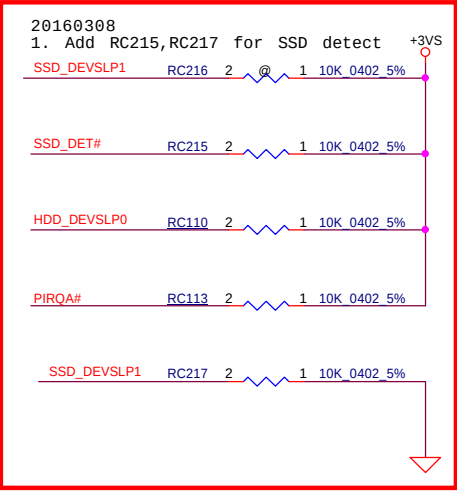
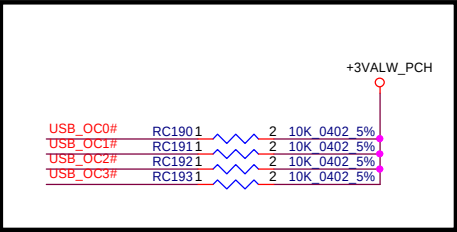


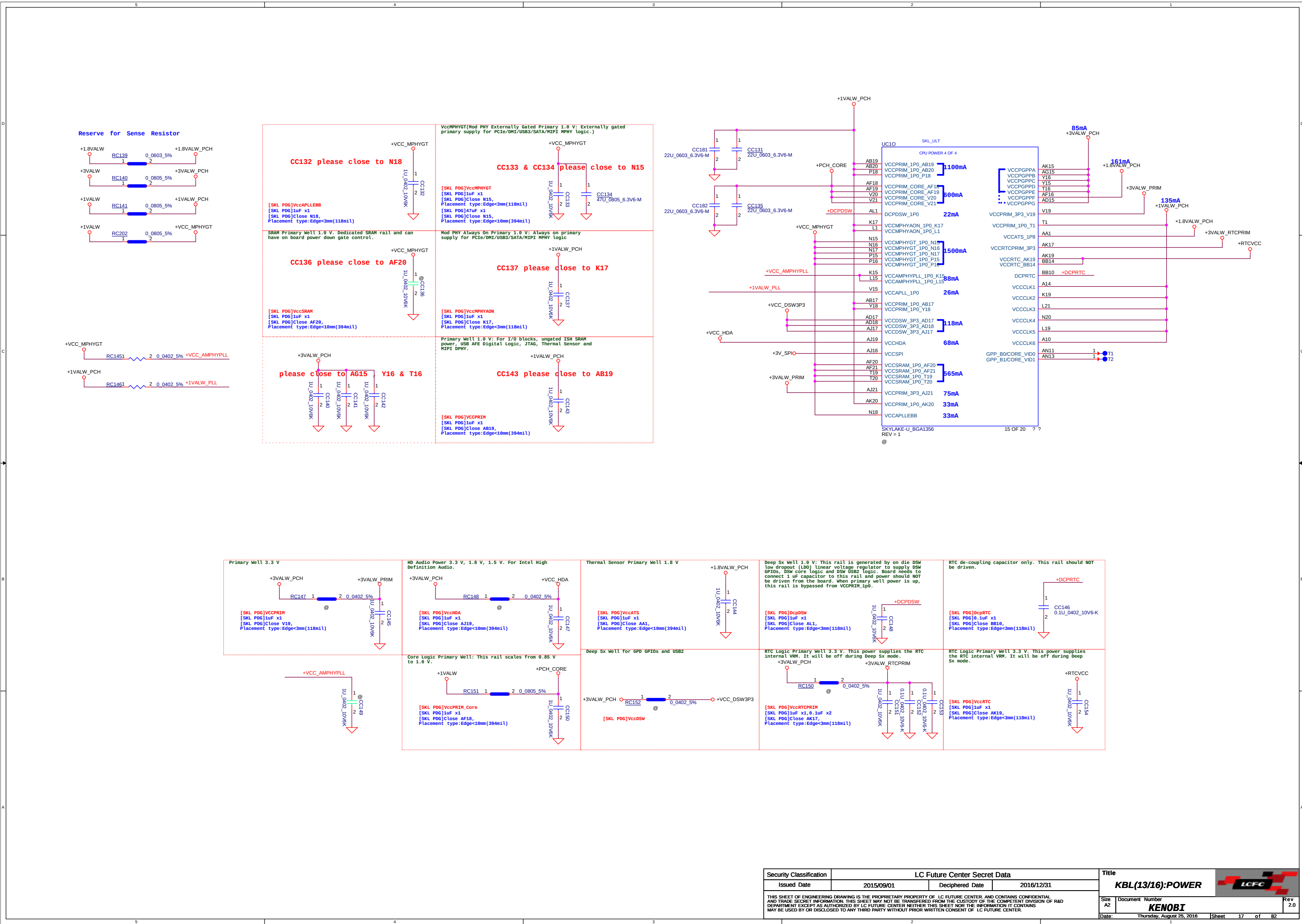






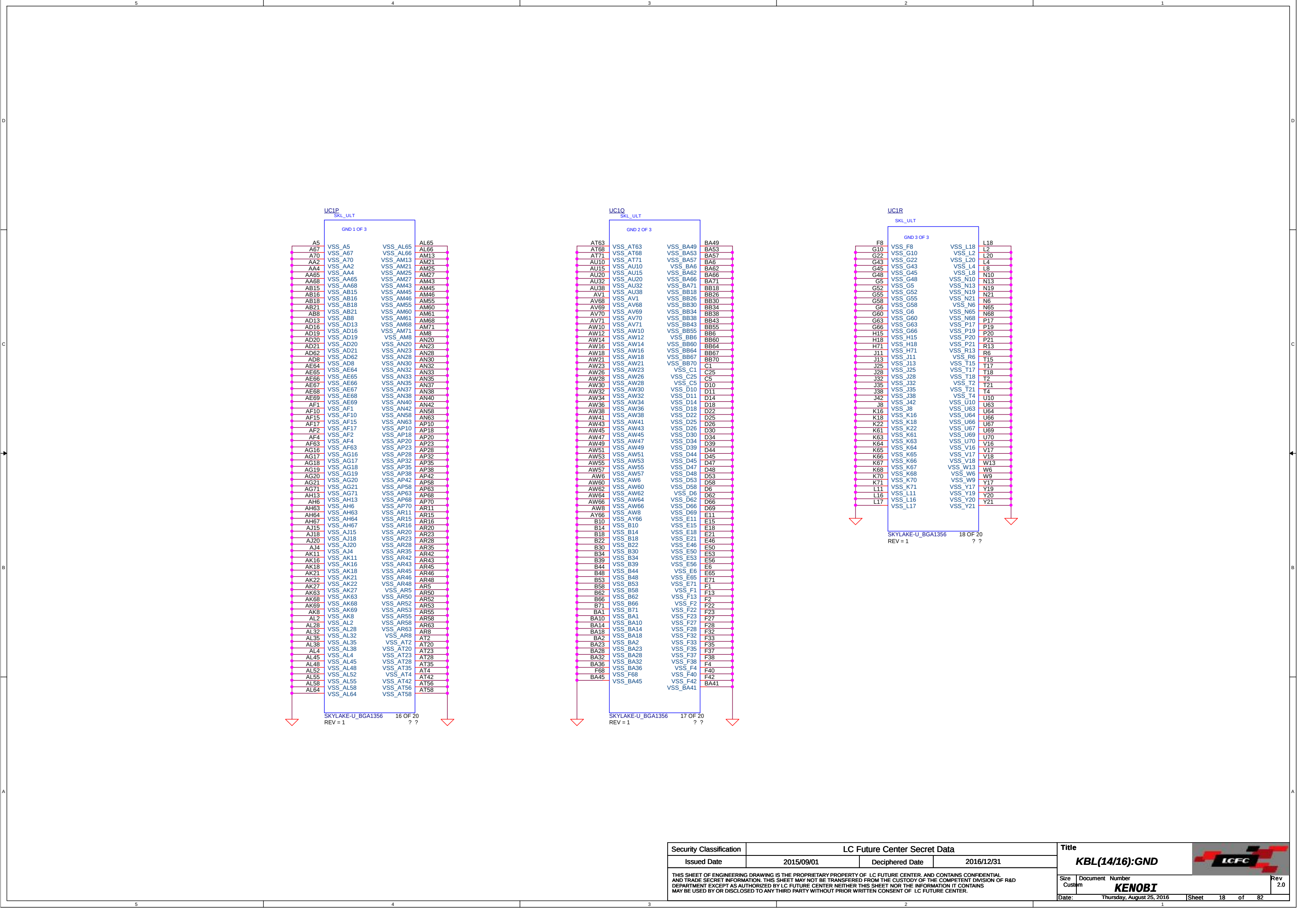
	USB Port Number
USB_OC0#	Reserve
USB_OC1#	Port2
USB_OC2#	Port3
USB_OC3#	Port4

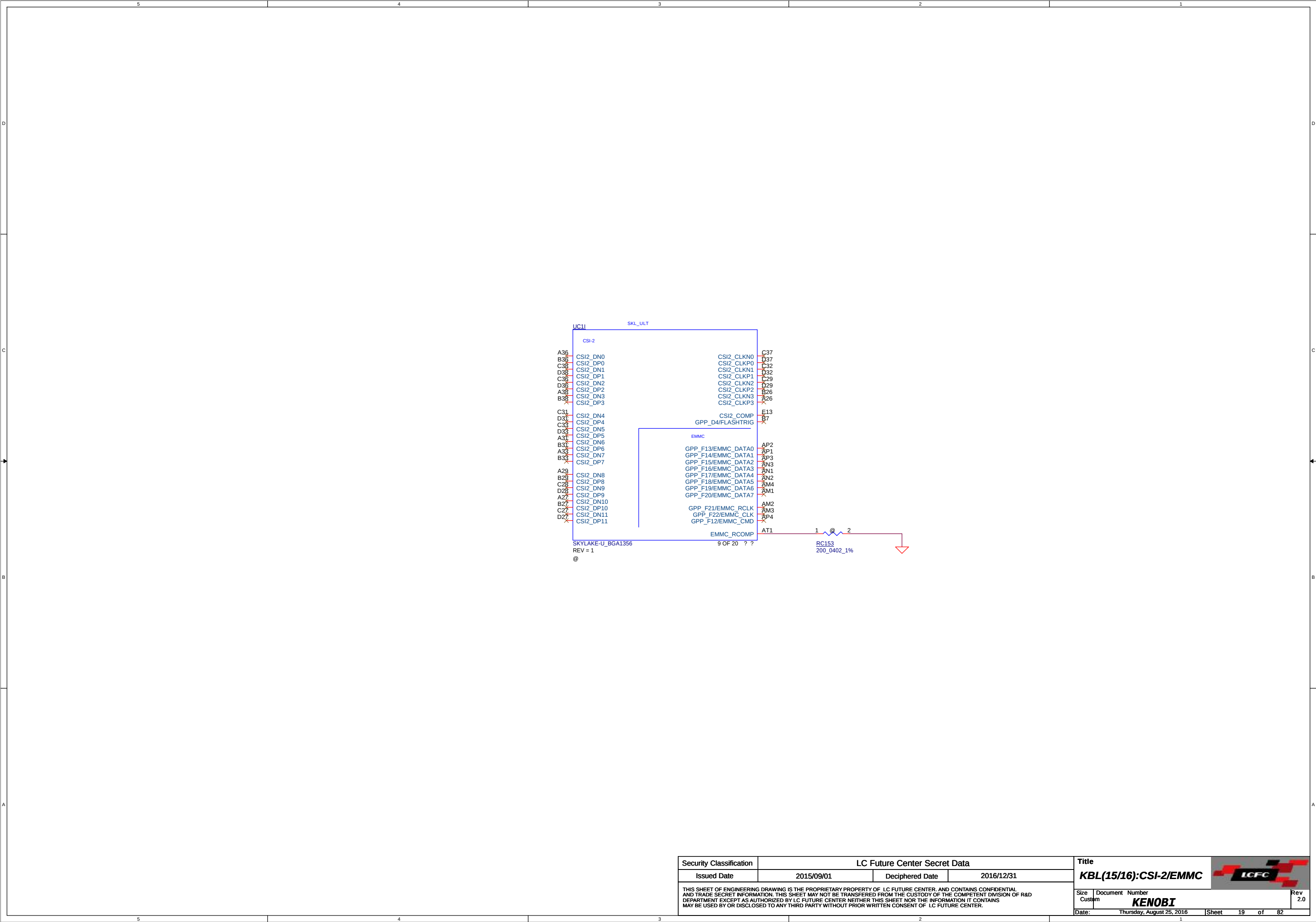


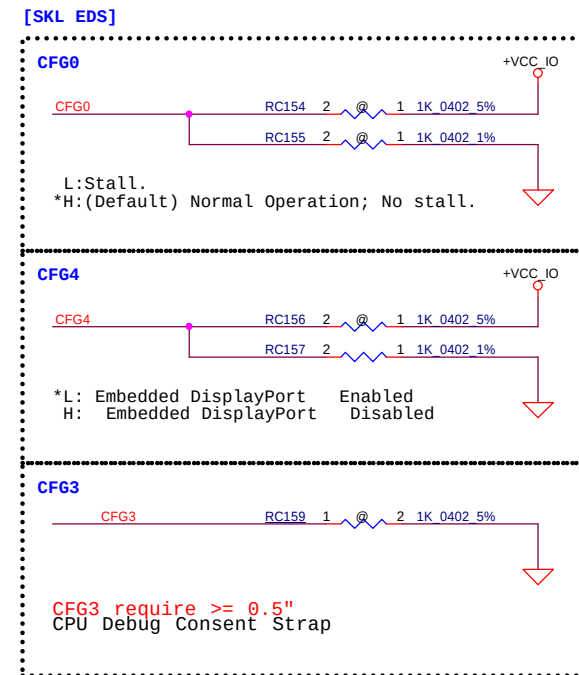
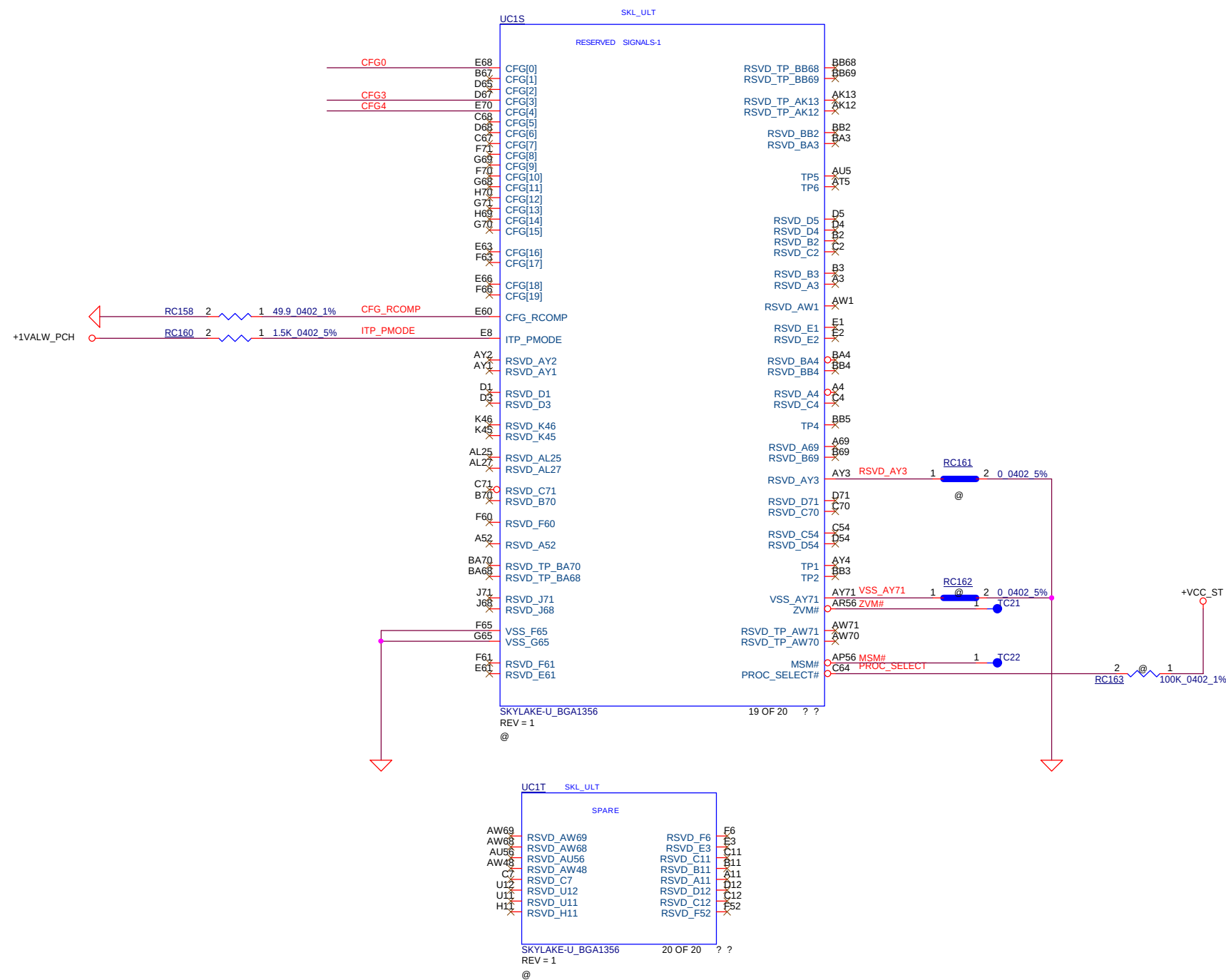


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Date:	Thursday, August 25, 2016	Sheet	17 of 82







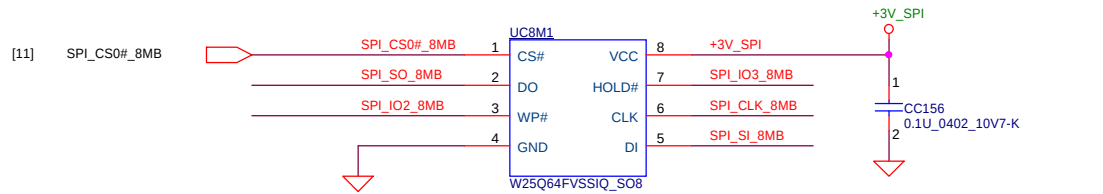
TABLE

CFG0 : Stall Reset Sequence after PCU PLL Lock until de-asserted 1 : No Stall 0 : Stall
CFG4 : eDP Enable 1 : Disabled 0 : Enabled

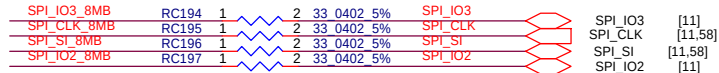
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Issued Date	2015/09/01	Deciphered Date	2016/12/31	KBL(16/16):CFG/RESERVED		
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Date:				Thursday, August 25, 2016	Sheet	20 of 82



4MB(32Mb) Reserve



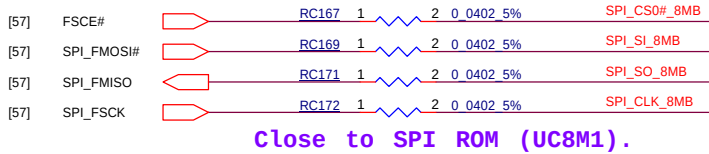
Place RC194,195,196,197 close together



Near SPI ROM

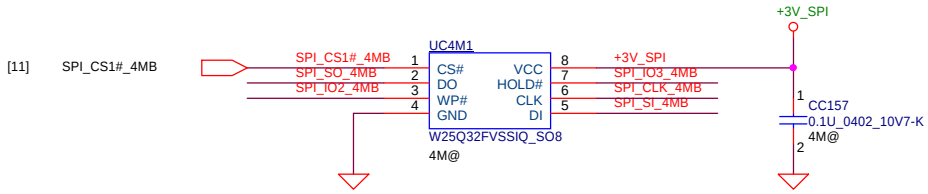


Mirror Code

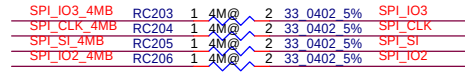


8MB(64Mb)

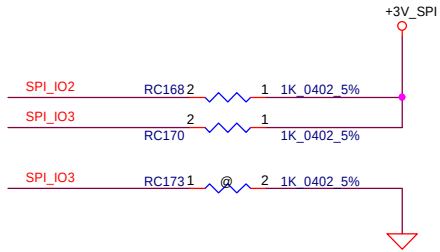
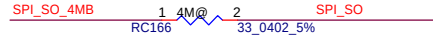
[SKL]SPI0_CS0#: SPI FLASH
SPI0_CS1#: SPI FLASH
SPI0_CS2#: SPI TPM

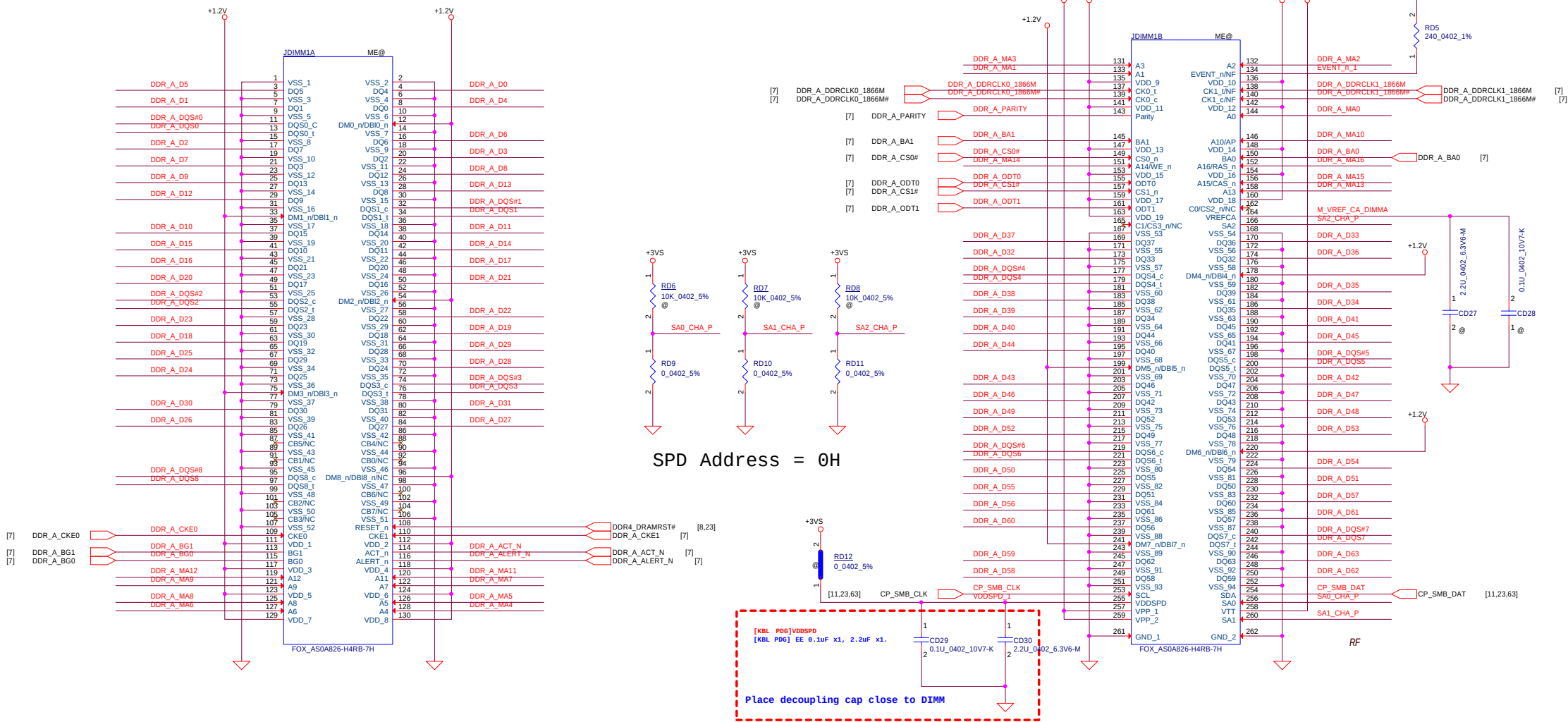
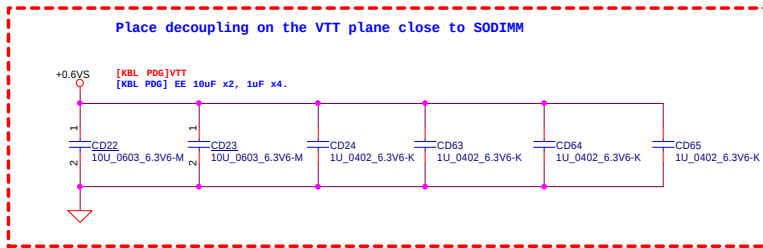
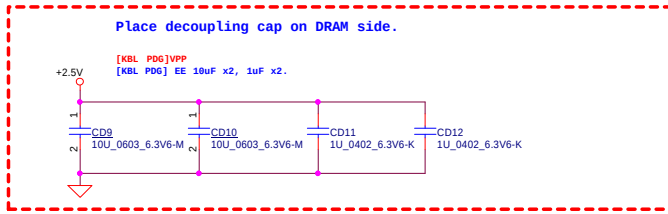
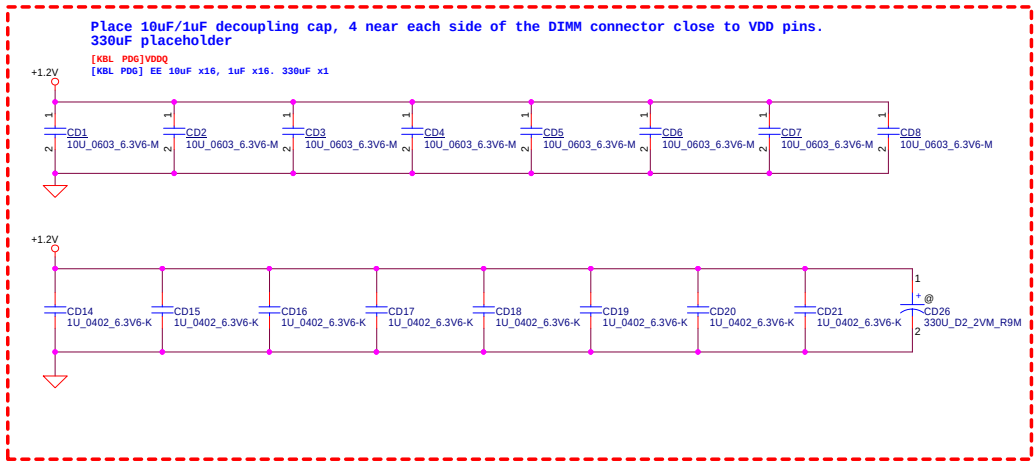


Place RC203,204,205,206 close together

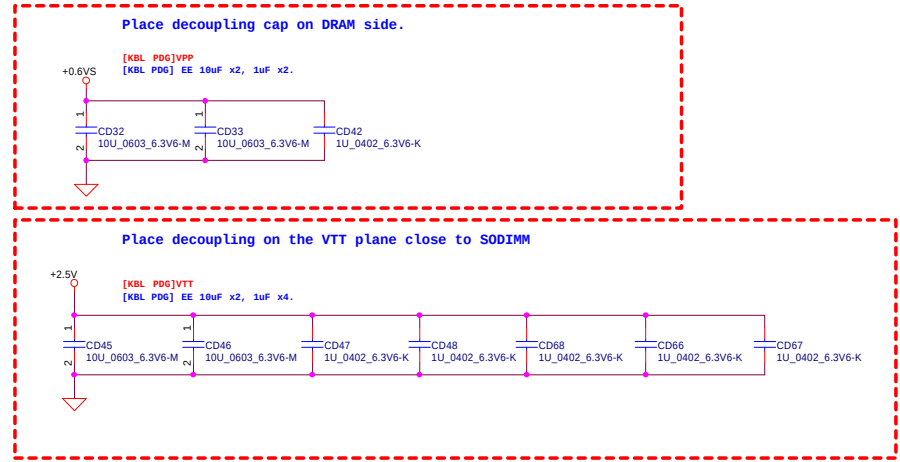
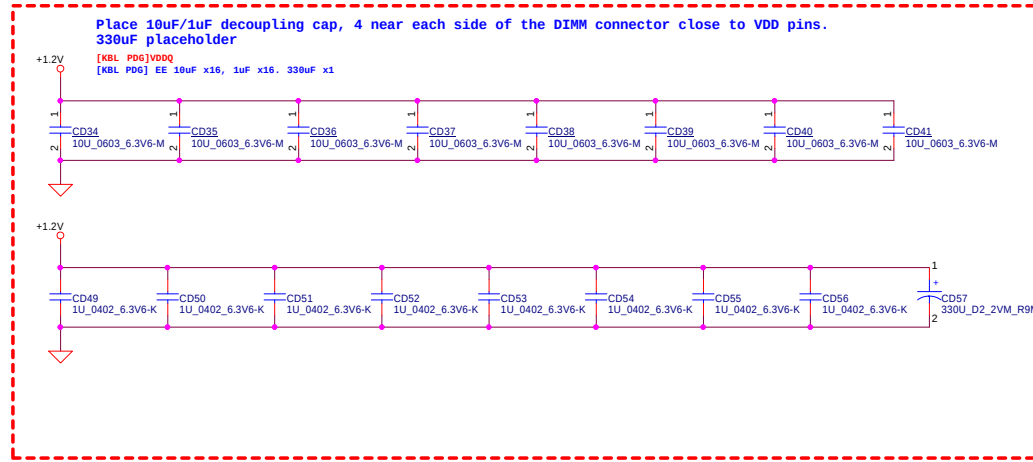


Near SPI ROM

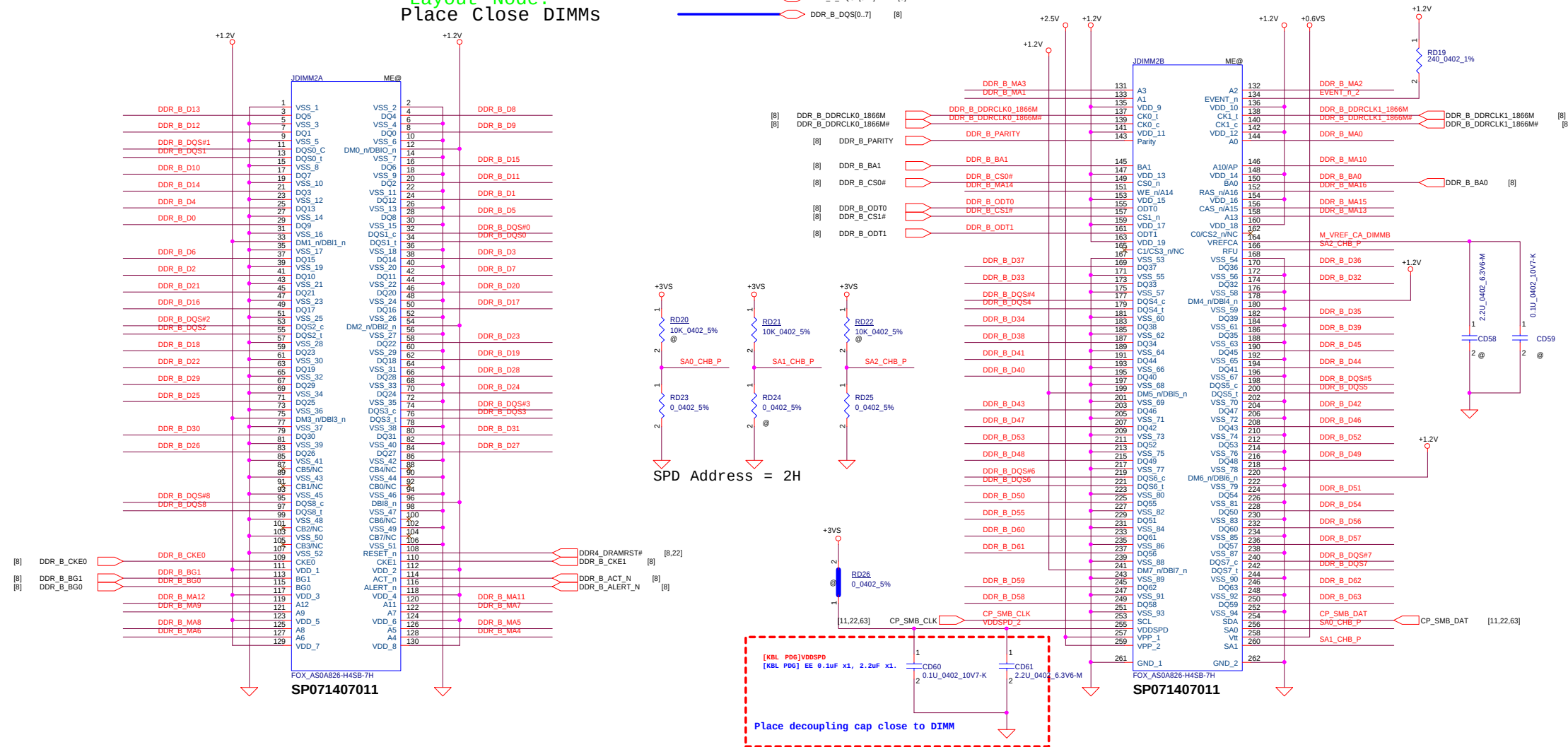
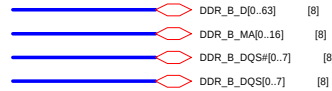




Signal Name	Description	Dir.	Buffer Type	Link Type	Availability
DDR0_DQSP[8:0] DDR0_DQSN[8:0] DDR1_DQSP[8:0] DDR1_DQSN[8:0]	Data Strobes: Differential data strobe pairs. The data is captured at the crossing point of DQS during read and write transactions.	I/O	DDR4/-R5	Diff	The 9th signals[8] are applicable for UDIMM/ SODIM module with ECC in S and H-processor line processors

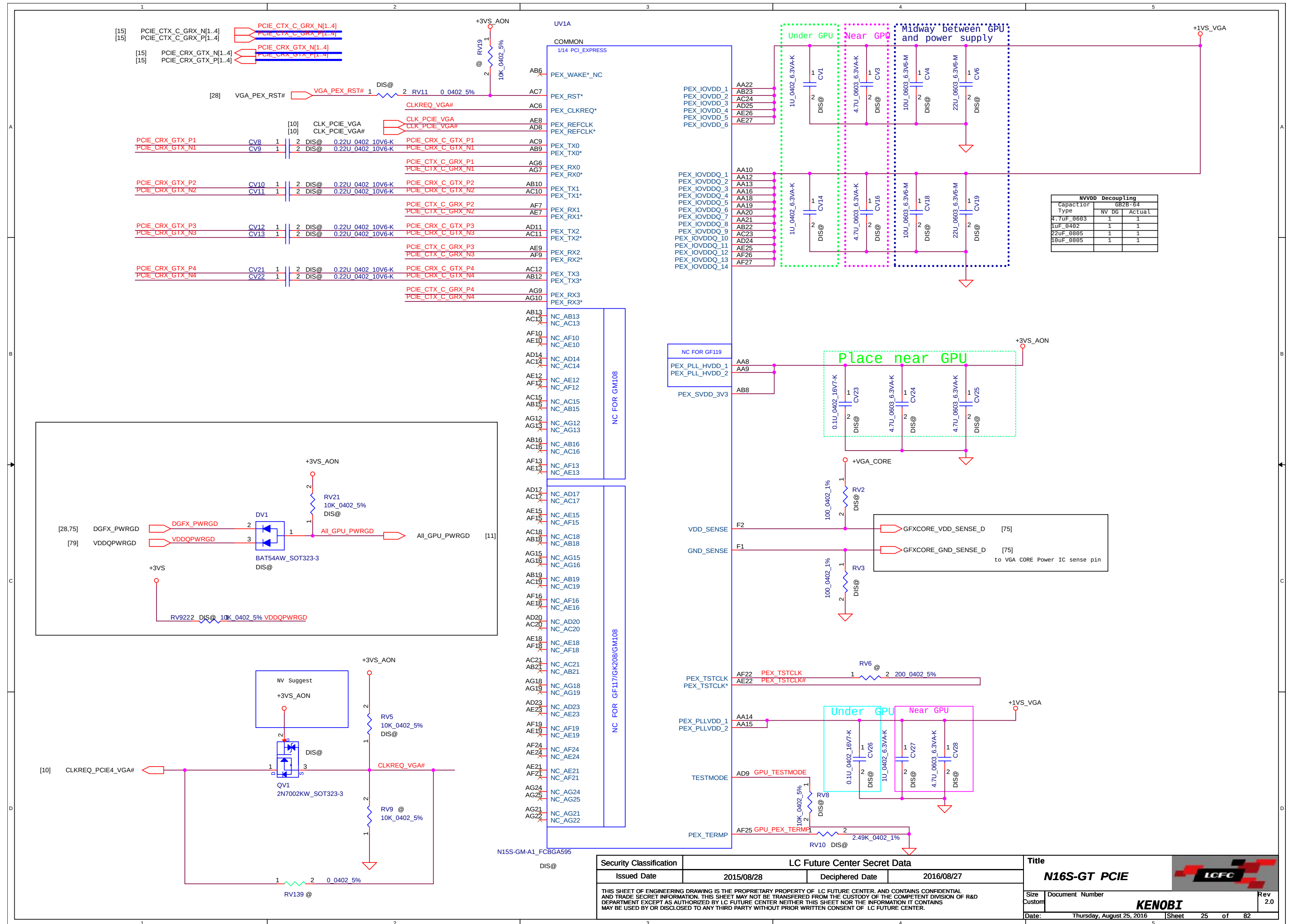


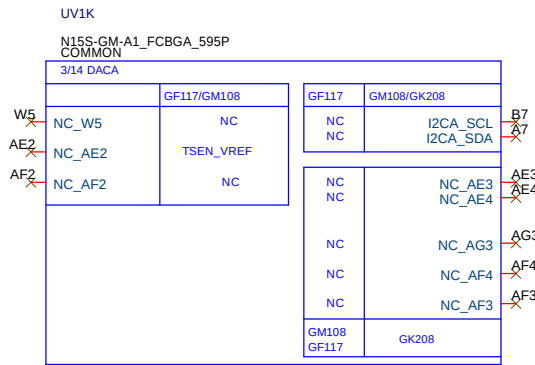
Layout Node:
Place Close DIMMs



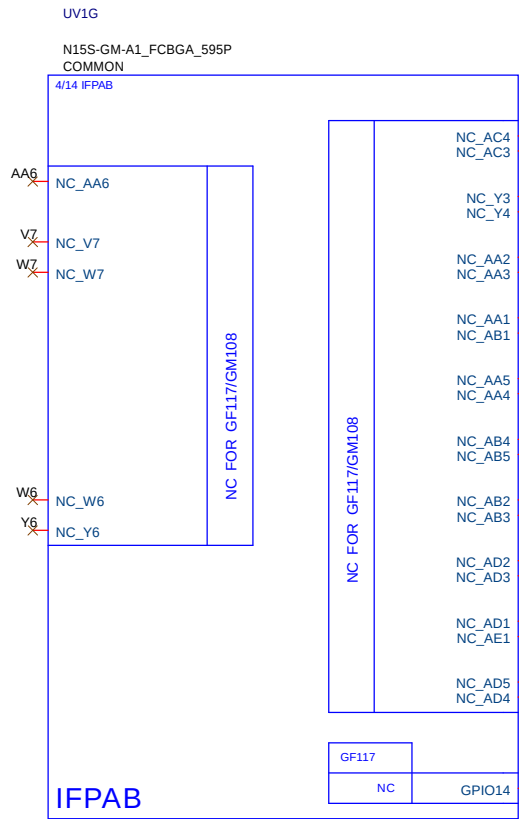
Signal Name	Description	Dir.	Buffer Type	Link Type	Availability
DDR0_DQSP[8:0] DDR0_DQSN[8:0] DDR1_DQSP[8:0] DDR1_DQSN[8:0]	Data Strobes: Differential data strobe pairs. The data is captured at the crossing point of DQS during read and write transactions.	I/O	DDR4/-RS	DIFF	The 9th signals(8) are applicable for UDIMM/SODIM module with ECC in S and H-processor line processors

5			4			3			2			1		

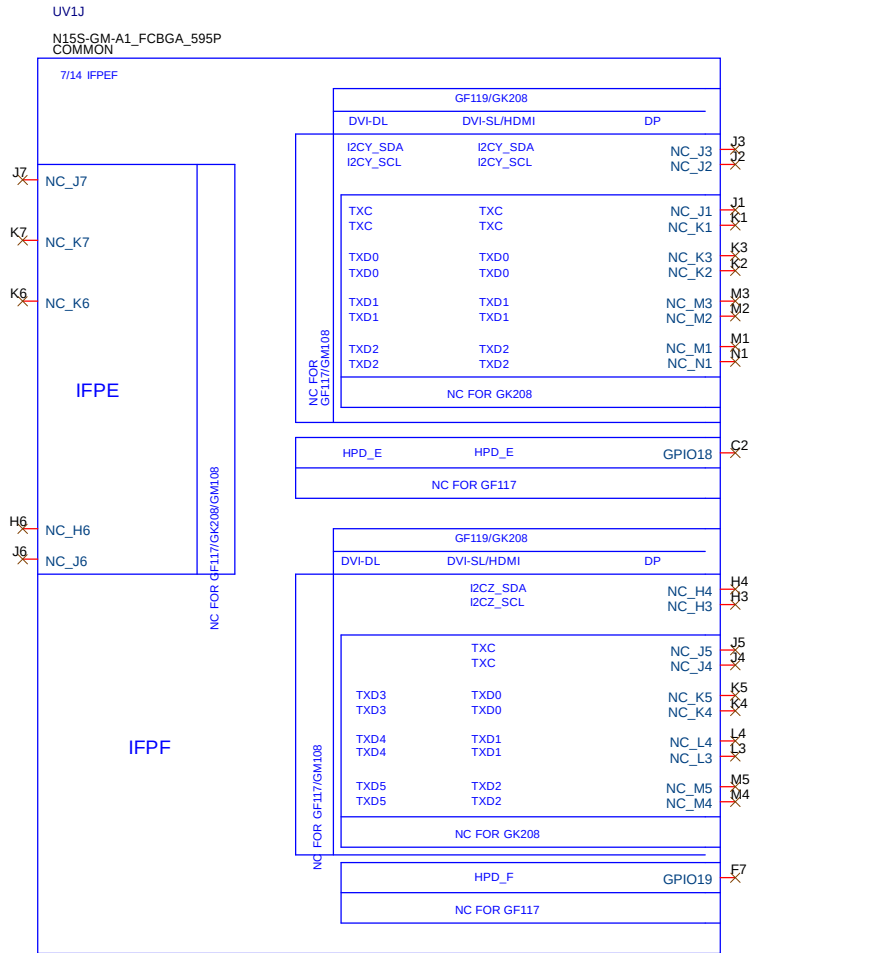




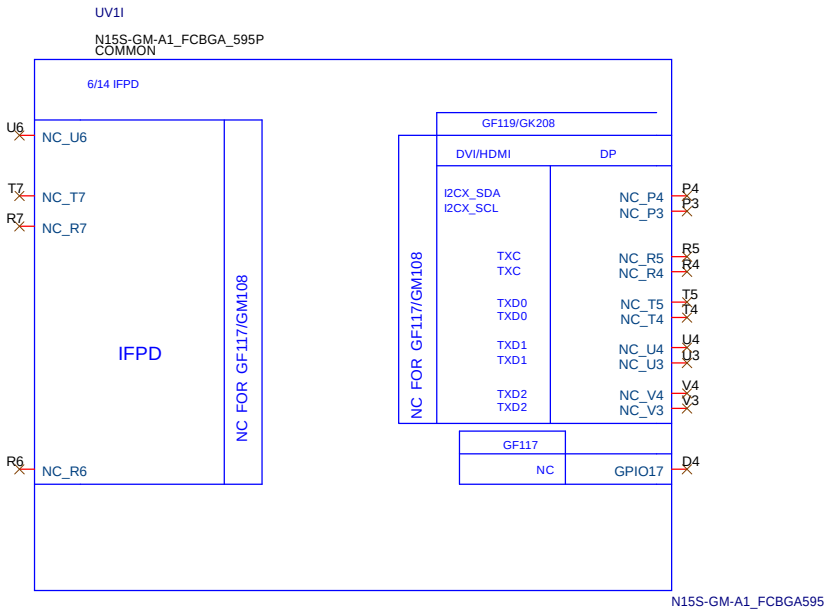
N15S-GM-A1_FCBGA595



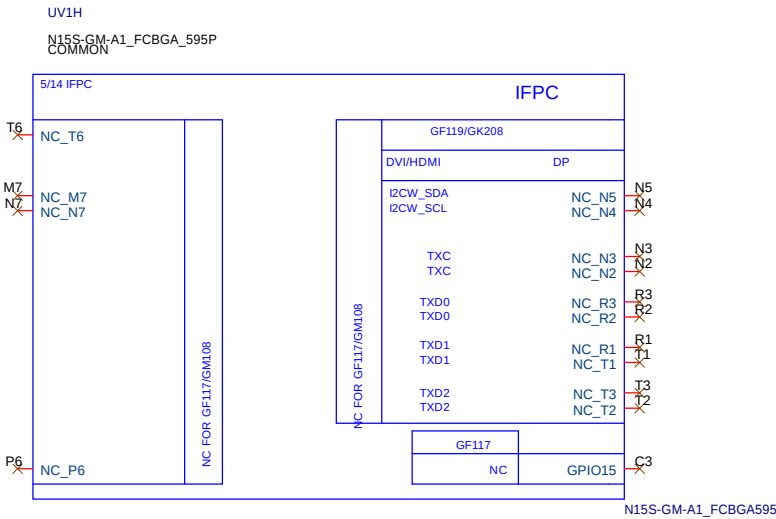
N15S-GM-A1_FCBGA595



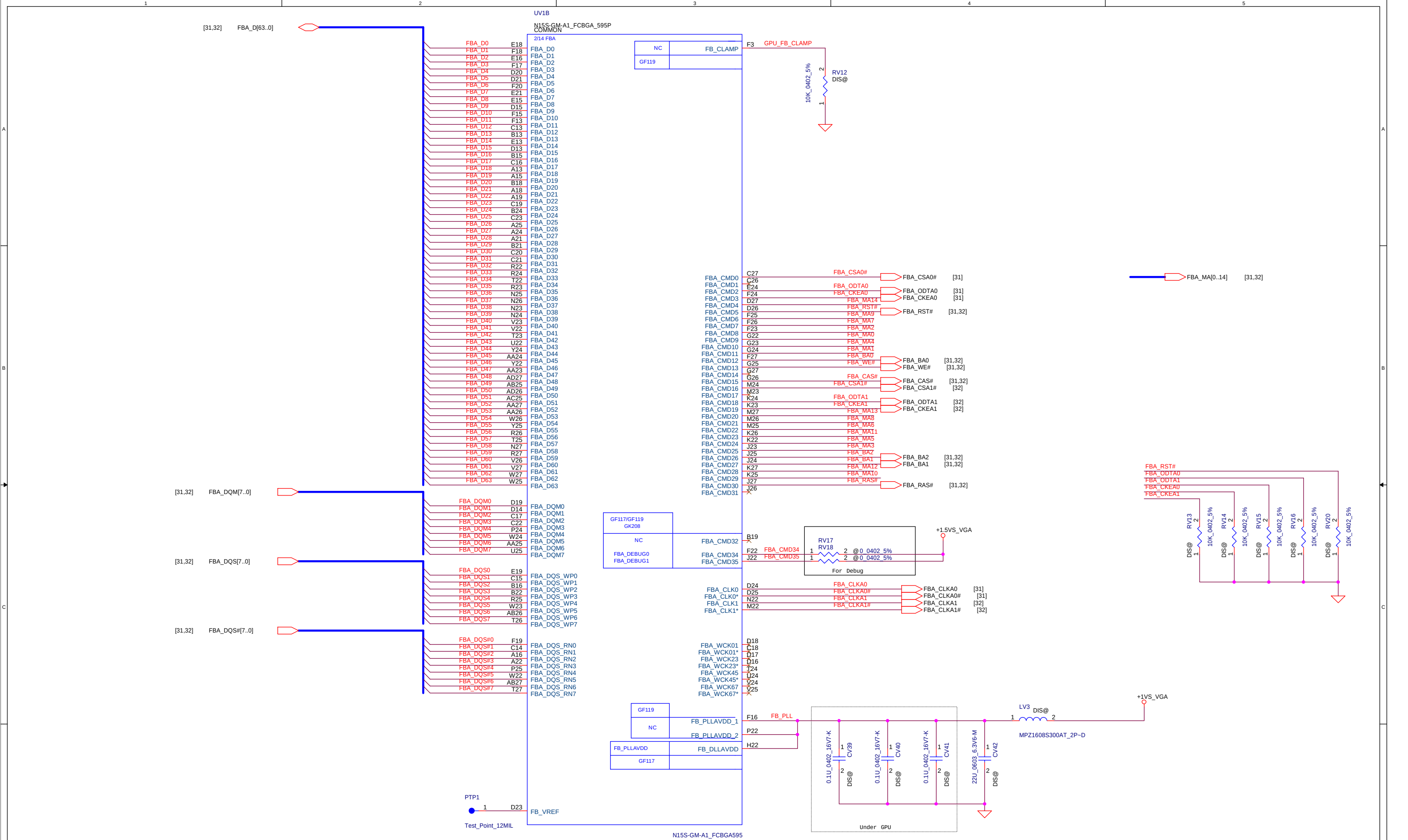
N15S-GM-A1_FCBGA595

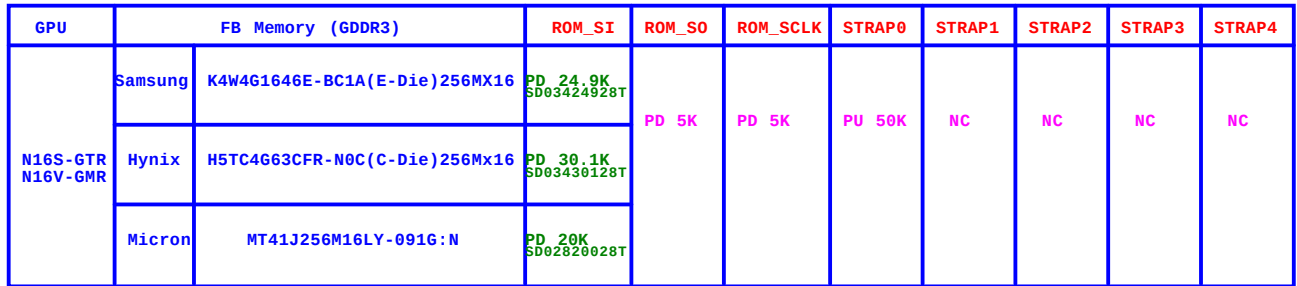


N15S-GM-A1_FCBGA595

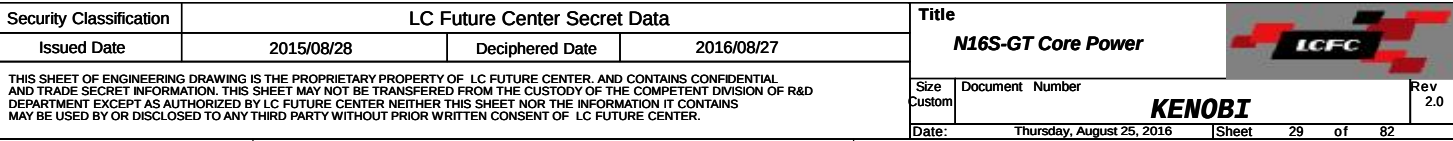


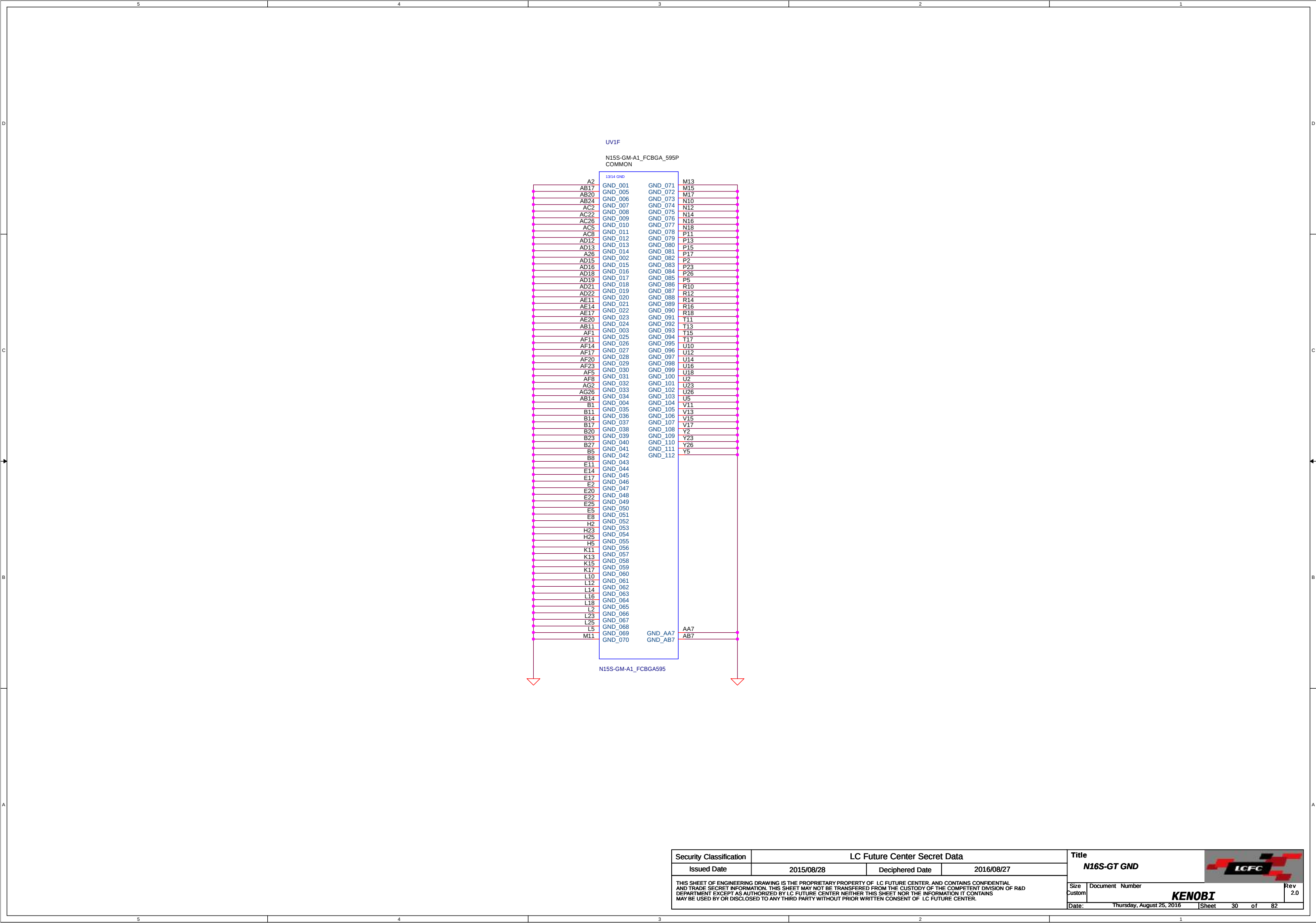
N15S-GM-A1_FCBGA595



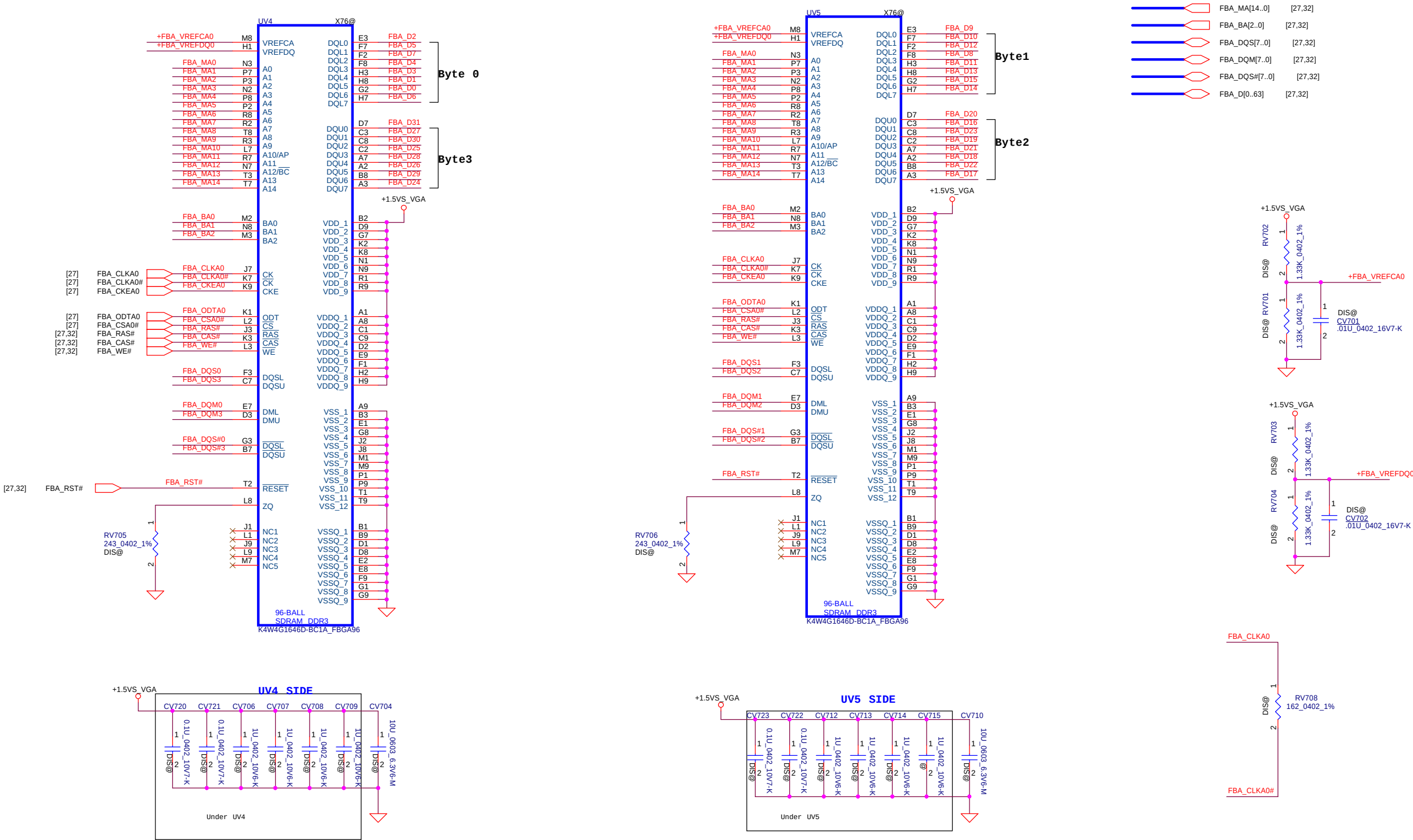


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				Document Number KENOBI	Rev 2.0
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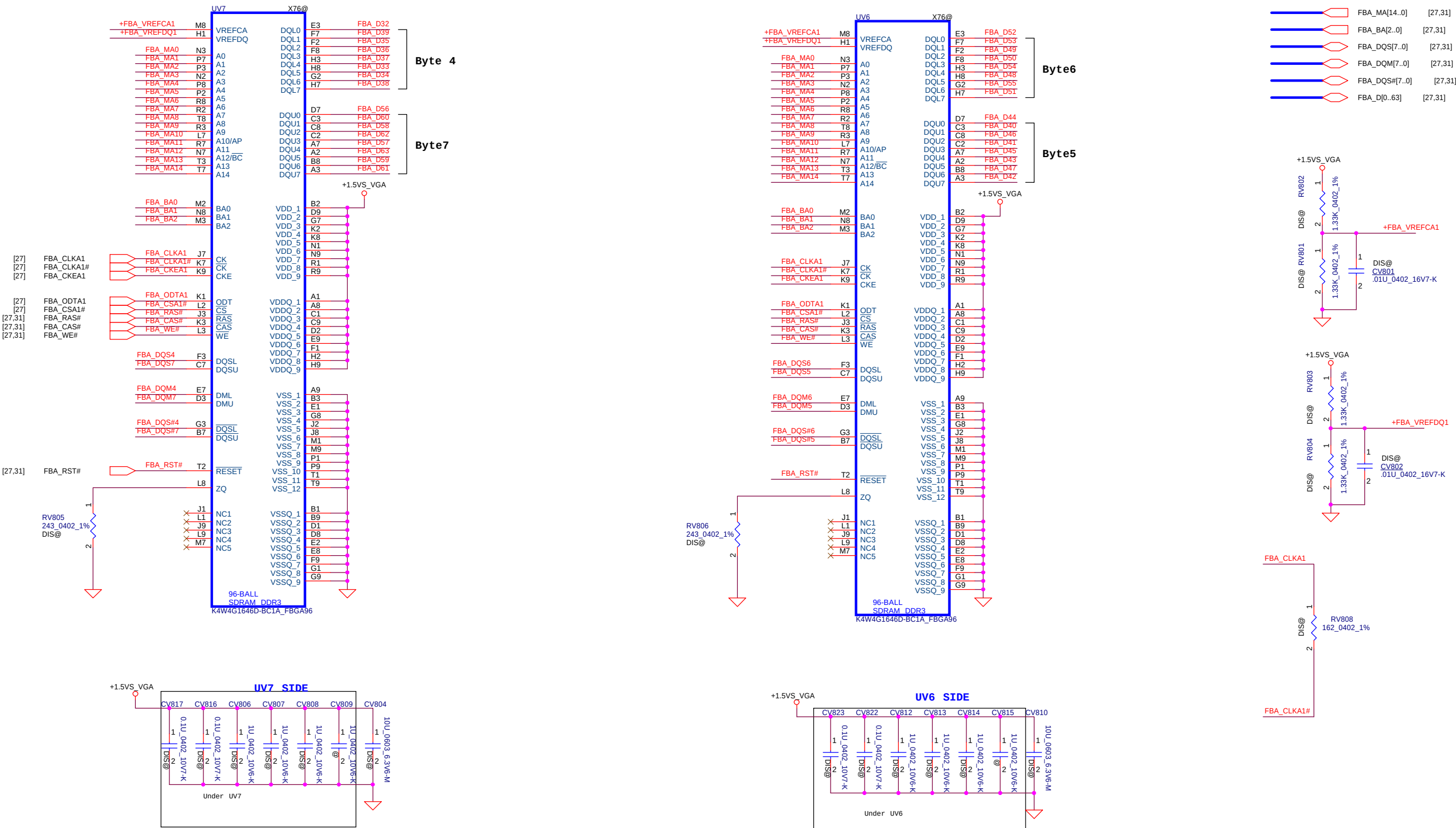




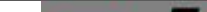
Memory Partition A - Lower 32 bits



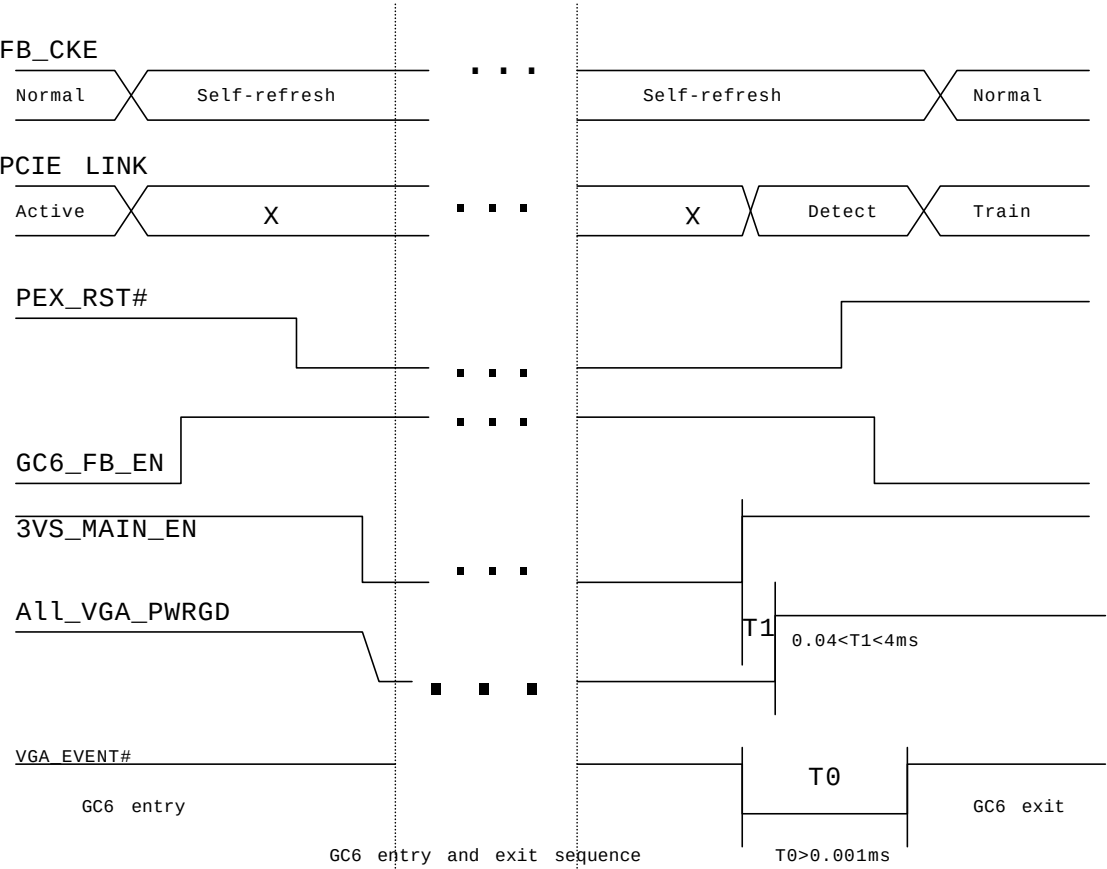
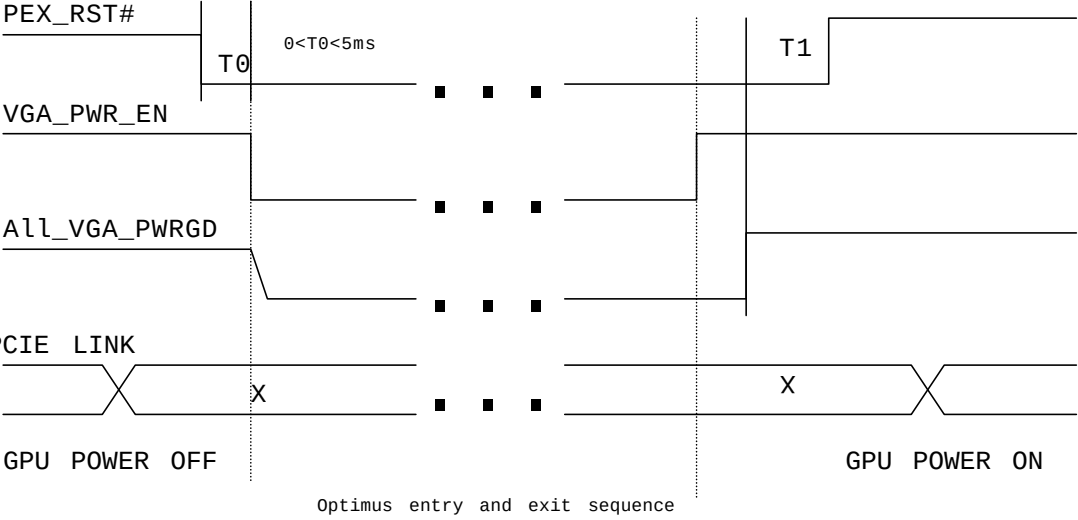
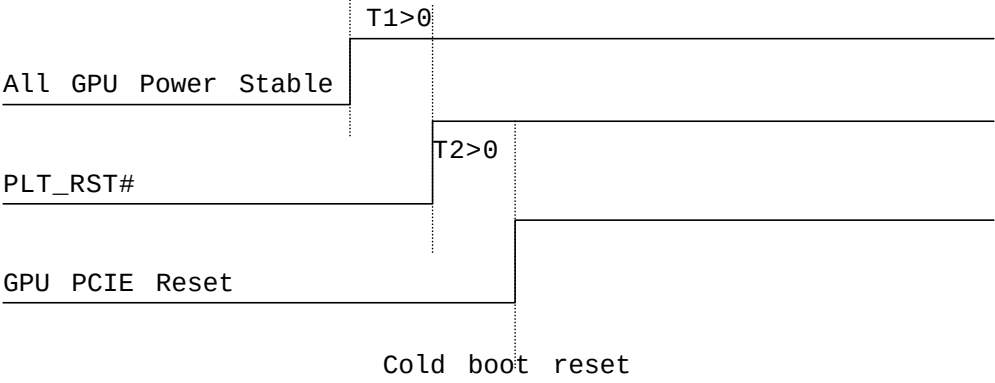
Memory Partition A - Upper 32 bits



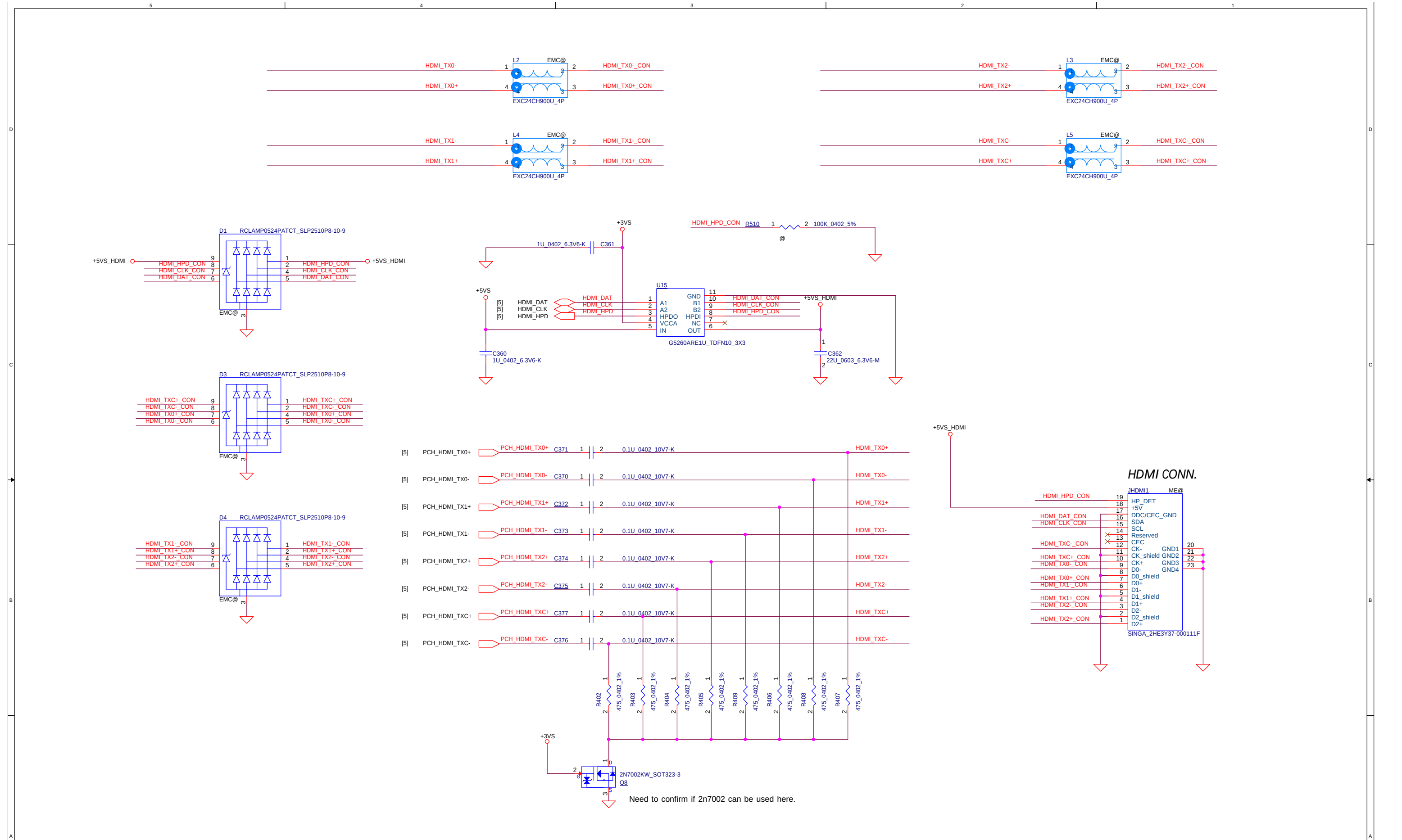
[illegible]

Security Classification		LC Future Center Secret Data		Title		
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				KENOBI		
				Date: Thursday, August 25, 2016		Sheet 33 of 82

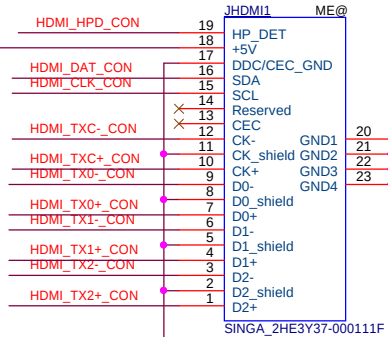
GPI0	I/O	Functional Description	I/O Termination
GPI00	0	FB Enable for GC6 2.0, Open source	10K pull-down
GPI01	0	Memory voltage control	Pull-up/pull down to set the FBVDD/Q boot voltage
GPI02	0	Panel Backlight PWM Brightness Control	100K pull down
GPI03	0	Panel Power Enable	100K pull down
GPI04	0	Panel Backlight Enable	100K pull down
GPI05	0	GPU Power Sequence for GC6 2.0, Open Drain	10k pull-up to 3V3_AON
GPI06	I	GPU wake signal for GC6 2.0	10k pull-up to 3V3_AON
GPI07	0	3D Vision L/R signal	100K pull down
GPI08	0	System side PCIe rest monitor	10k pull-up to 3V3_AON
GPI09	I/O	Active low thermal alert, open drain	10k pull-up to 3V3_AON
GPI010	0	Memory VREF Control	100K pull down
GPI011	0	GPU Core VDD PWM control signal	
GPI012	I	AC power detect or power supply overdraw input	100k pull-up to 3V3_AON
GPI013	0	Phase Shedding	10K pull-up to 3V3_AON to enable two phase
GPI014	I	Hot Plug Detect for IFPA used as DisplayPort for IFPAB when used as Dual Link DVI	
GPI015	I	Hot Plug Detect for IFPC	
GPI016	I	Active Low Frame Lock, Open Drain	10k pull-up to 3V3_AON
GPI017	I	Hot Plug Detect for IFPD	
GPI018	I	Hot Plug Detect for IFPE	
GPI019	I	Hot Plug Detect for IFPF or for IPFB when used as DisplayPort	
GPI020	0	Reserved	
GPI021	0	GPU PCIe self-reset control, Open Drain	10k pull-up to 3V3_AON
OVERT	I/O	Catastrophic Over Temperature	100k pull-up to 3V3_AON



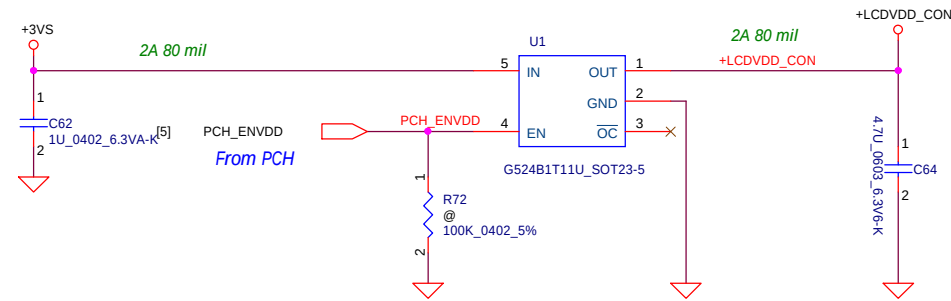
The central portion of the image is a large, empty white rectangle, which serves as the workspace for the engineering drawing.



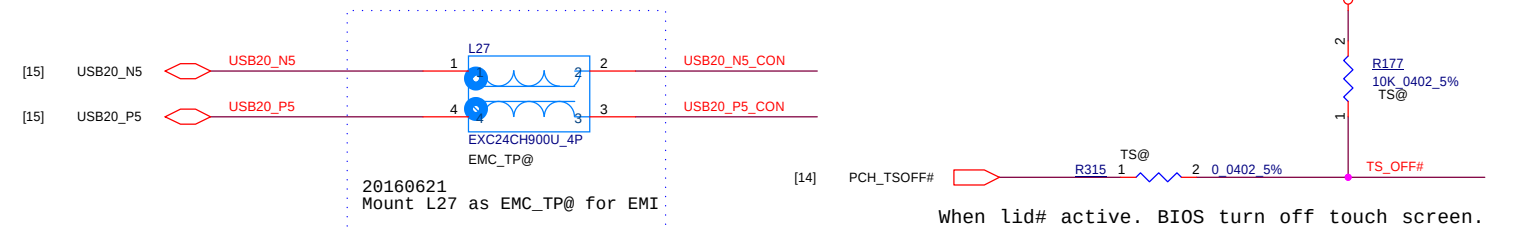
HDMI CONN.



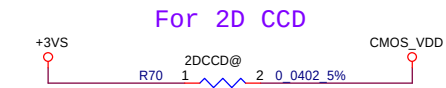
LCDVDD Circuit



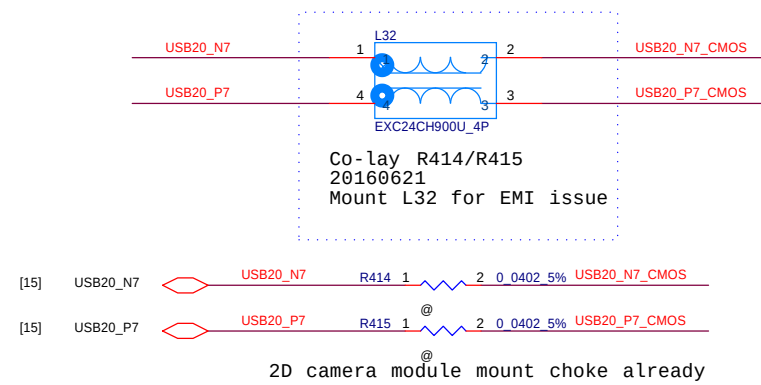
Touch Panel



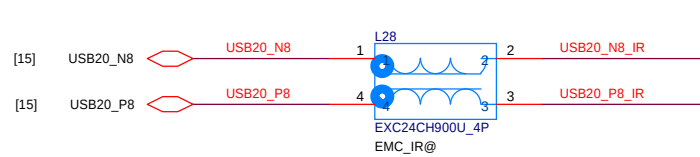
CMOS Camera



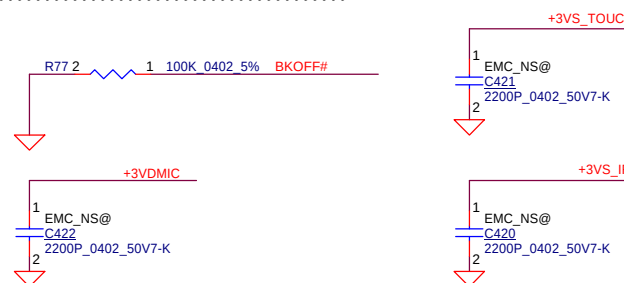
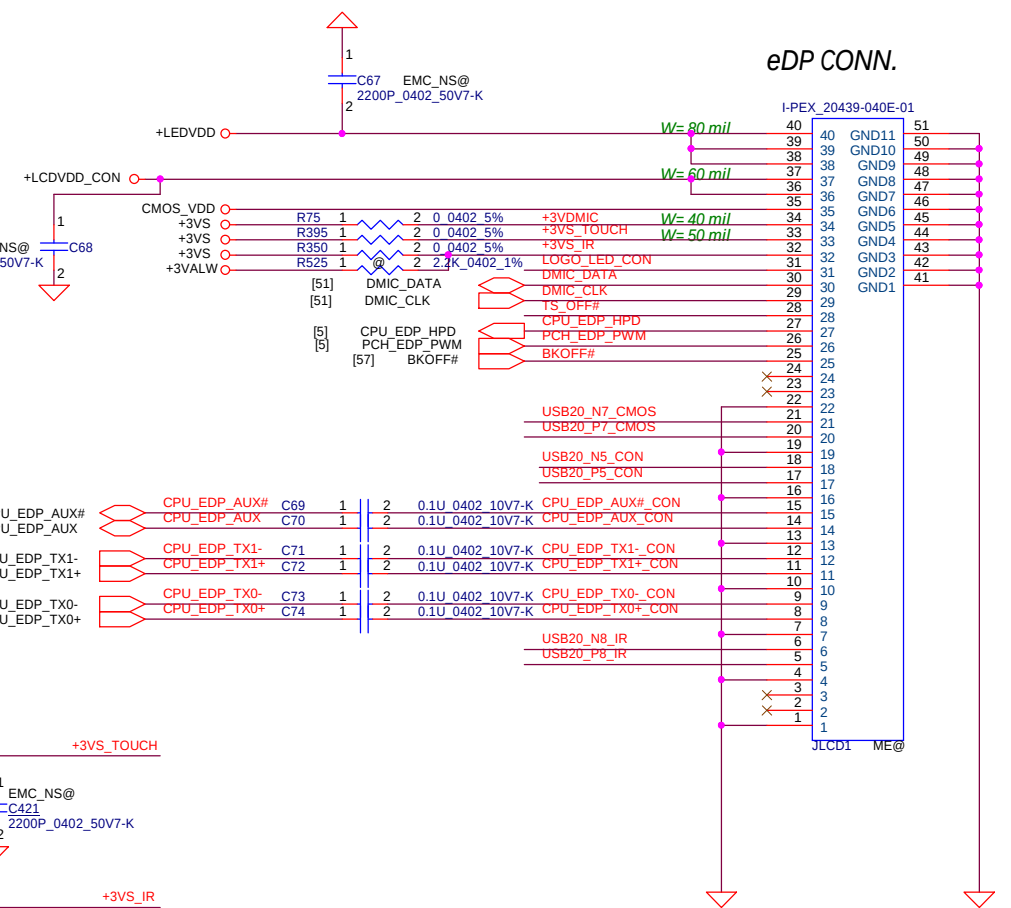
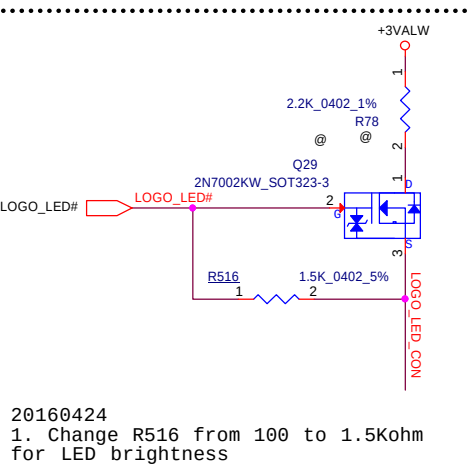
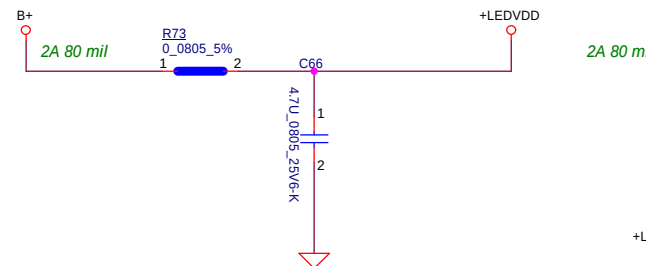
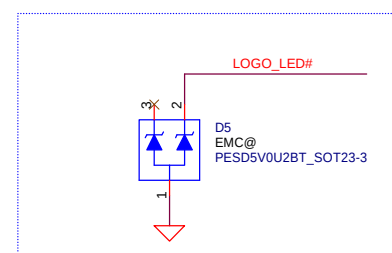
CMOS USB Port



IR camera USB Port



ESD request



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Date:		Thursday, August 25, 2016		Sheet		37 of 82					

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D				D																									
C				C																									
B				B																									
A				A																									
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<table><tr><td>Security Classification</td><td colspan="3">LC Future Center Secret Data</td><td>Title</td><td rowspan="2"></td></tr><tr><td>Issued Date</td><td>2015/10/5</td><td>Deciphered Date</td><td>2016/12/31</td><td>CRT CONN</td></tr><tr><td colspan="4">THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF LC FUTURE CENTER AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY LC FUTURE CENTER NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF LC FUTURE CENTER.</td><td>Size Custom</td><td>Document Number</td><td>Rev 2.0</td></tr><tr><td colspan="4"></td><td>Date: Thursday, August 25, 2016</td><td>Sheet 39 of 82</td><td></td></tr></table>					Security Classification	LC Future Center Secret Data			Title		Issued Date	2015/10/5	Deciphered Date	2016/12/31	CRT CONN	THIS SHEET OF ENGINEERING DRAWING IS THE PROPRIETARY PROPERTY OF LC FUTURE CENTER AND CONTAINS CONFIDENTIAL AND TRADE SECRET INFORMATION. THIS SHEET MAY NOT BE TRANSFERED FROM THE CUSTODY OF THE COMPETENT DIVISION OF R&D DEPARTMENT EXCEPT AS AUTHORIZED BY LC FUTURE CENTER NEITHER THIS SHEET NOR THE INFORMATION IT CONTAINS MAY BE USED BY OR DISCLOSED TO ANY THIRD PARTY WITHOUT PRIOR WRITTEN CONSENT OF LC FUTURE CENTER.				Size Custom	Document Number	Rev 2.0					Date: Thursday, August 25, 2016	Sheet 39 of 82	
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Issued Date	2015/10/5	Deciphered Date	2016/12/31	CRT CONN																									
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				Date: Thursday, August 25, 2016	Sheet 39 of 82																								
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				Date:	Thursday, August 25, 2016	Sheet 40 of 82

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Security Classification	LC Future Center Secret Data			Title		
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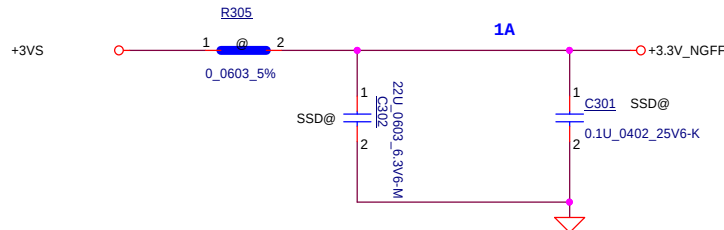
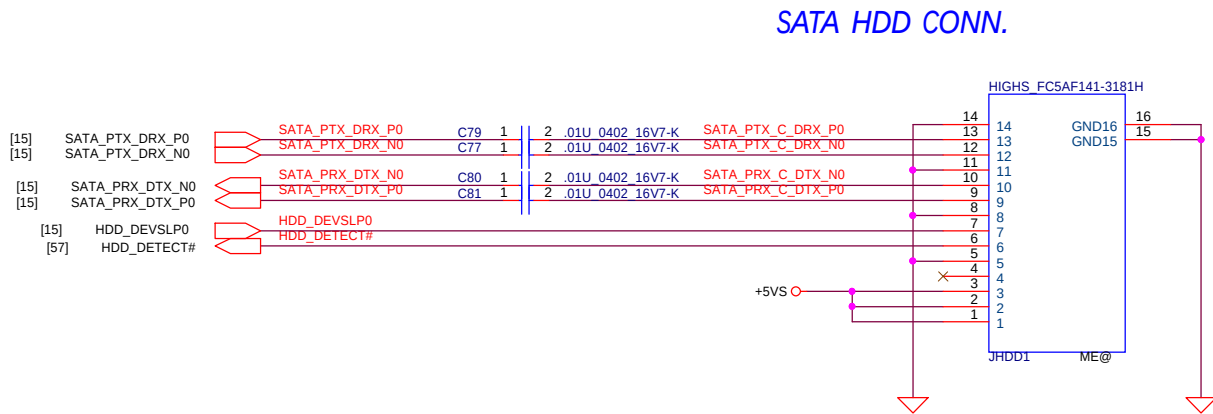
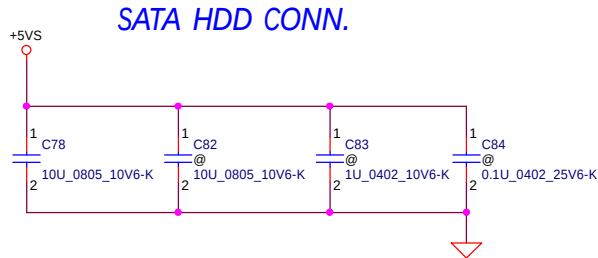
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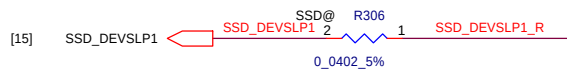
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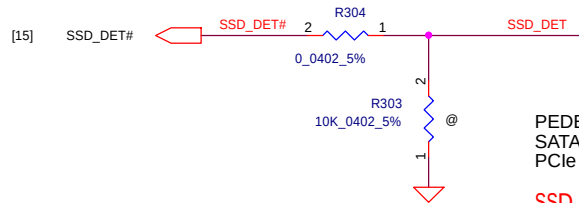
H



M.2 SSD(SATA/PCIE)

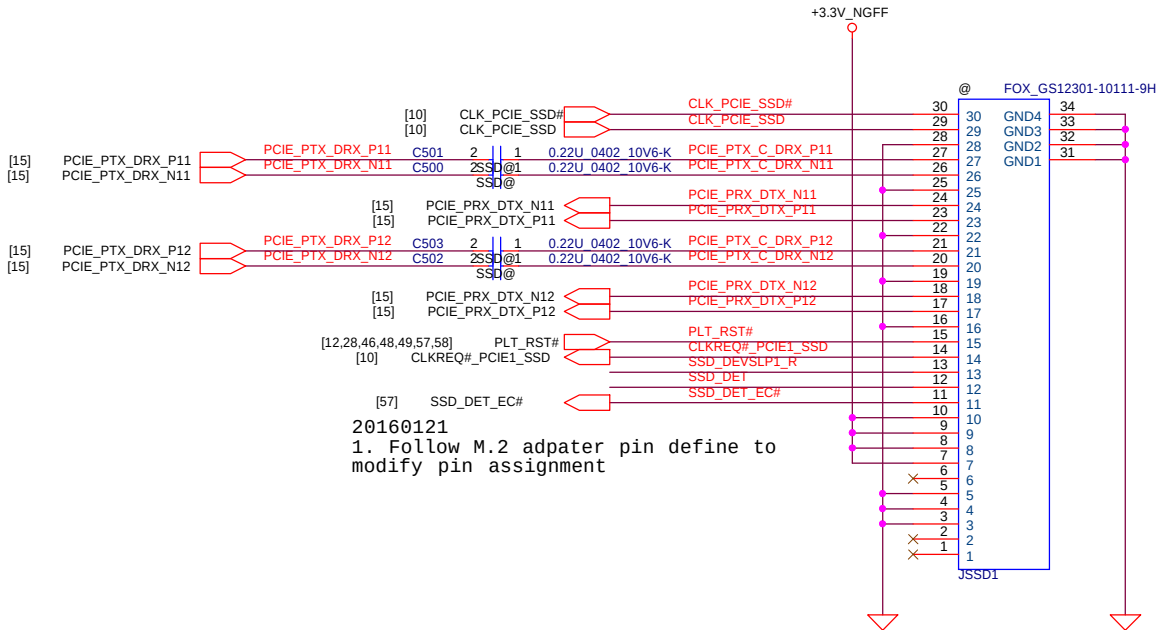


20160308
1. Remove R300,R301,R302 and put it to CPU side



PEDET (PE_DTCT)
SATA Device GND
PCIe Device Open

SSD_DET#
0 - SATA
1 - PCIE



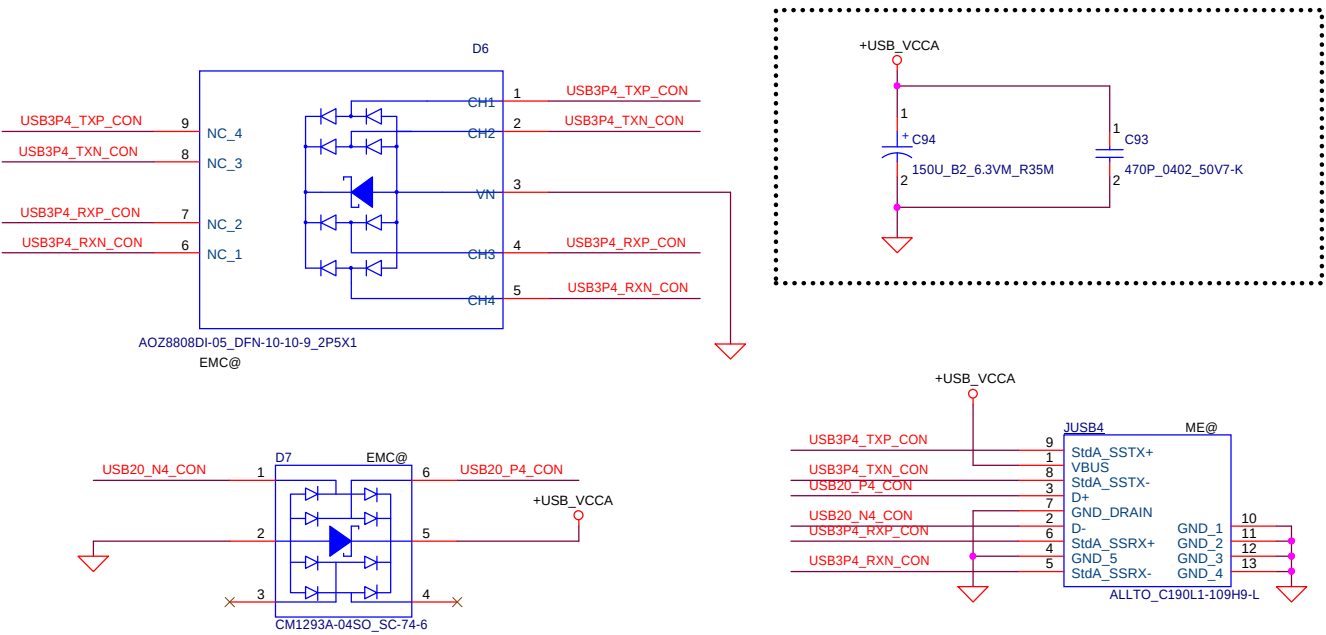
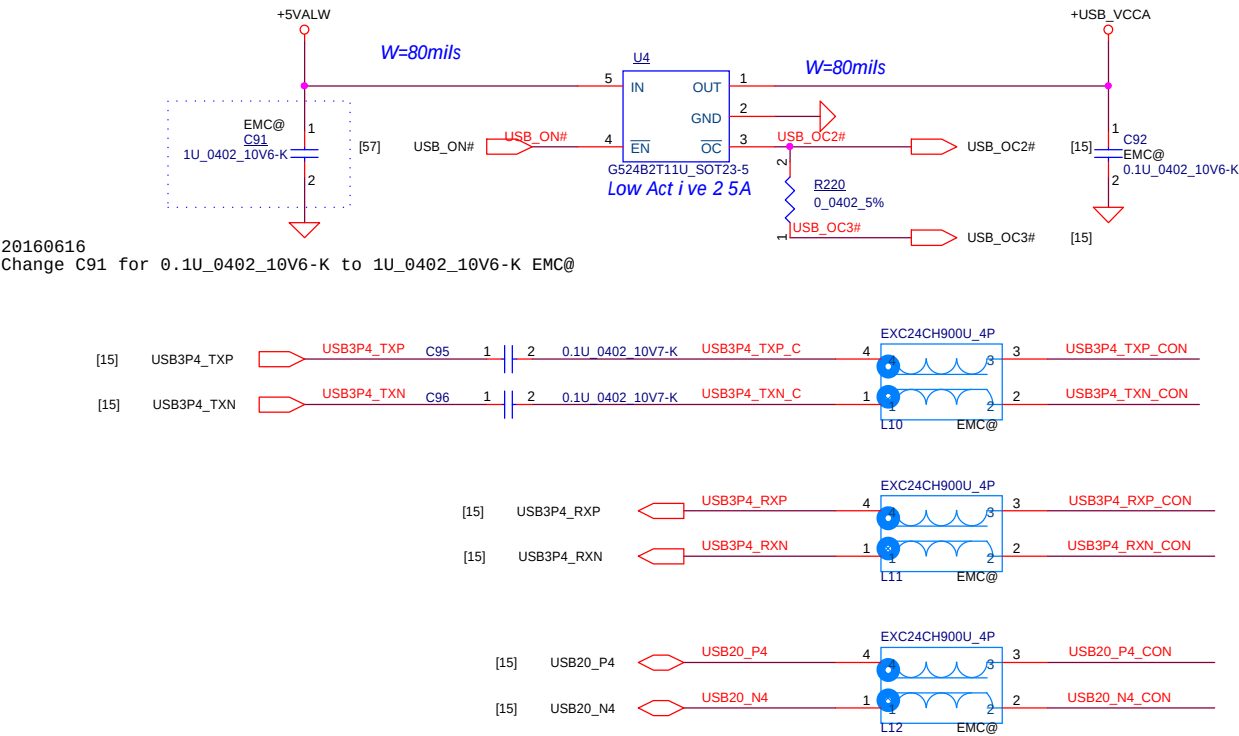
20160121
1. Follow M.2 adapter pin define to modify pin assignment

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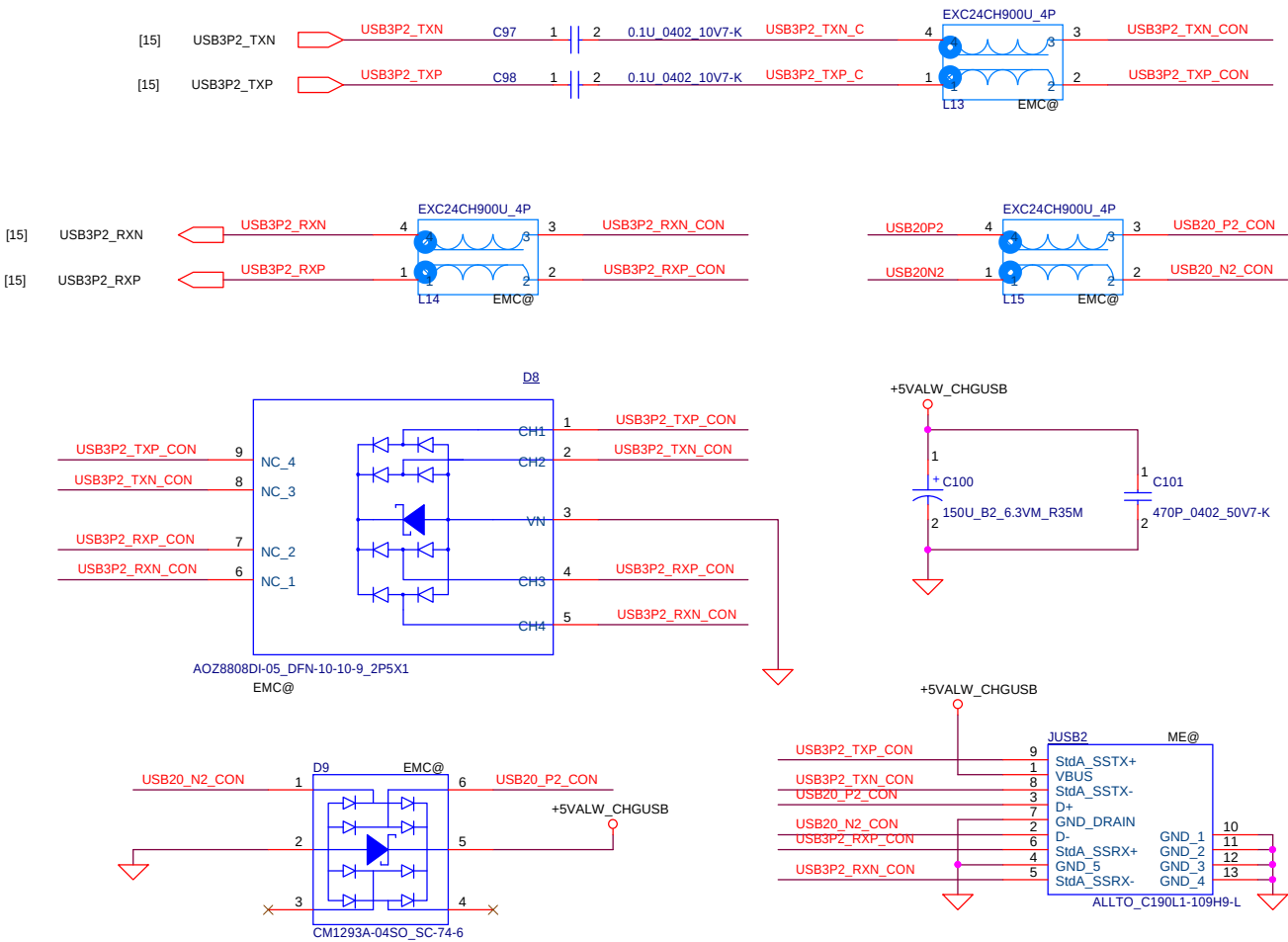
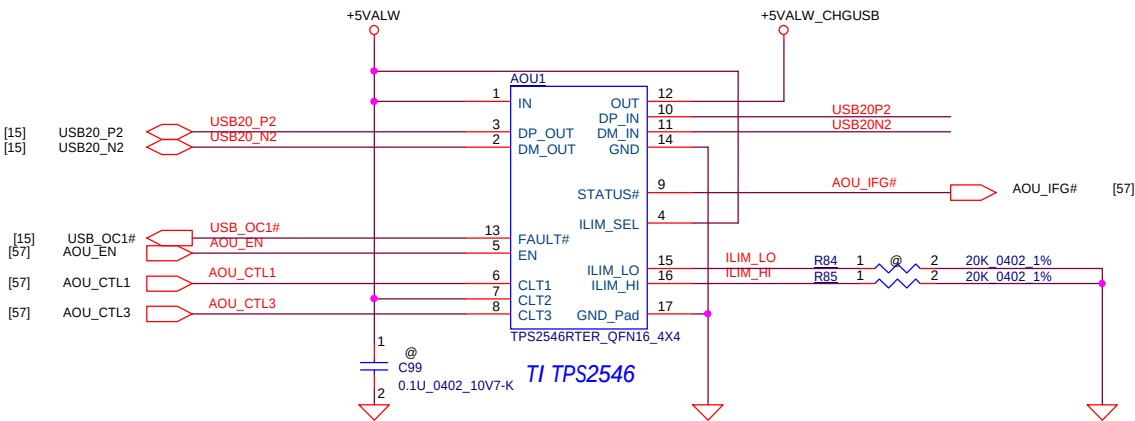
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Issued Date	2015/10/5	Deciphered Date	2016/12/31	ODD		
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USB3 PORT4

POWER SWITCH

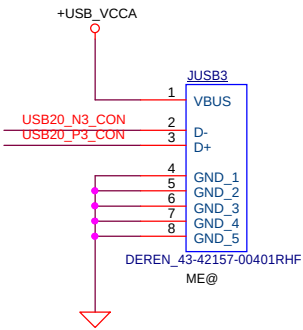
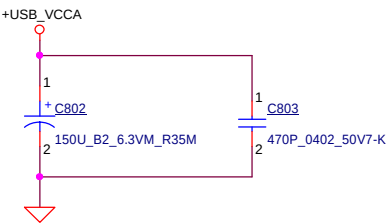
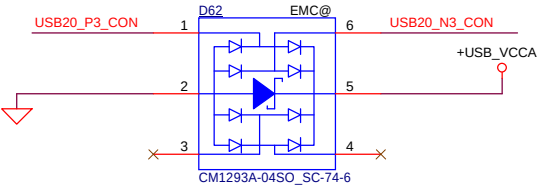
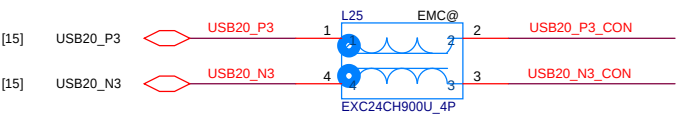


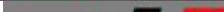
PORT2 (AOU)

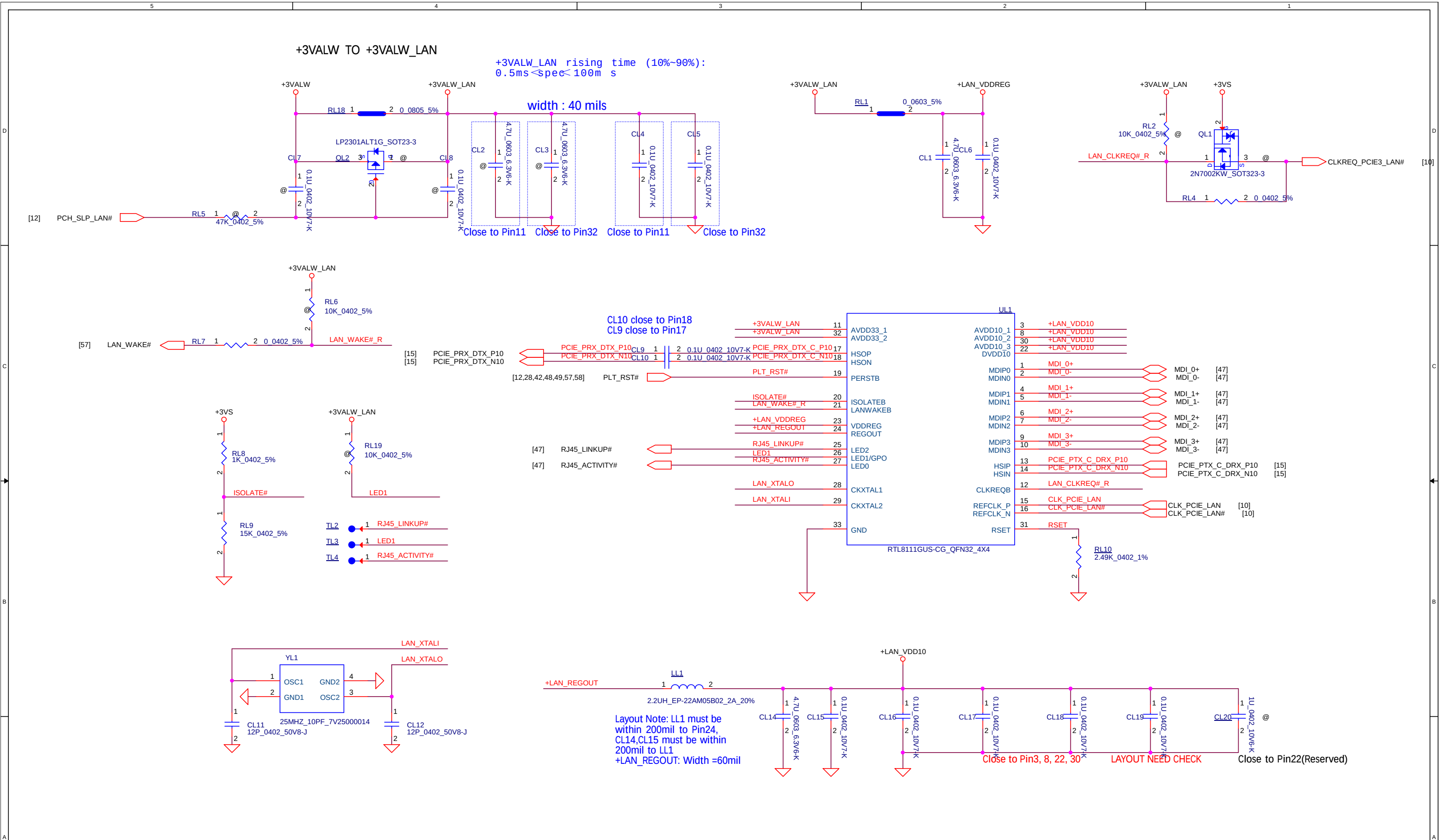


CLT1	CLT2	CLT3	ILIM_SEL	MOD
0	0	0	X	DCH OUT held low
1	1	1	1	CDP Data Connected and Port Power Mgt. Function Active
1	1	1	0	SDP2 Data Connected
1	1	0	X	SDP1 Data Connected
0	1	0	X	SDP1 Data Connected
1	0	0	X	DCP_Short Device Forced to stay in DCP BC 1.2 charging mode
1	0	1	X	DCP_Divider Device Forced to stay in DCP Divider 1 Charging Mode
0	1	1	X	DCP_Auto Data Disconnected and Port Power Mgt. Function Active
0	0	1	X	DCP_Auto Data Disconnected and Power Wake Function Active

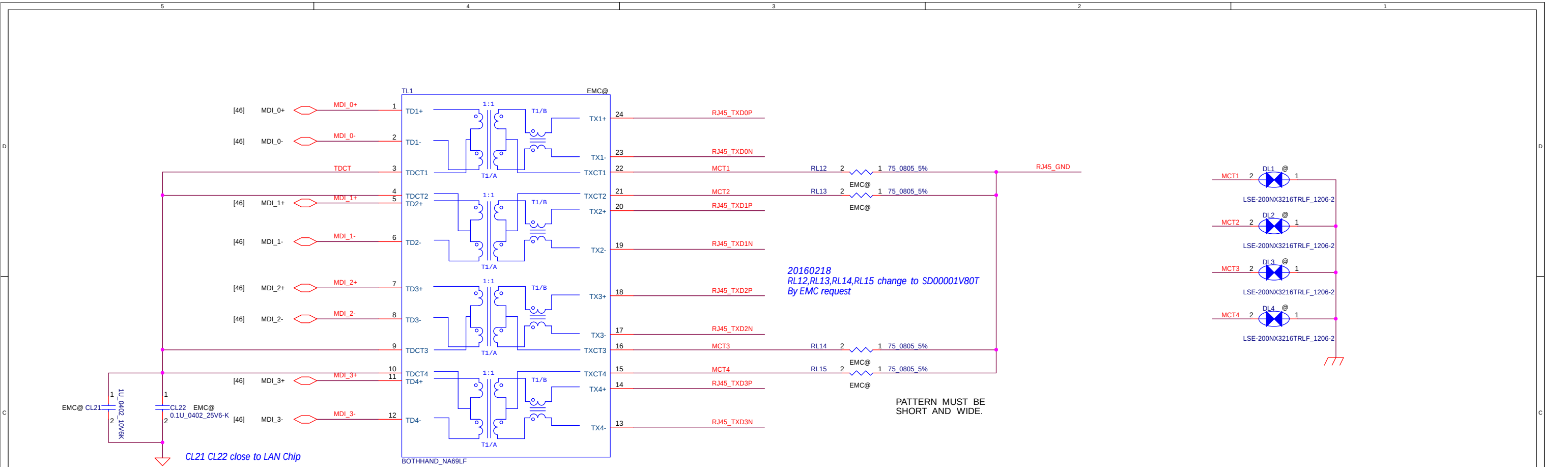
USB3 PORT3



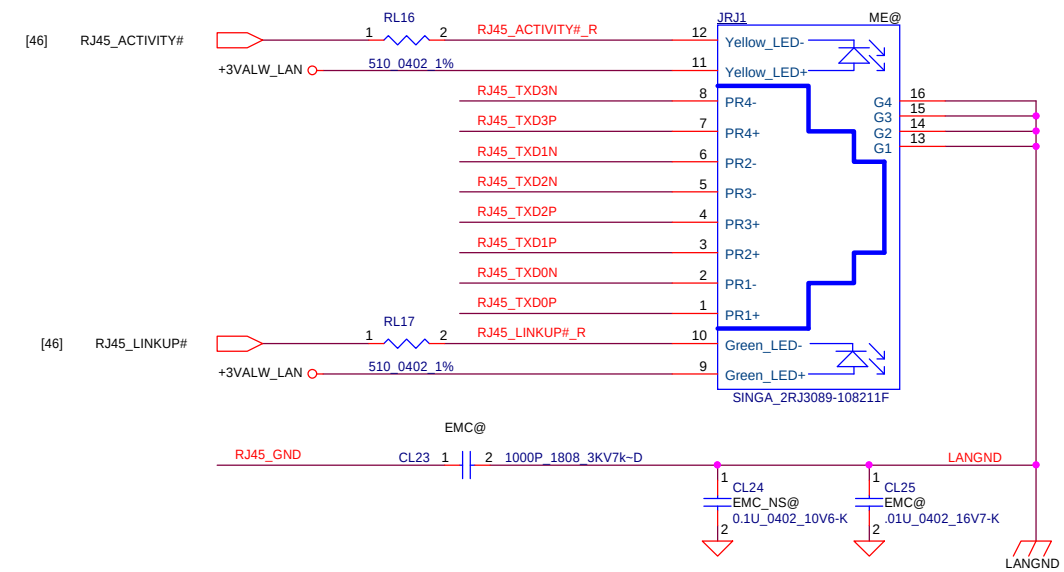
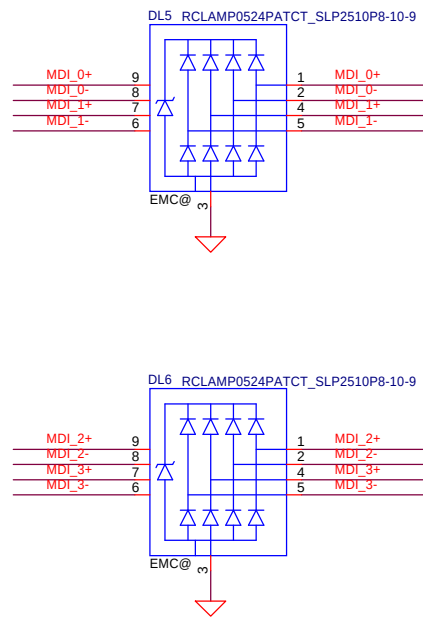
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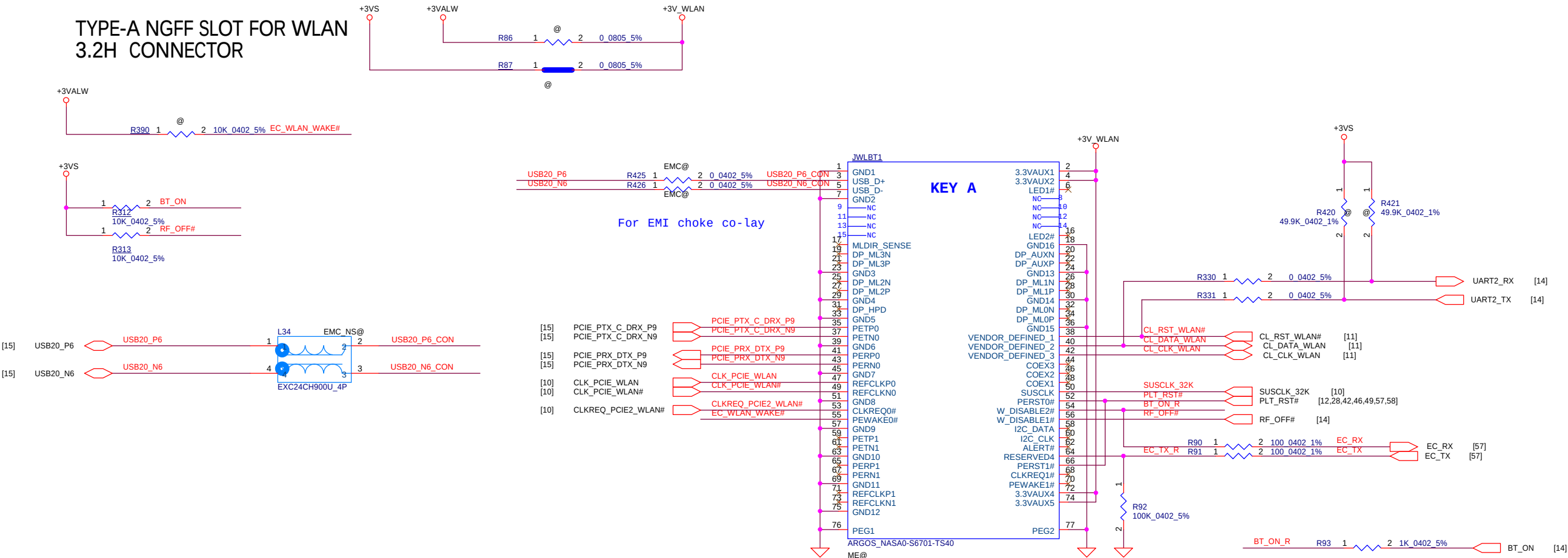
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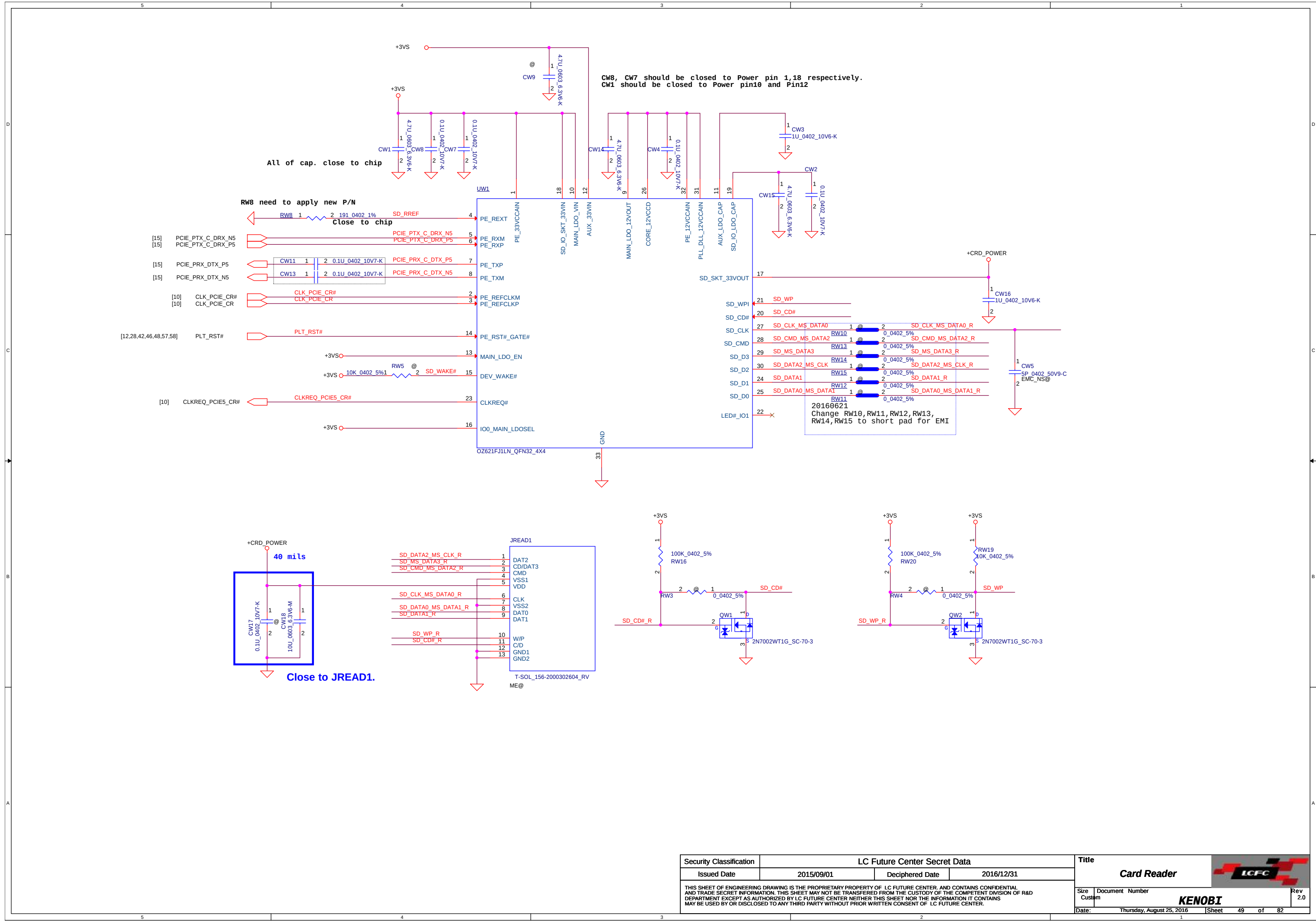


RJ-45 Conn.

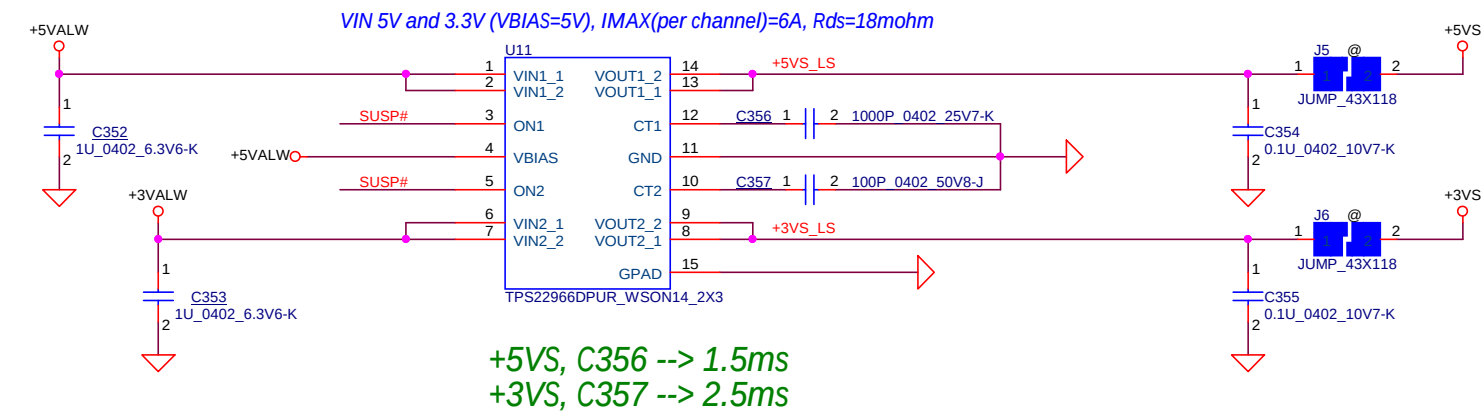


TYPE-A NGFF SLOT FOR WLAN
3.2H CONNECTOR

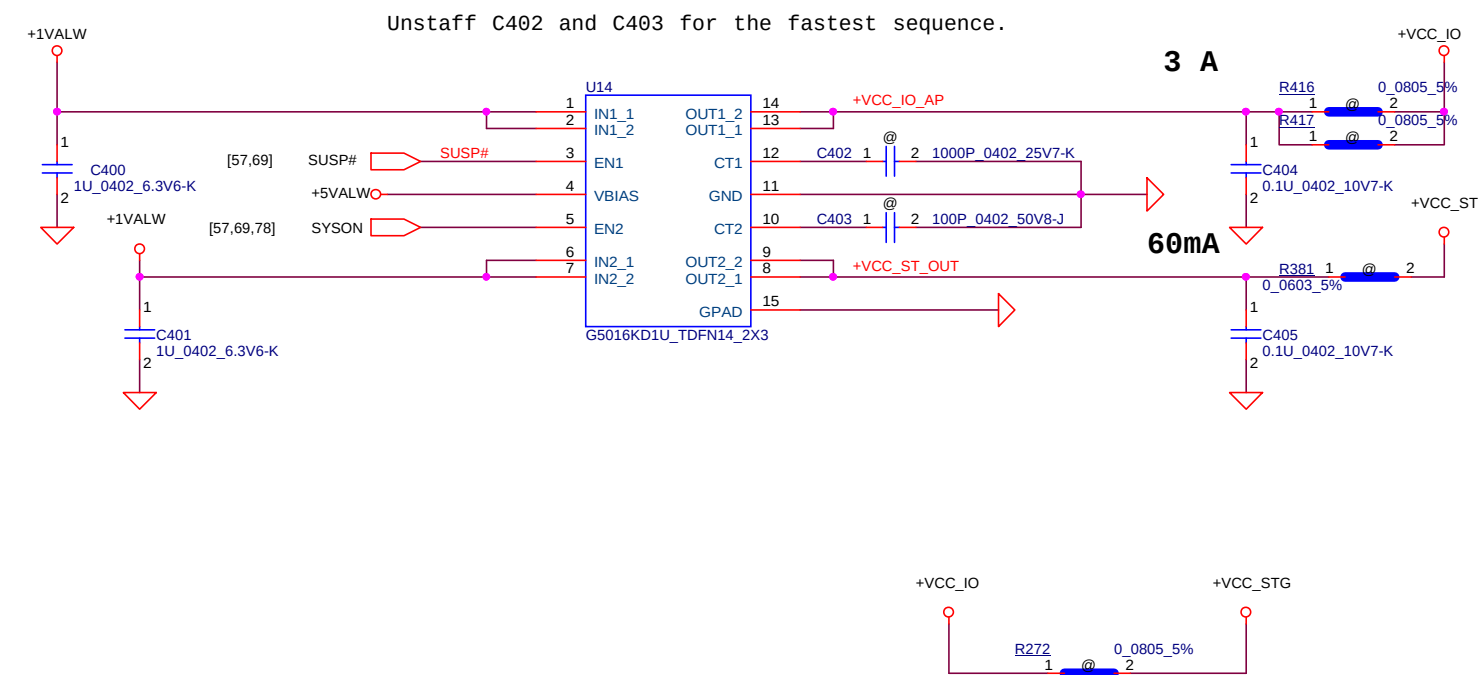




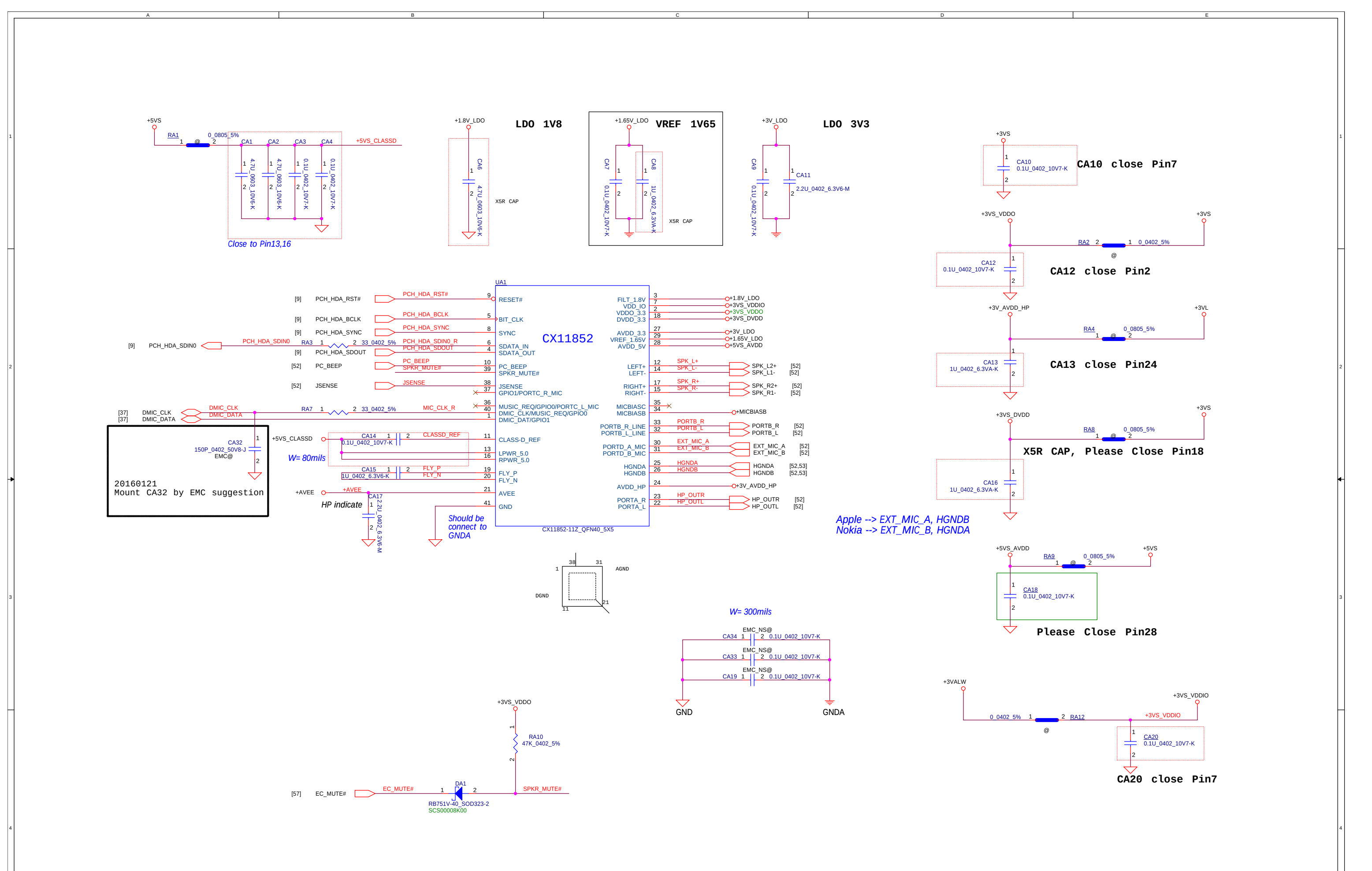
Load Switch
+5VALW To +5VS
+3VALW To +3VS



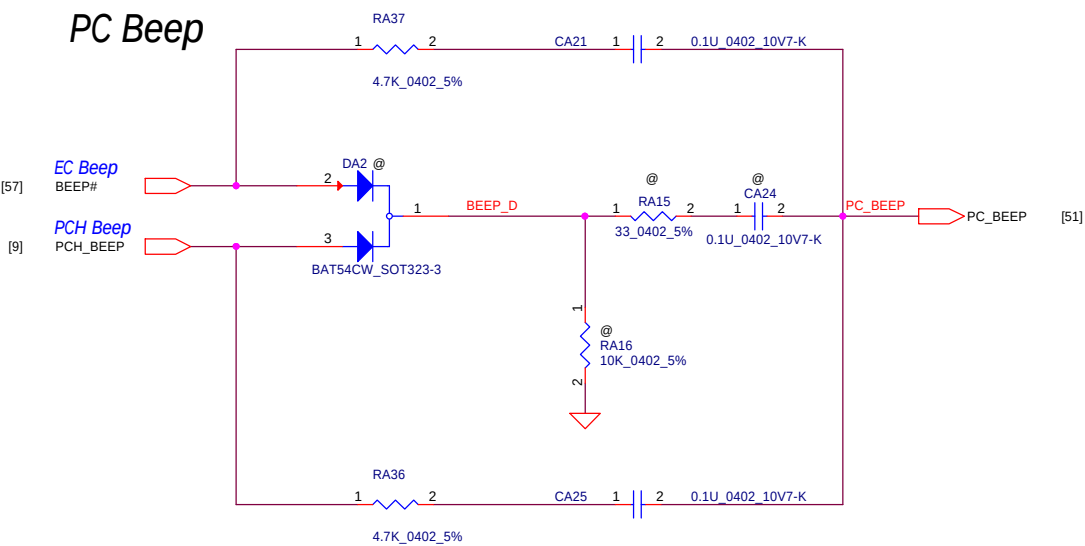
+1VALW to +VCC_IO_AP & +VCC_ST



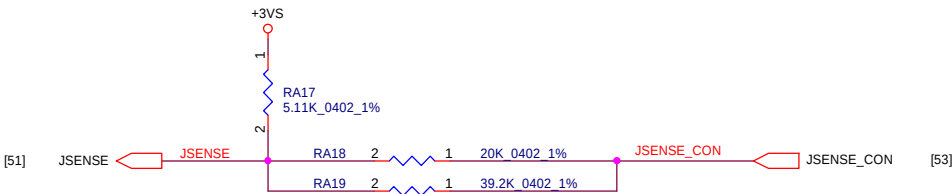
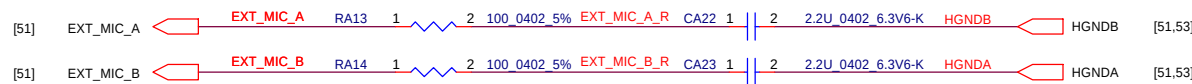
Slew Rate=10uS<TR<65us



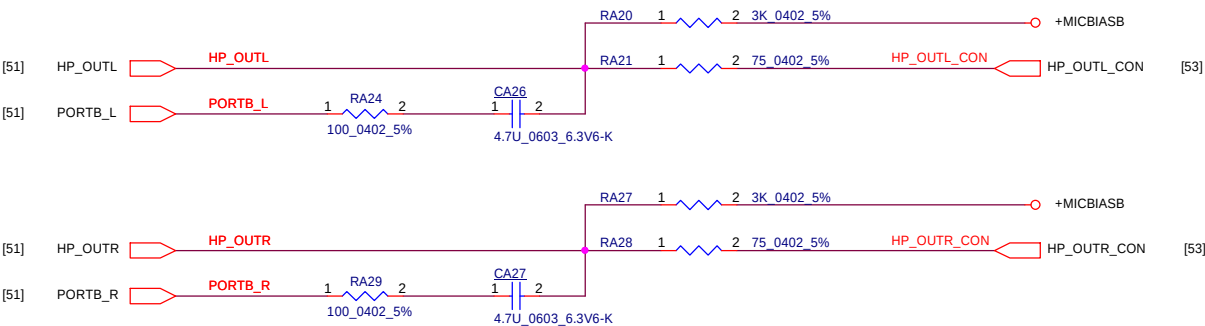
PC Beep



EXT. MIC/LINE IN Apple --> EXT_MIC_A, HGND B
Nokia --> EXT_MIC_B, HGND A



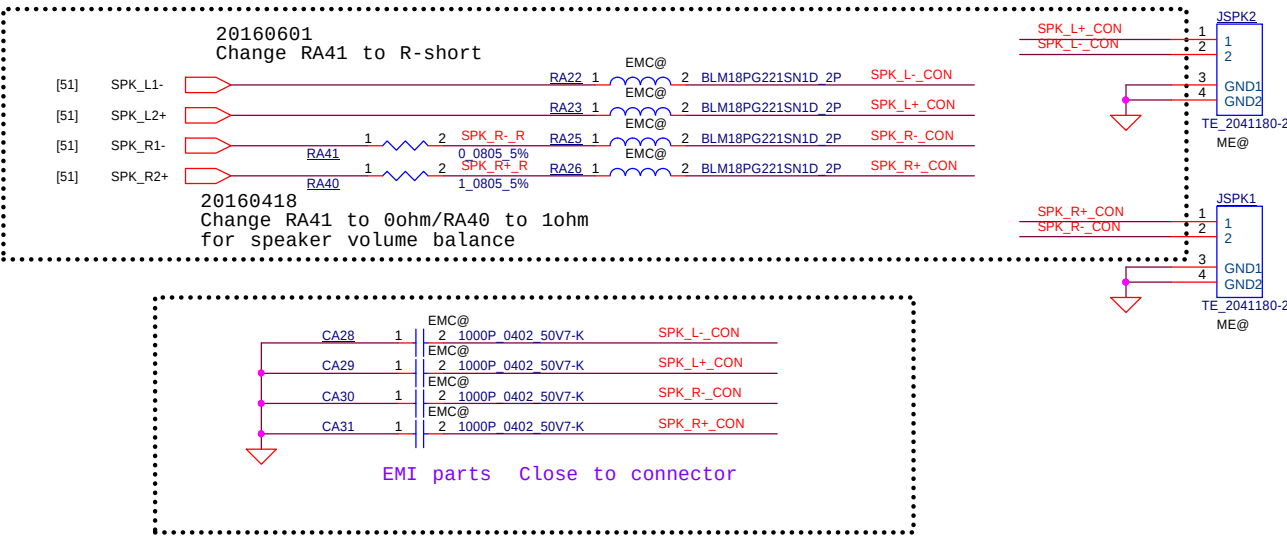
HeadPhone/LINE OUT

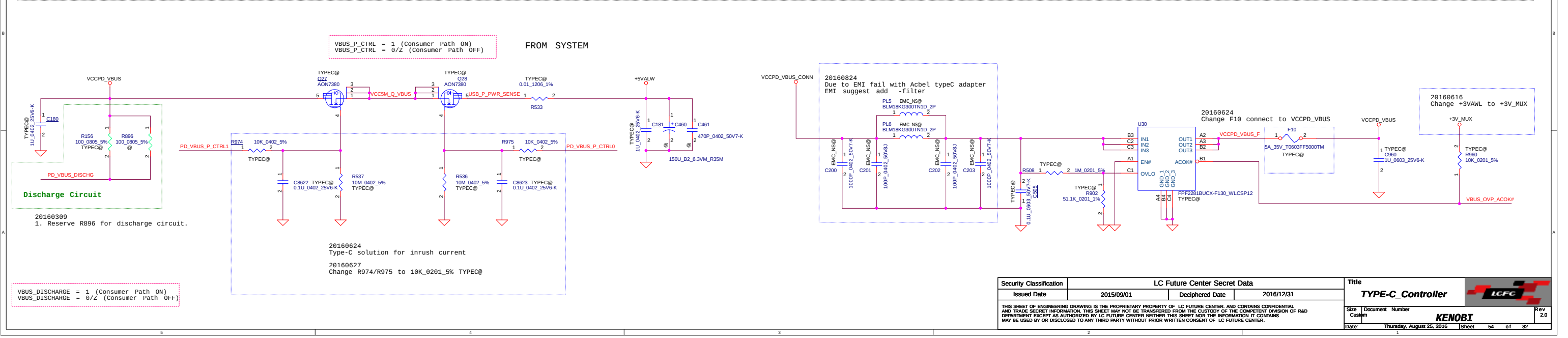
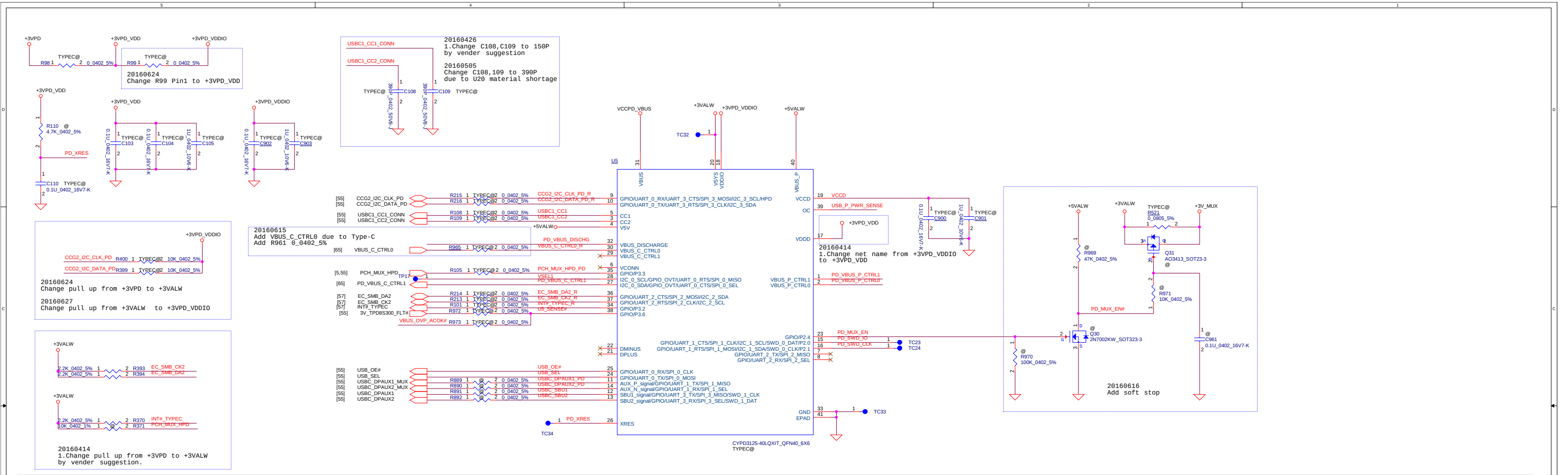


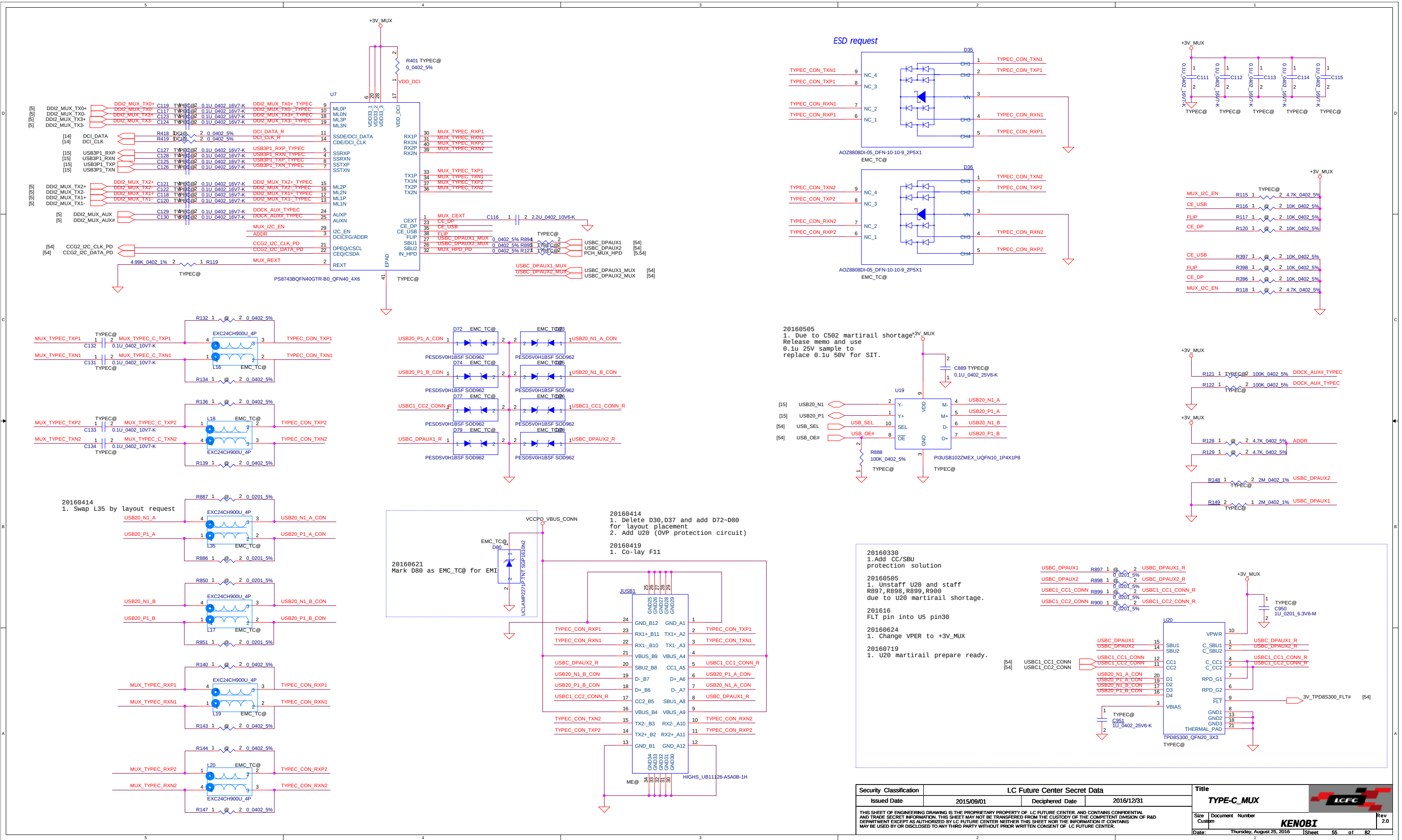
Speaker OUT

Need Lenght Match

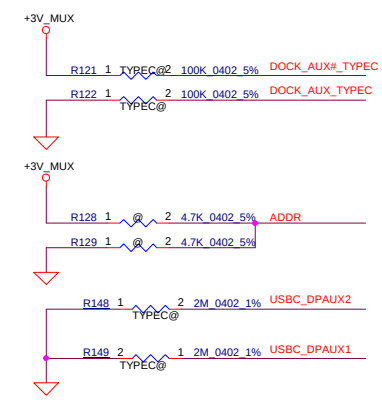
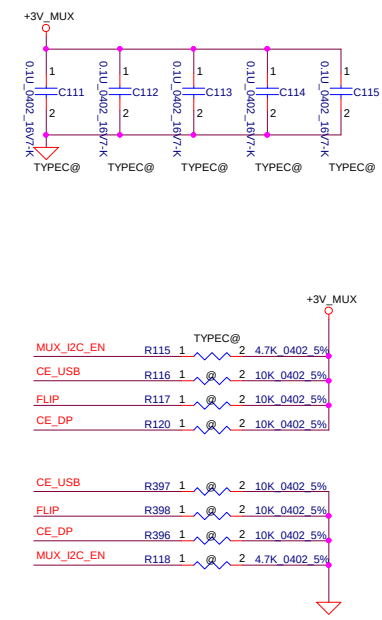
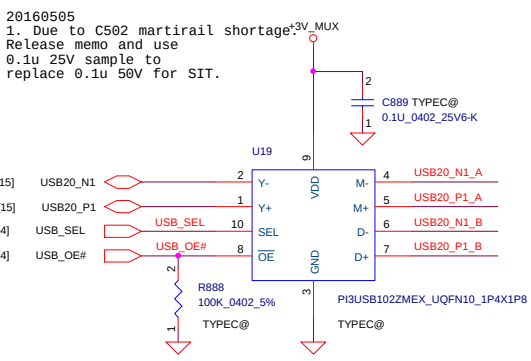
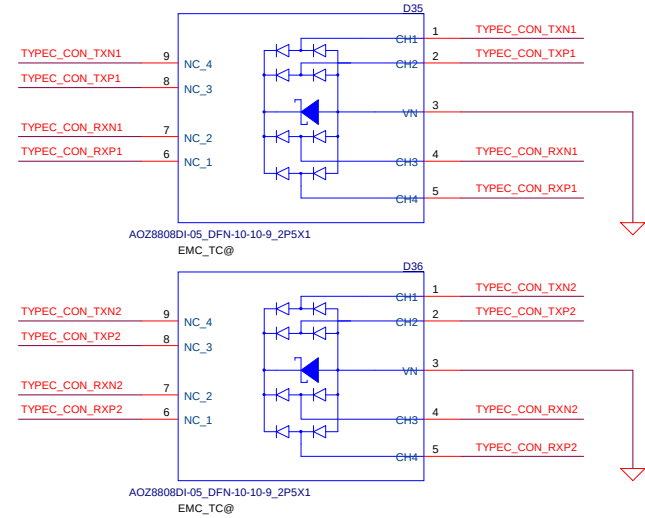
SPK CONN.





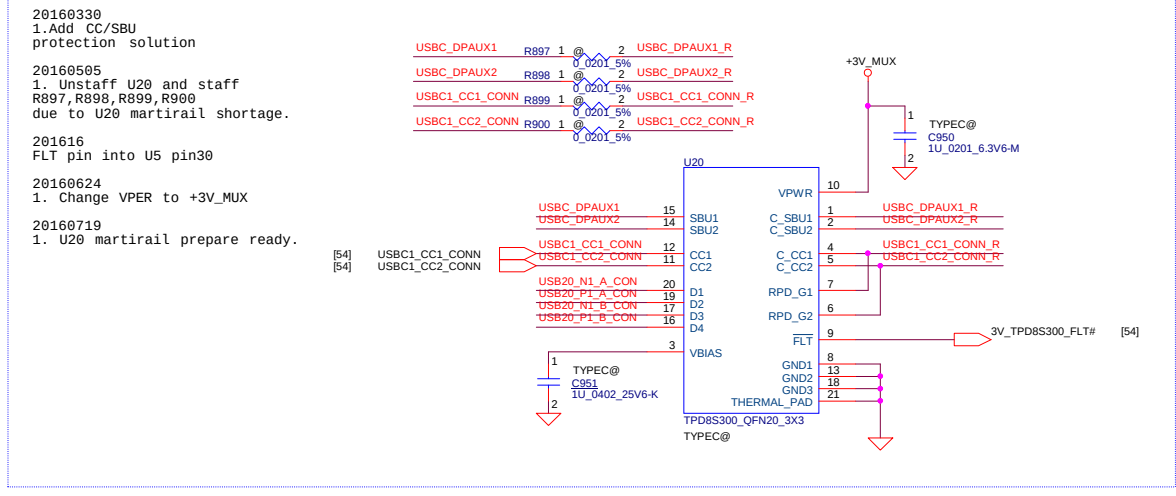
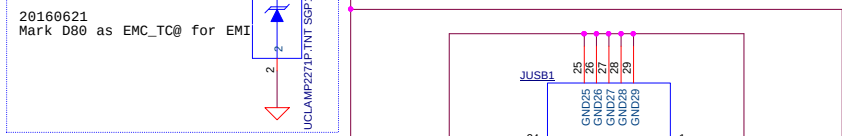


ESD request



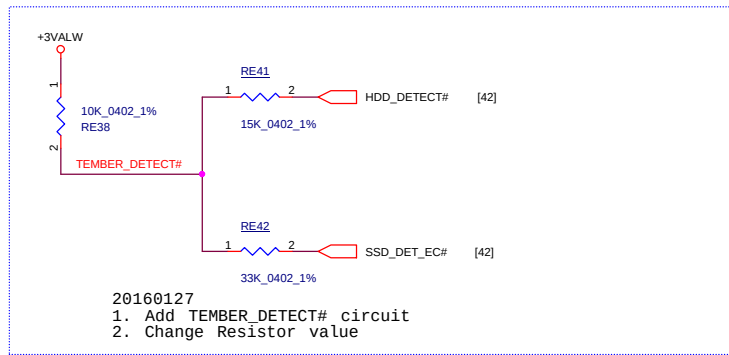
20160414
1. Swap L35 by layout request

20160414
1. Delete D30, D37 and add D72-D80 for layout placement
2. Add U20 (OVP protection circuit)

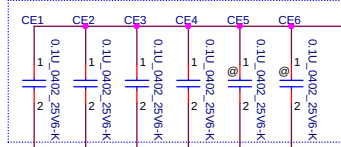


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[illegible]



All capacitors close to EC



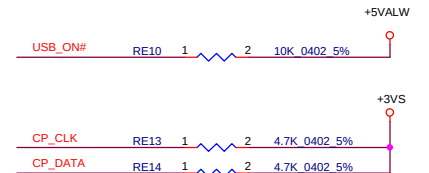
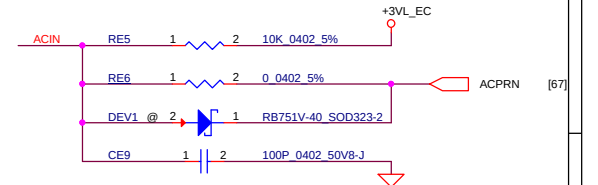
Close to EC



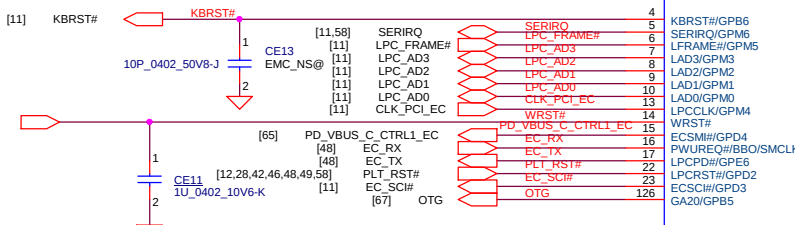
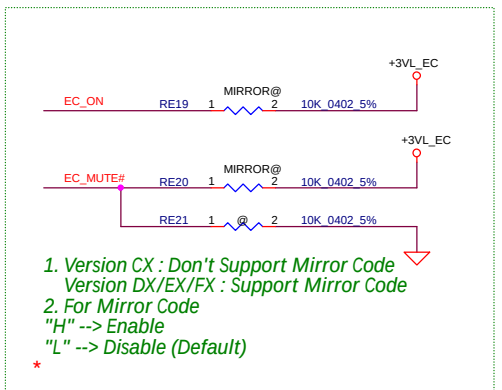
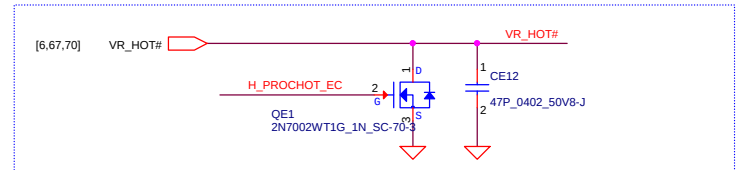
minimum trace width 12 mil

Vcc		3.3V +/- 5%			
RE1		100K +/- 1%			
Board ID	RE2	V _{AD_BID} min	V _{AD_BID} typ	V _{AD_BID} max	Phase
0	0K +/- 5%	0 V	0 V	0 V	SDV
1	8.2K +/- 5%	0.216 V	0.250 V	0.289 V	FVT
2	18K +/- 5%	0.436 V	0.503 V	0.538 V	SIT
3	33K +/- 5%	0.712 V	0.819 V	0.875 V	SVT
4	4.7K +/- 5%	0.141 V	0.148 V	0.155 V	
5	24K +/- 5%	0.612 V	0.638 V	0.664 V	

20160419
Change RE2 to 18K
for SIT board ID



Un-stuff if not necessary.



IT8586E/AX
LQFP-128L

EXTERNAL SERIAL FLASH

SPI Flash ROM

UART

SM Bus

WAKE UP

GPIO

Clock

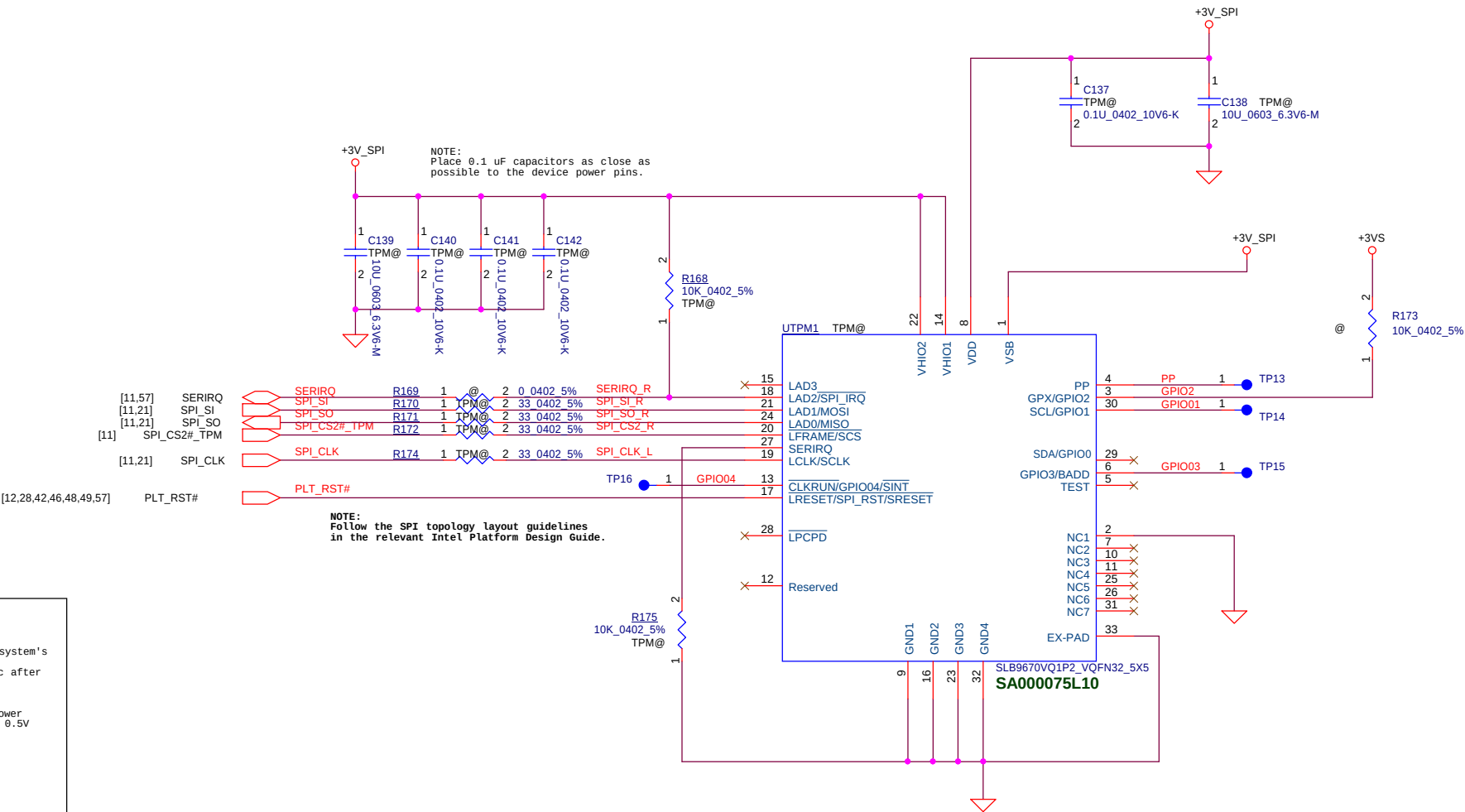
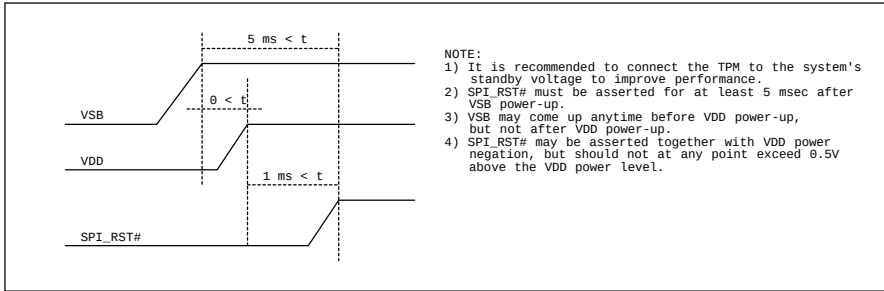
Please don't place any PU Resistor on GPG[7:2]
(Reserve hardware strapping)

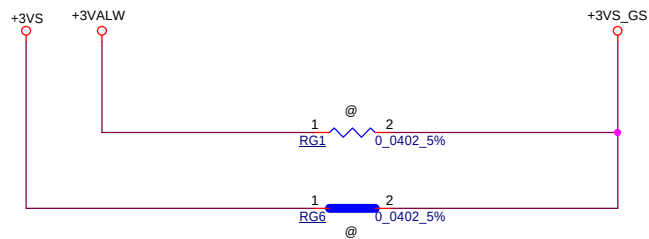
TPM IC

TABLE				
Pin No	TCG PTP Spec (v36)	Infineon SLB967VQ1 2 FW 6.10	ST Micro ST30HTPM2E32AAB9	Navteon NFCT653LB0YX
1	VDD	VDD	NC	VSB
2	GND	GND	GND	NC
3	GPIO	NC	NC	GPX/GPIO2
4	GPIO	NC	PP	PP
5	NC	NC	NC	TEST
6	VNC/GPIO	GPIO	NC	GPIO3
7	GPIO/VDD	PP	GPIO	NC
8	VDD	VDD	NC	VDD
9	GND	GND	NC	GND
10	VNC	NC	NC	NC
11	NC	NC	NC	NC
12	NC	NC	NC	Reserved
13	VNC/GPIO	NC	NC	GPIO4
14	VDD	NC	NC	VDD
15	NC	NC	NC	DNC
16	GND	NC	NC	GND
17	SPI_RST#	RST#	SPI_RST#	SPI_RST#
18	SPI_IRQ#	IRQ#	SPI_IRQ#	SPI_IRQ#
19	SPI_CLK	SCLK	SPI_CLK	SCLK
20	SPI_CS#	CS#	SPI_CS#	CS#
21	MOSI	MOSI	MOSI	MOSI
22	VDD	VDD	VPS	VDD
23	GND	GND	NC	GND
24	MISO	MISO	MISO	MISO
25	NC	NC	NC	NC
26	NC	NC	NC	NC
27	NC	NC	NC	(SERIRQ)
28	NC	NC	NC	DNC
29	VNC/GPIO	NC	NC	GPIO0
30	VNC/GPIO	NC	NC	GPIO1
31	VNC	NC	NC	NC
32	GND	GND	NC	GND

Follow THP1_SWG_SIT_EC005, update TPM table

NOTE:
Check timing sequence in SDV phase.





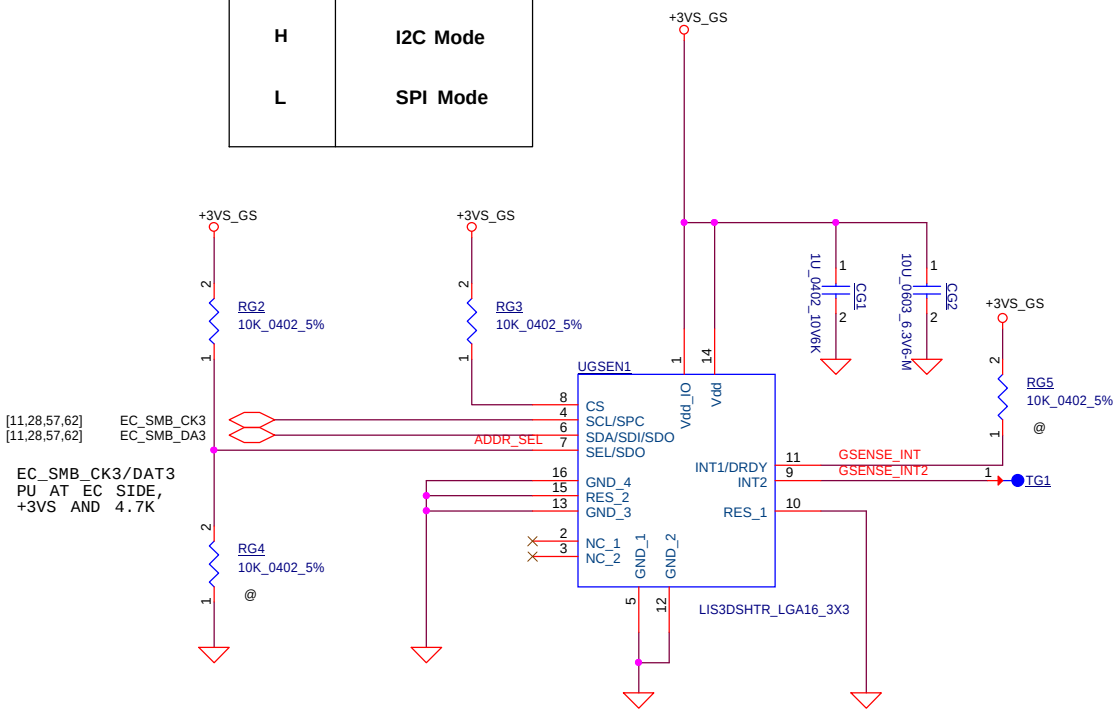
APS G-Sensor

TABLE

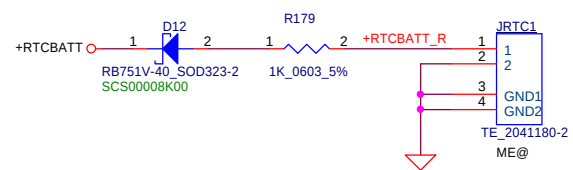
P/N	ADDR_SEL	Address
LIS3DSHTR	H	32h (W) & 33h (R)
	L	30h (W) & 31h (R)
KX023-1025	H	3Eh (W) & 3Fh (R)
	L	3Ch (W) & 3Dh (R)

TABLE

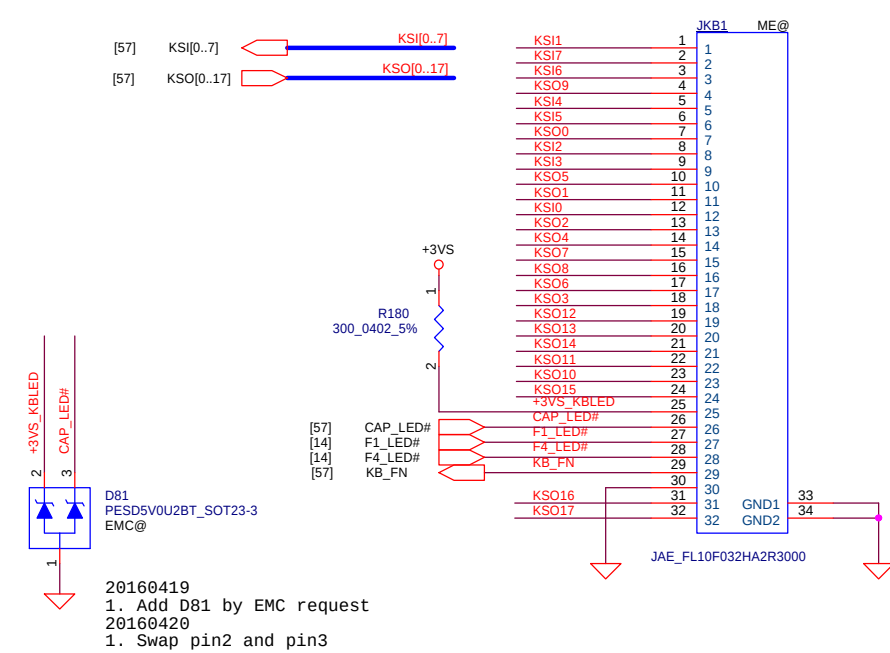
P/N	Mode Selection
H	I2C Mode
L	SPI Mode



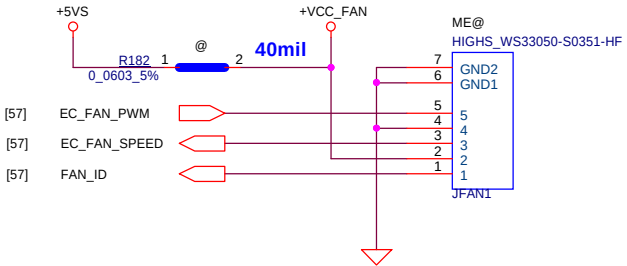
RTC CONN.



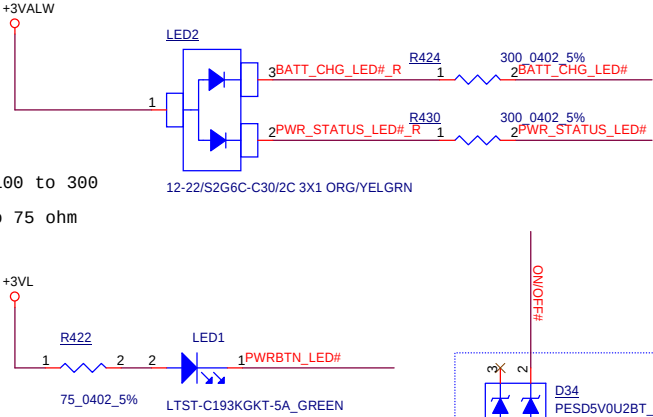
KB CONN



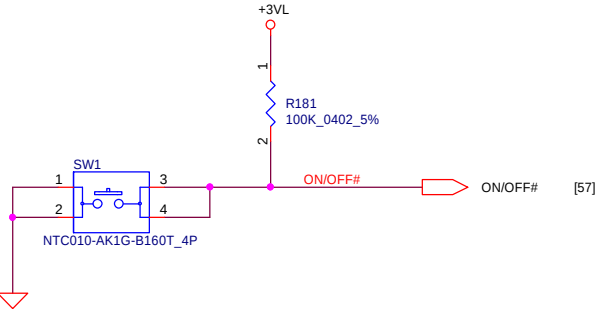
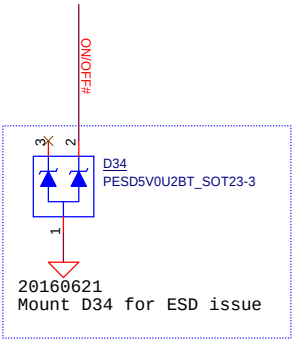
FAN CONN.



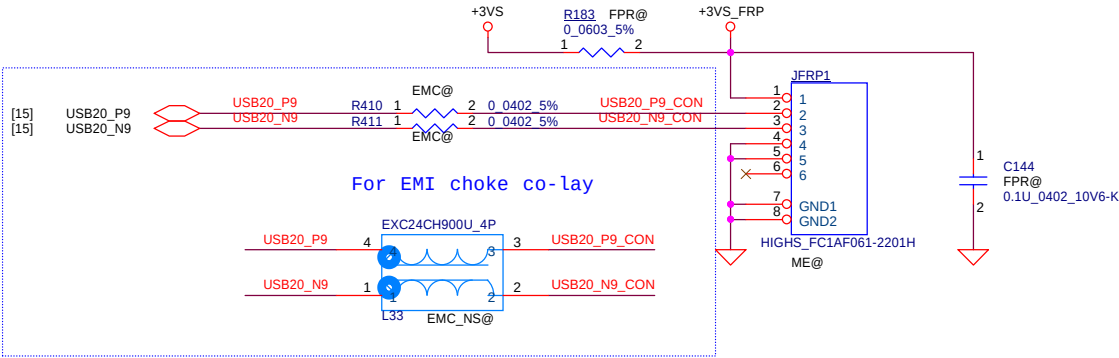
20160424
1. Change R430/R423 from 100 to 300 ohm for LED brightness
2. Change R422 from 100 to 75 ohm for LED brightness



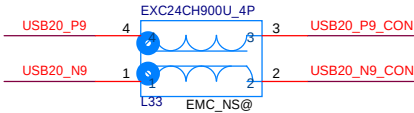
- [57] PWRBTN_LED# PWRBTN_LED#
- [57] BATT_CHG_LED# BATT_CHG_LED#
- [57] PWR_STATUS_LED# PWR_STATUS_LED#



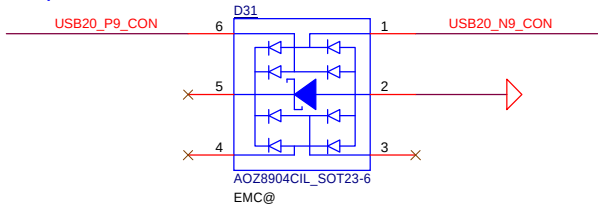
FingerPrint CONN.



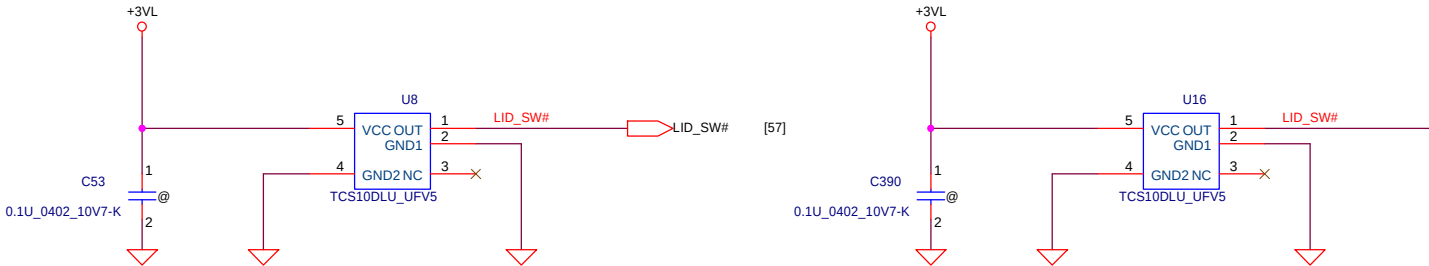
For EMI choke co-lay



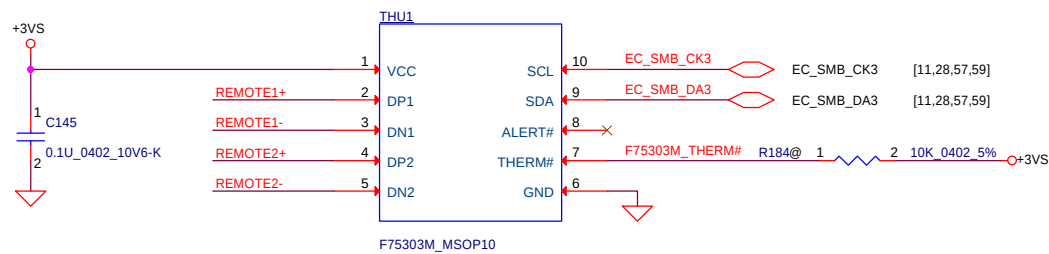
ESD request



Lid Switch

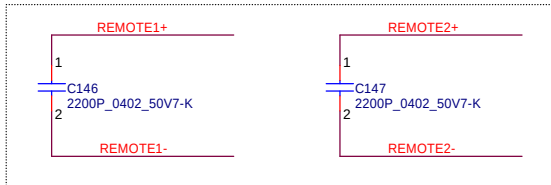


Thermal Sensor
placed near by VRAM

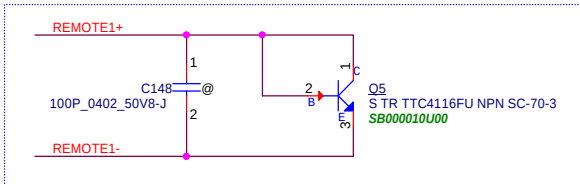


Address 1001_101xb
Internal pull up 1.2K to 1.5V
R for init i d t her m sh ut do wnt e mp

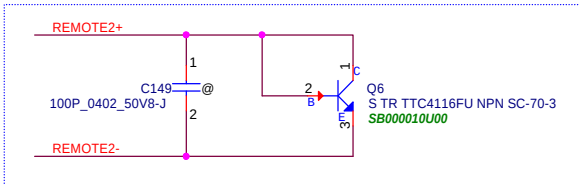
Close to U1



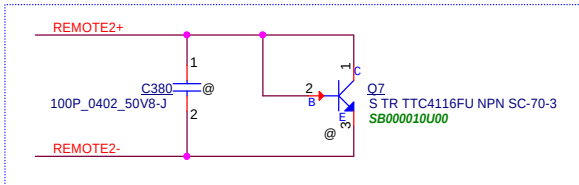
Close to +VCC_CORE

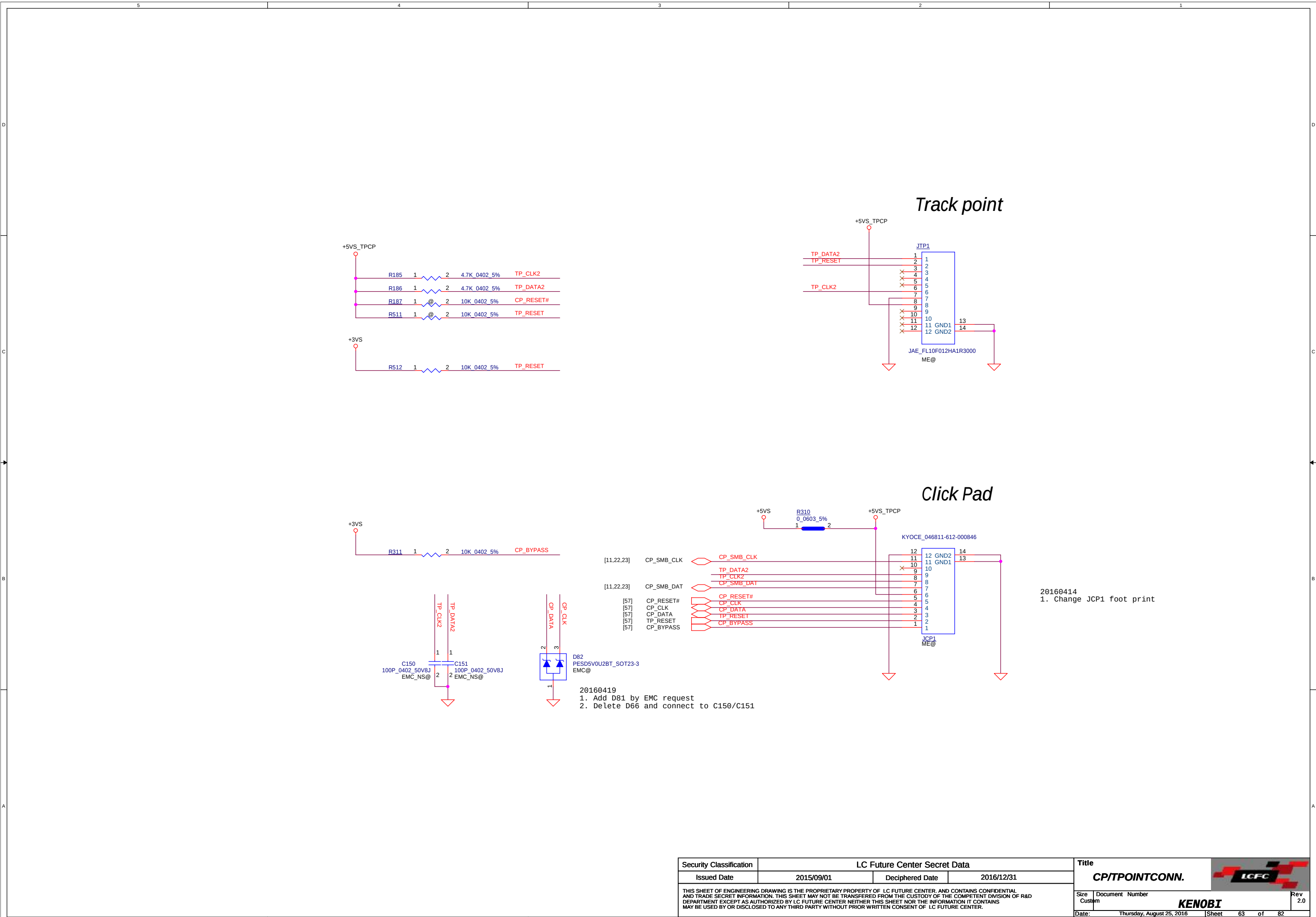


Close JDIMM1&JDIMM2

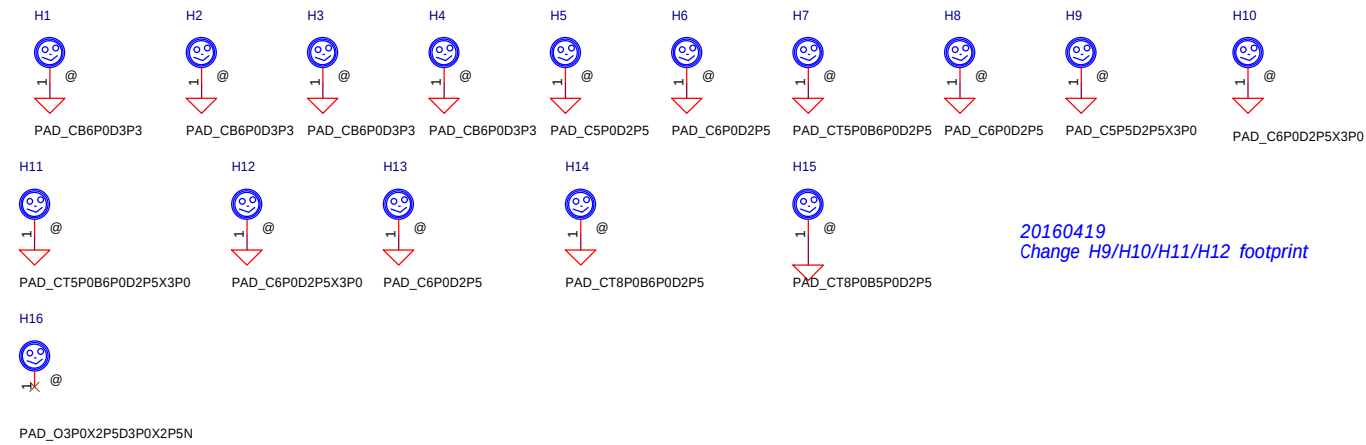


REMOTE2+/-:
Trace width/space:10/10 mil
Trace length:<8"

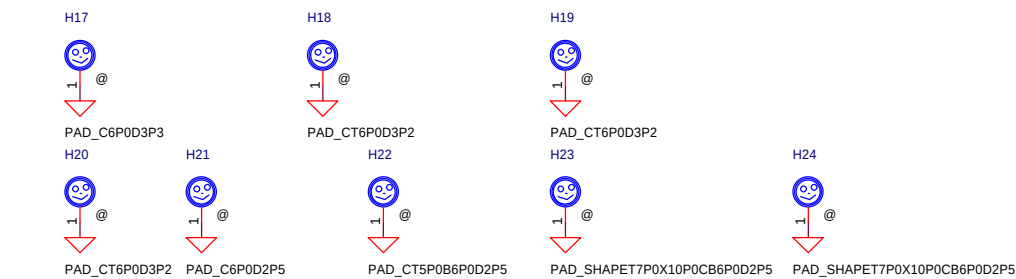




Screw Hole



20160419
Change H9/H10/H11/H12 footprint



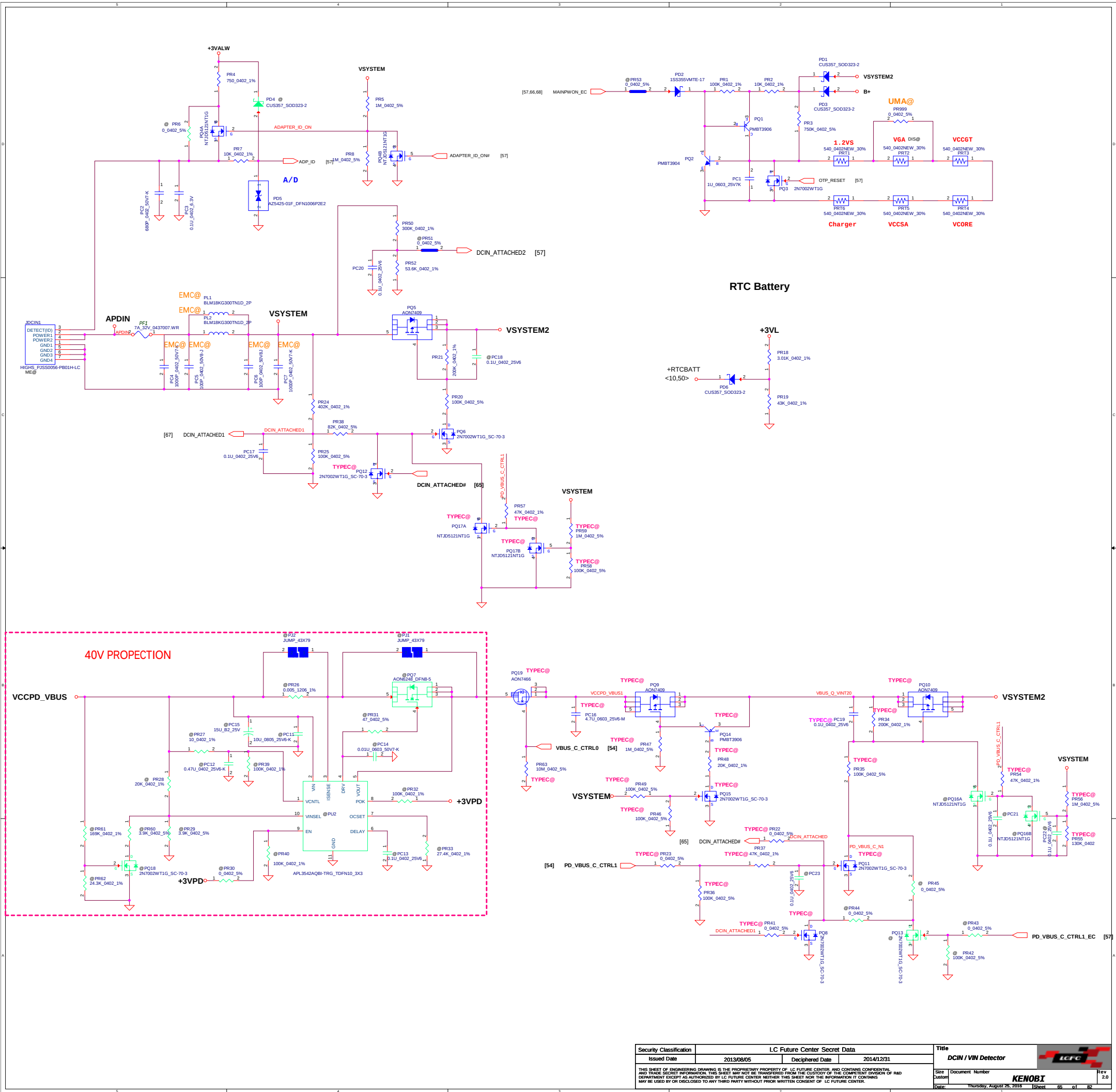
Center Zero

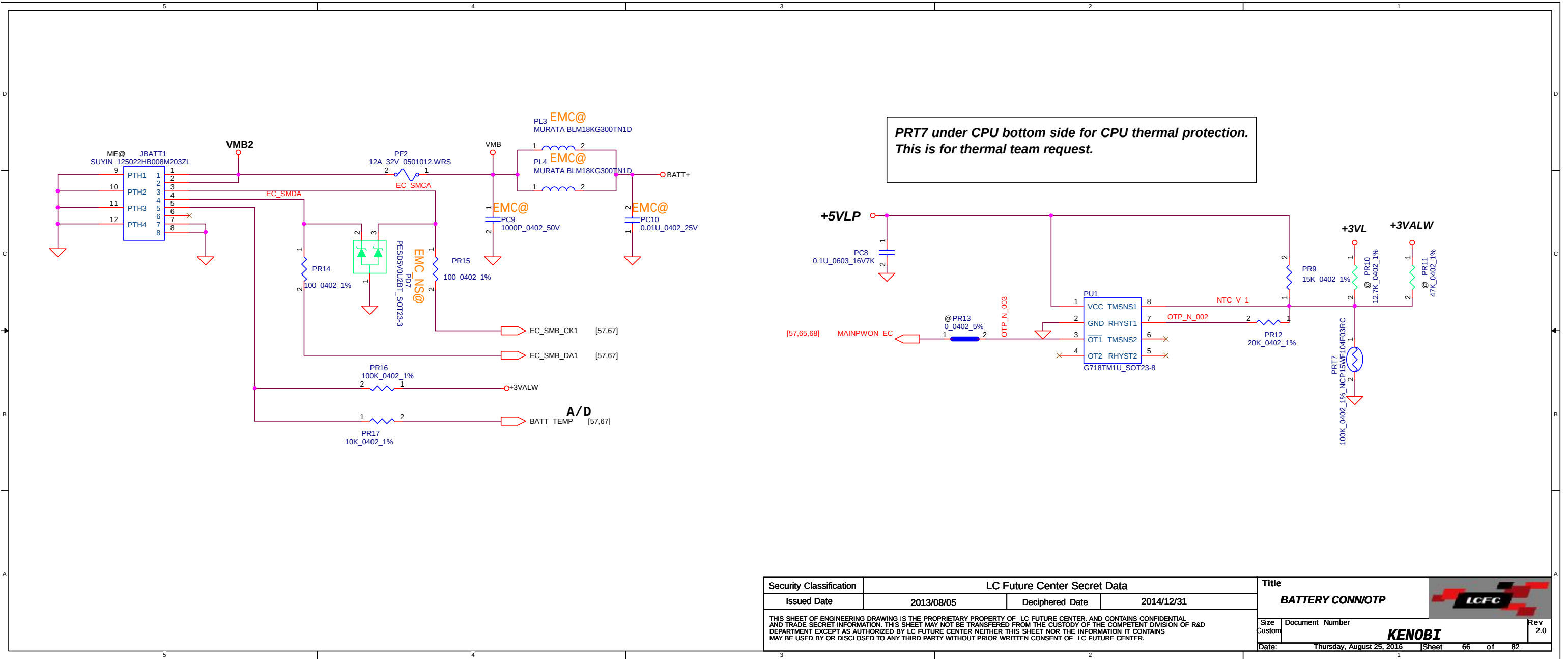


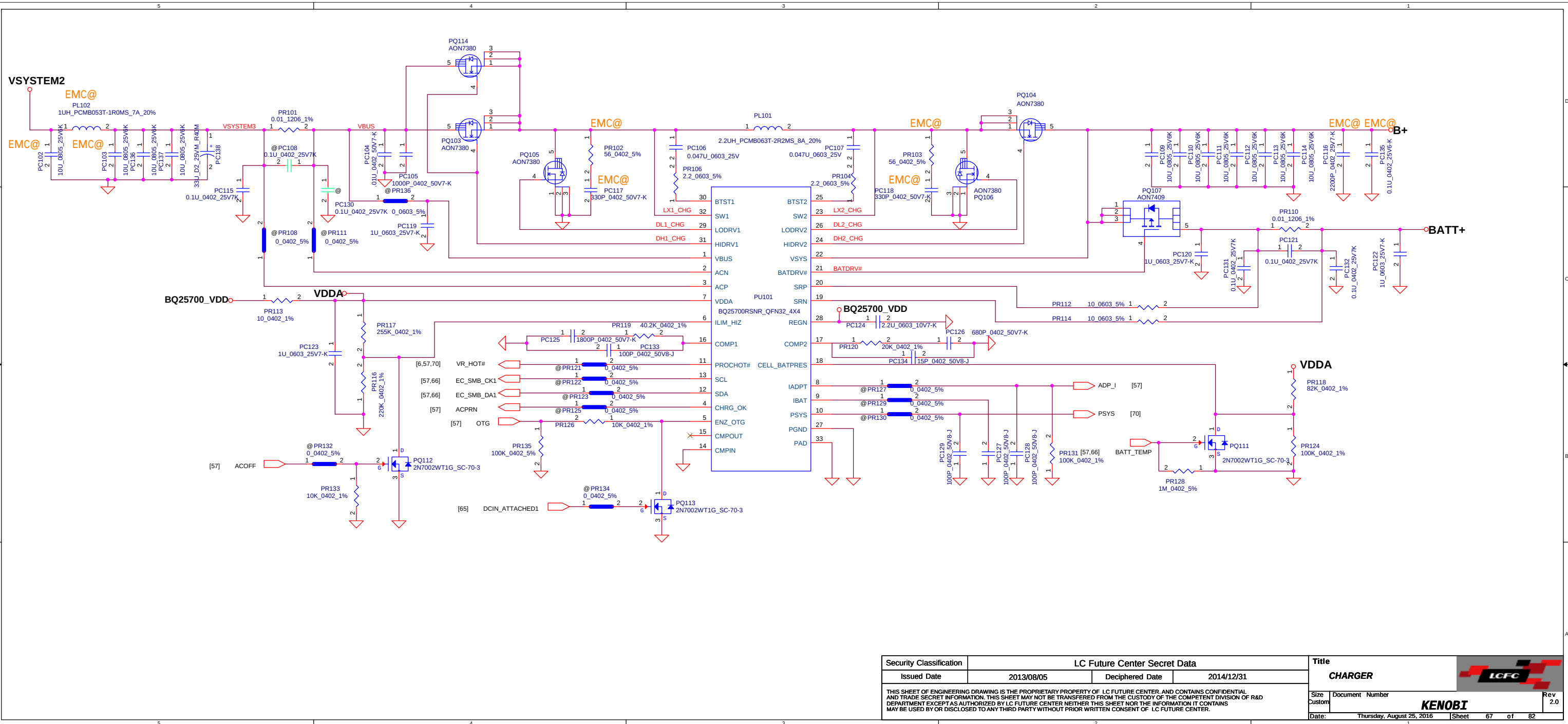
PCB Federal Mark PAD

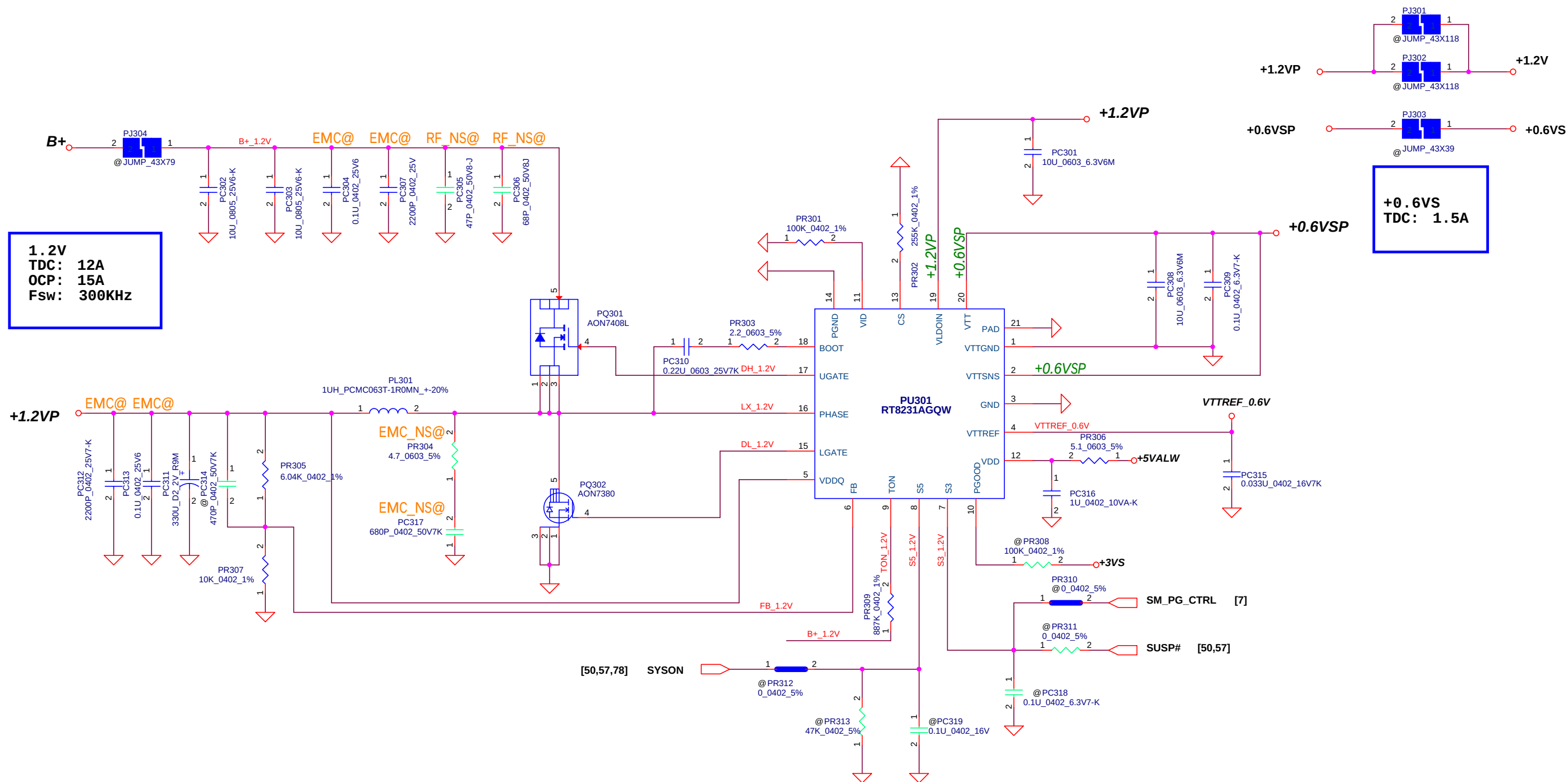


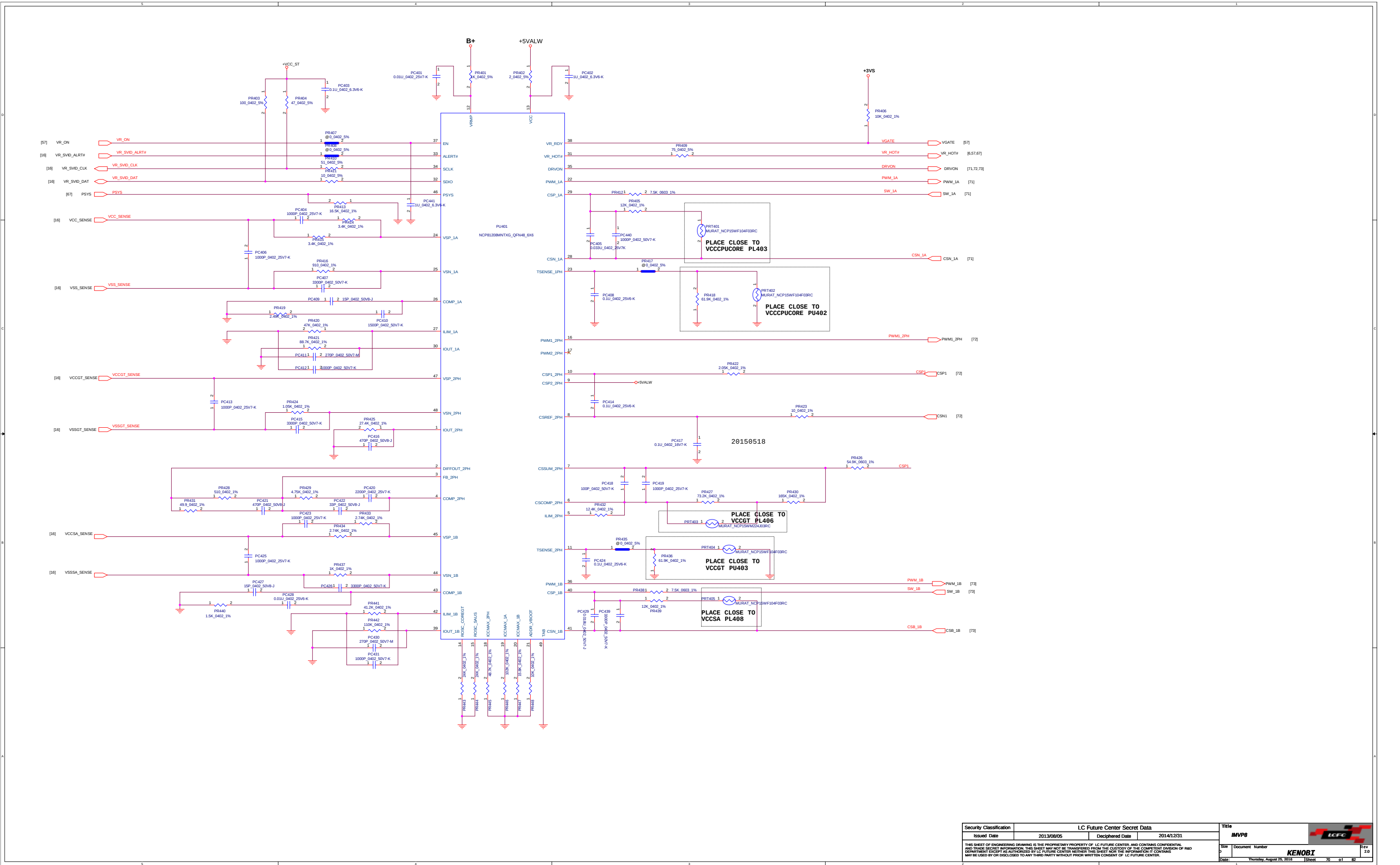
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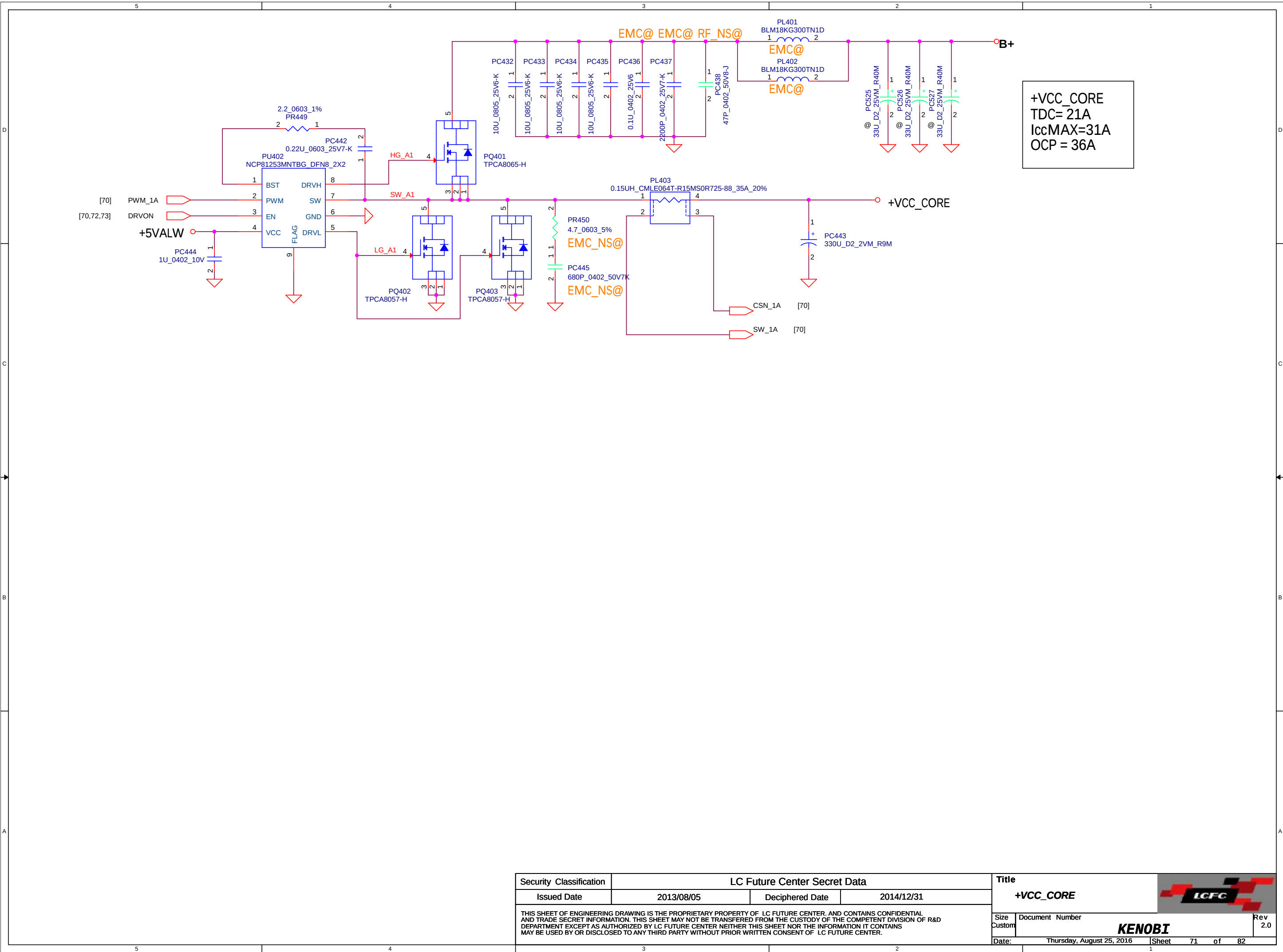




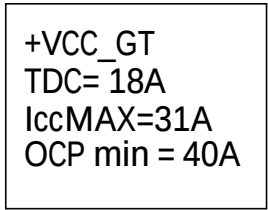




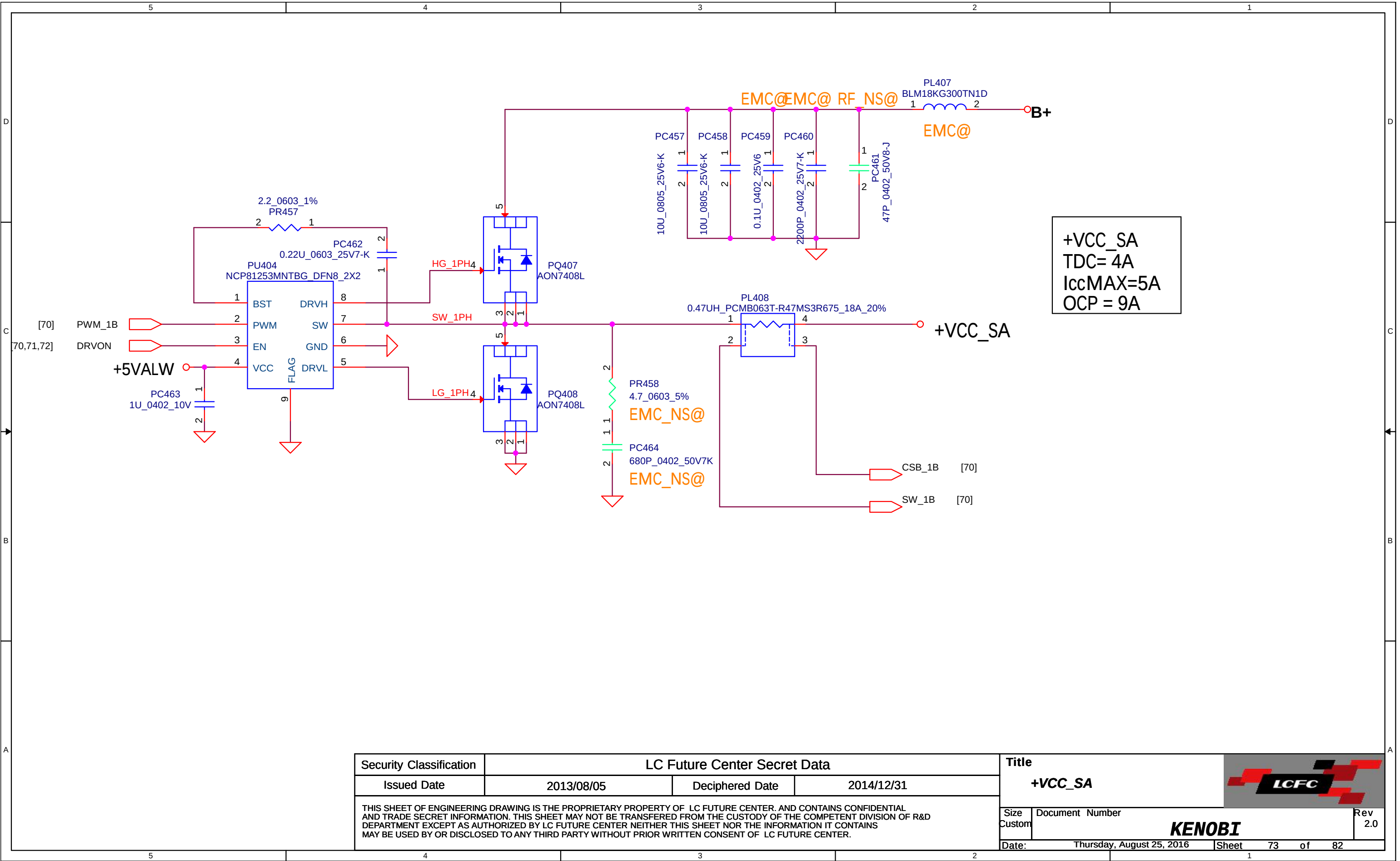




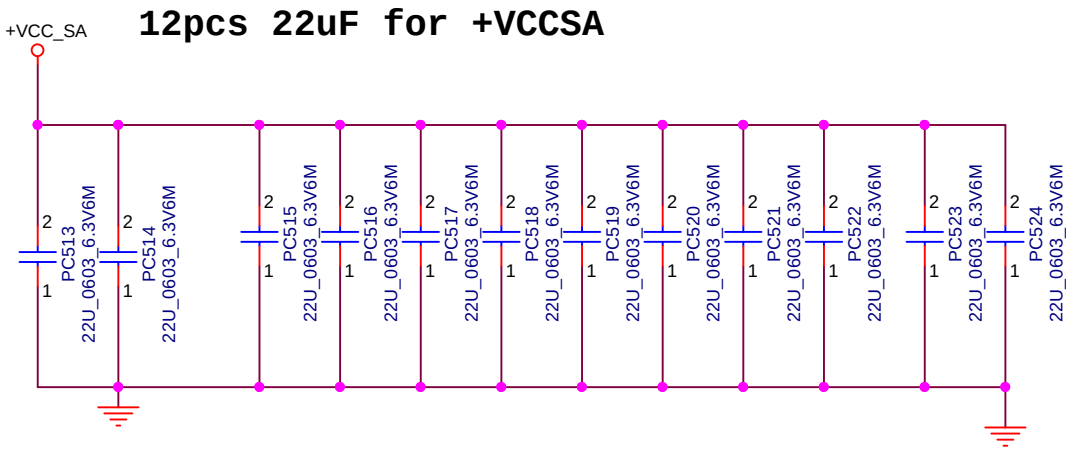
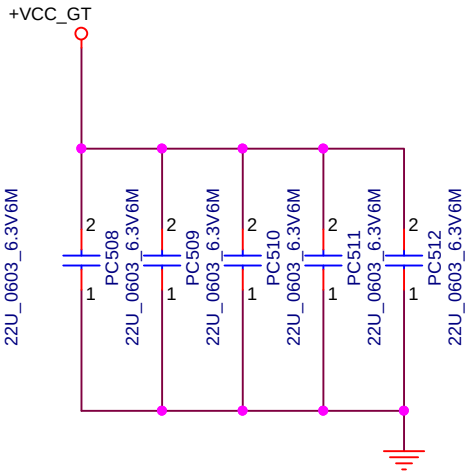
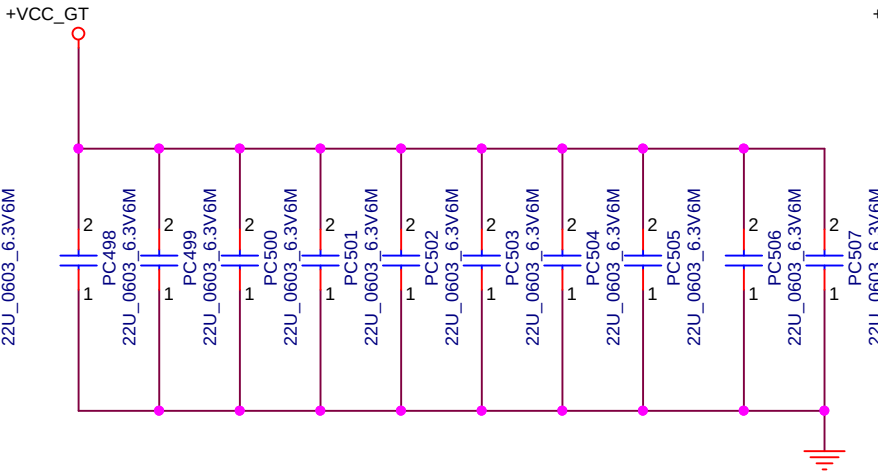
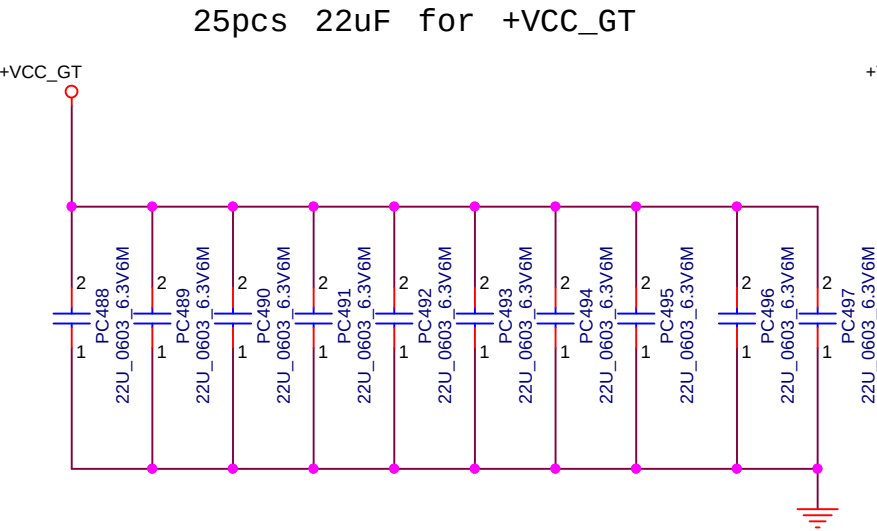
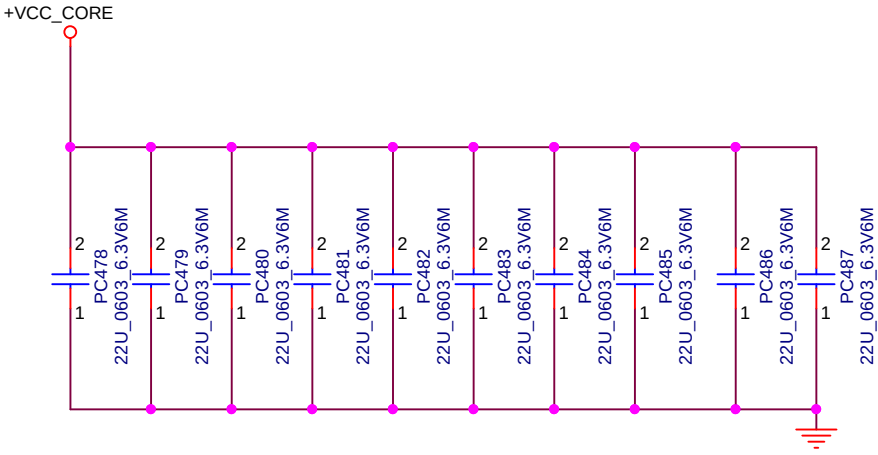
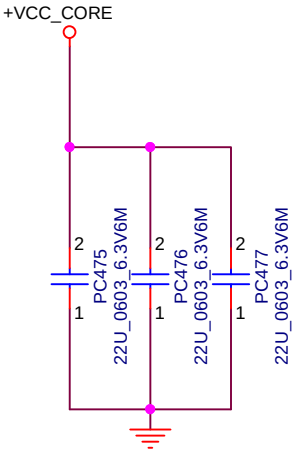
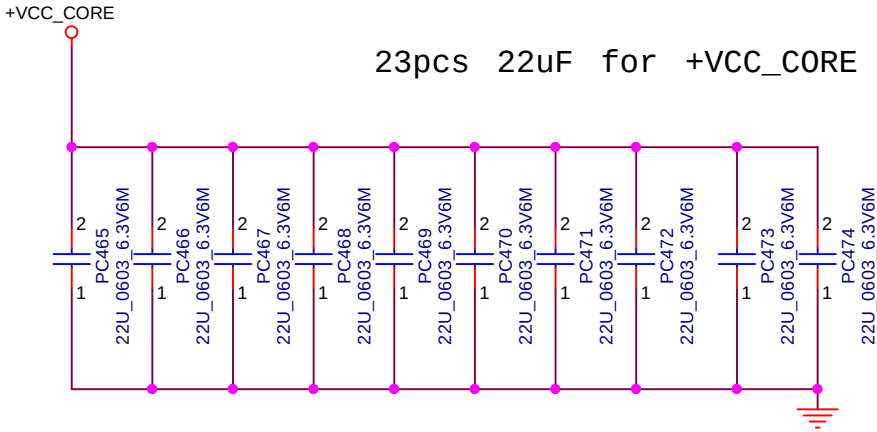
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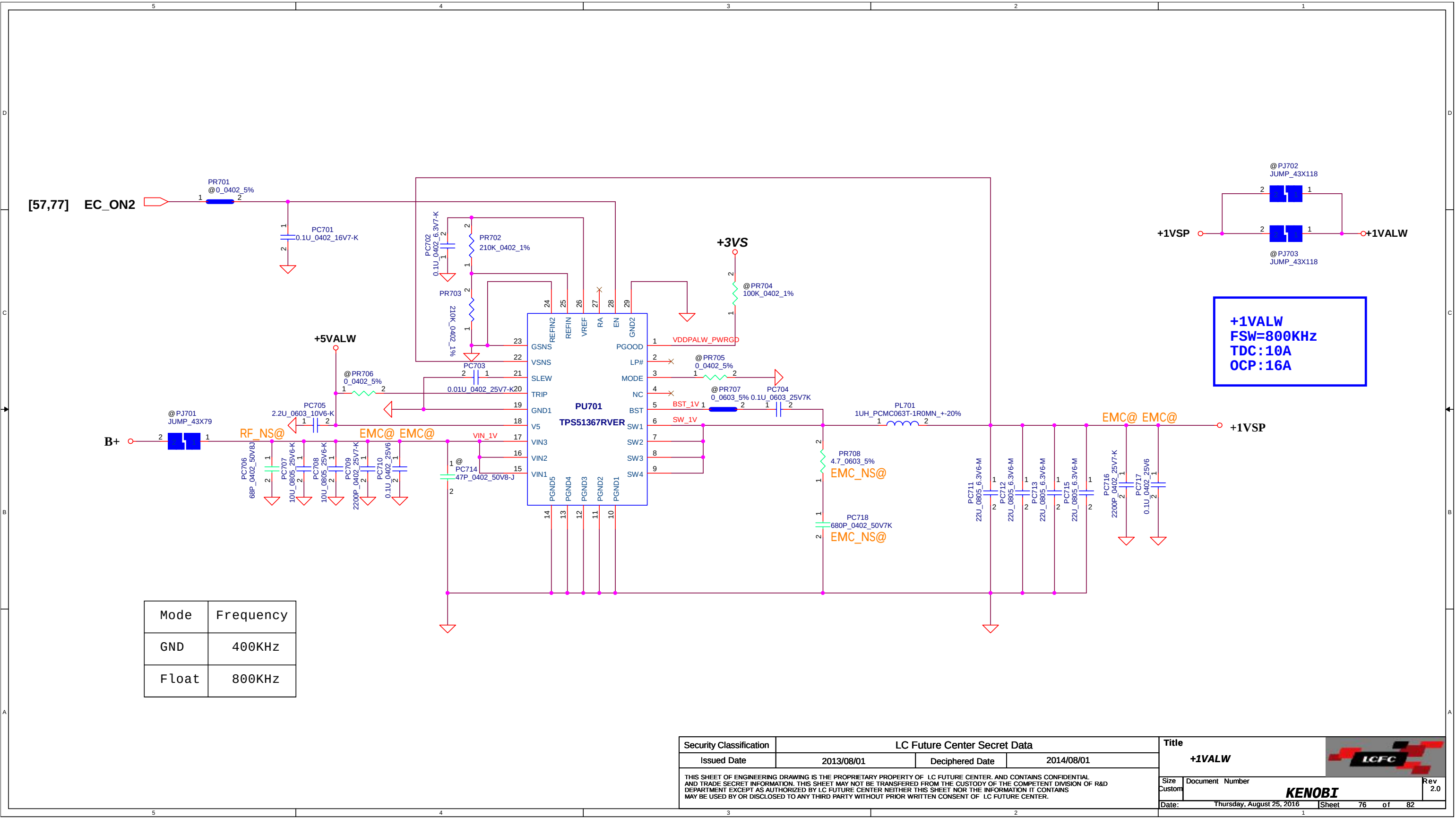
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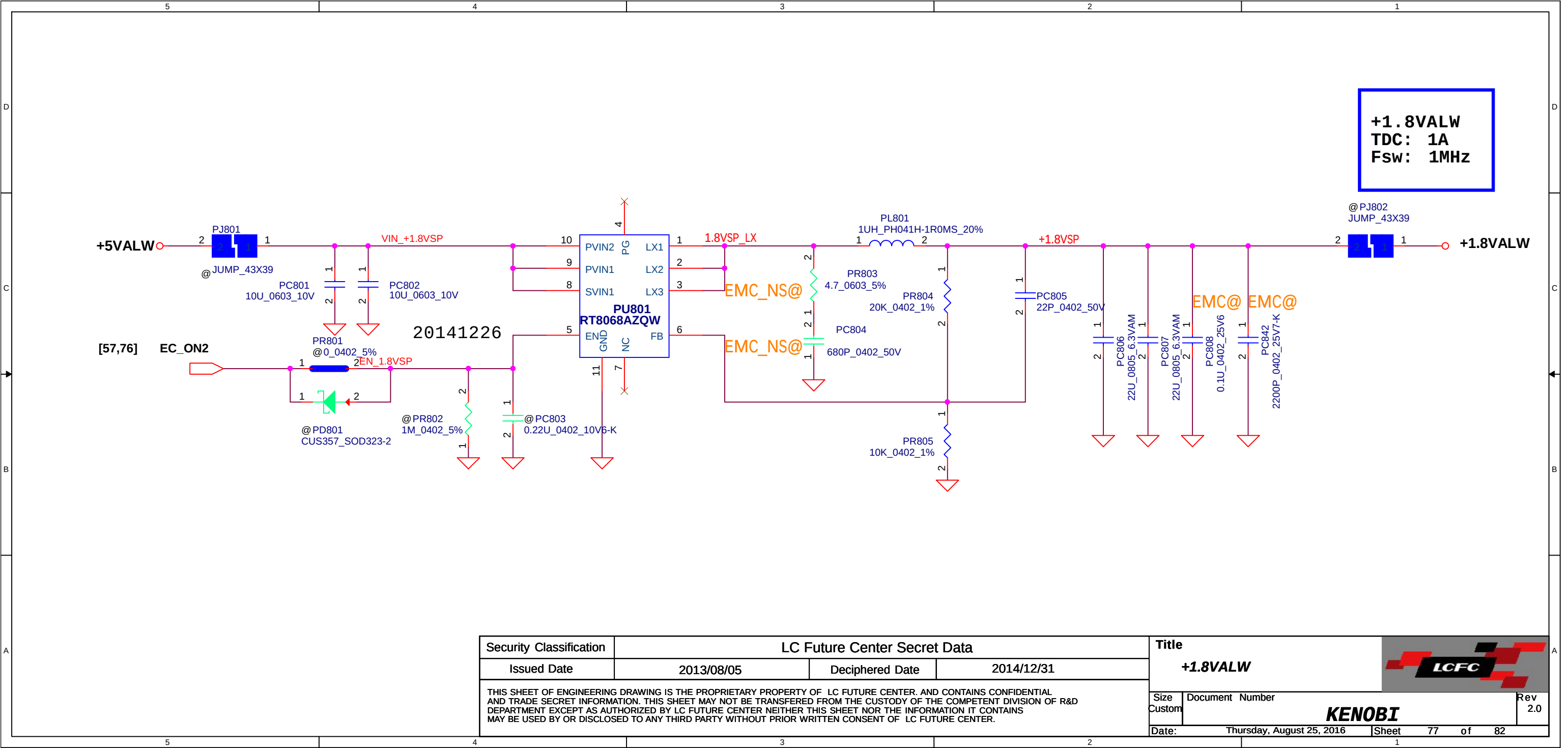


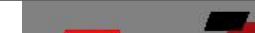
Based on PDDG rev 0.7 Table 5-1.

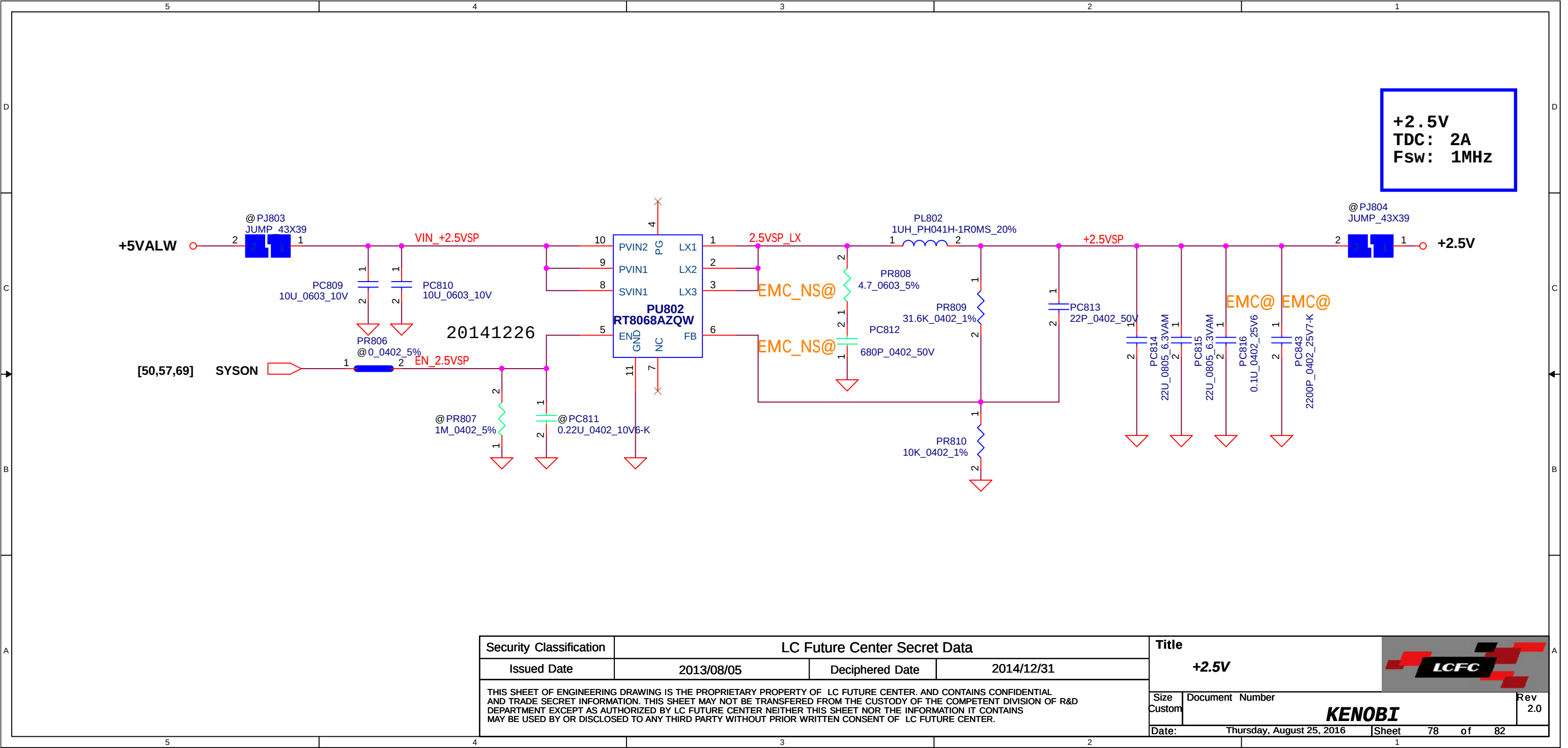


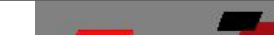
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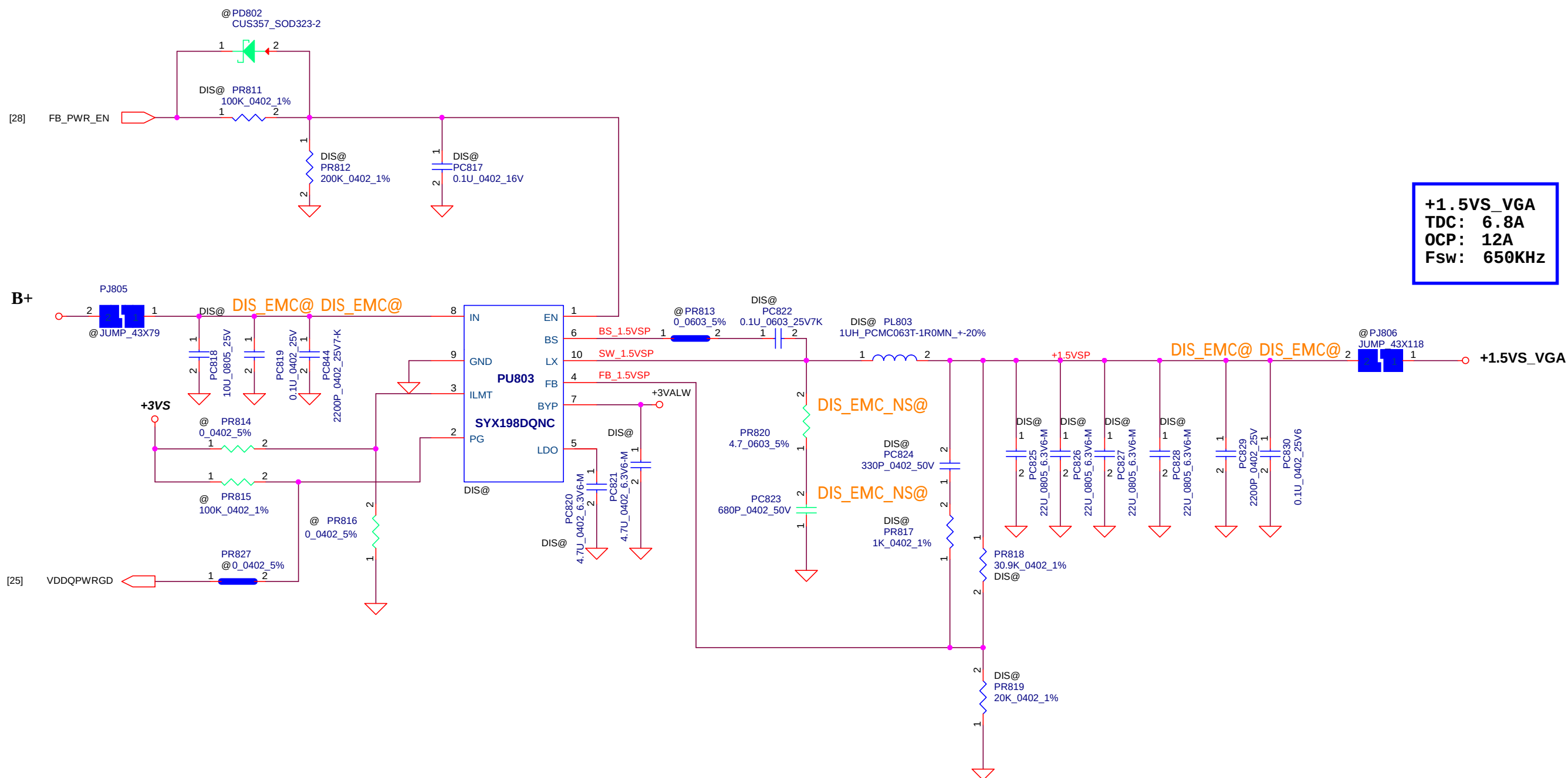




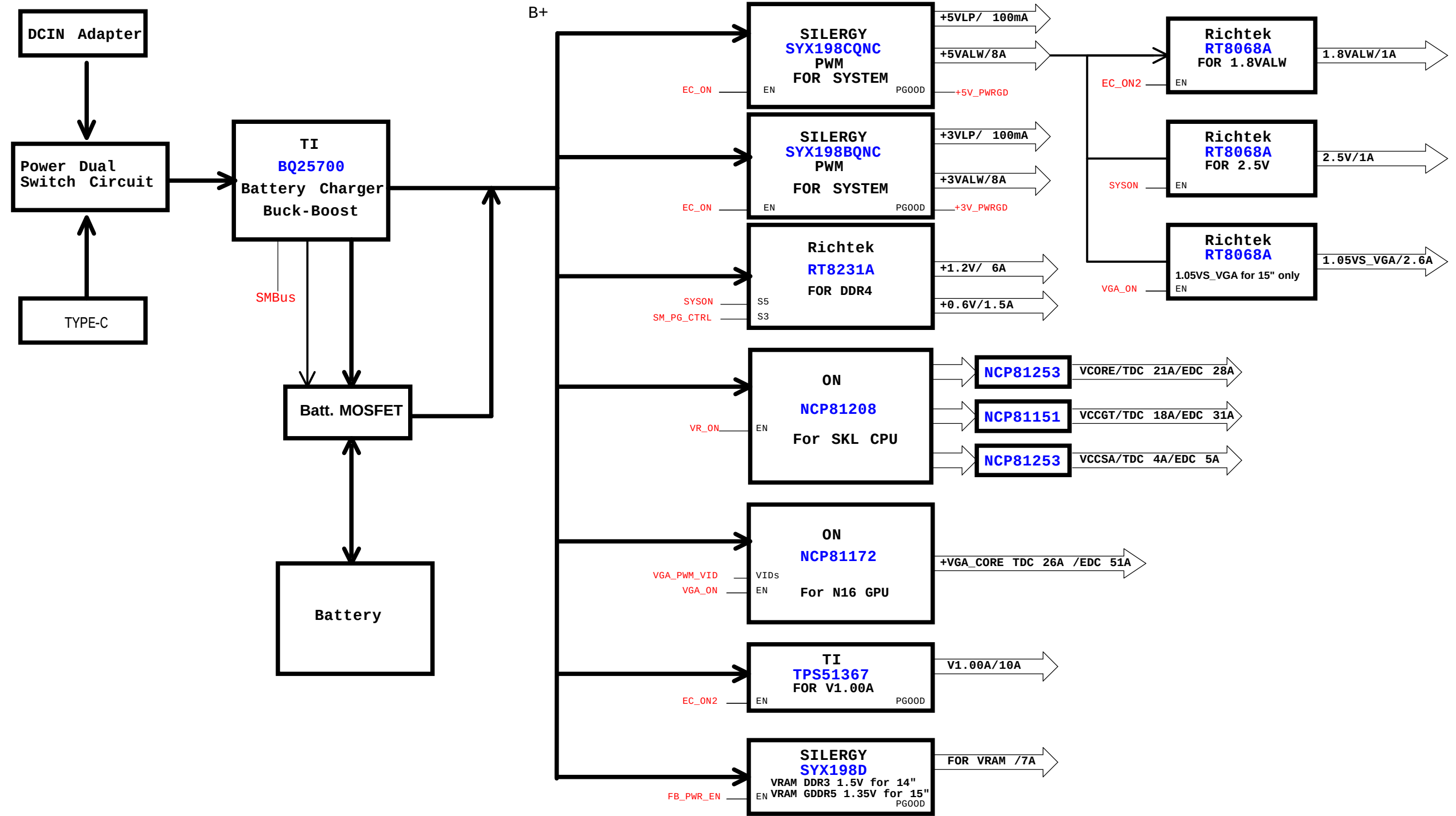
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